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(54) **LITHOGRAPHIC APPARATUS, FLUID HANDLING STRUCTURE FOR USE IN A LITHOGRAPHIC APPARATUS AND DEVICE MANUFACTURING METHOD**

(58) **Field of Classification Search**
CPC G03F 7/2041; G03F 7/70341; G03F 7/70716; G03F 7/70725
See application file for complete search history.

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(*) Notice: This patent is subject to a terminal disclaimer.

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Reissue of:

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(64) Patent No.: **8,767,169**
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(57) **ABSTRACT**

U.S. Applications:

A lithographic apparatus including a fluid handling structure configured to contain immersion fluid in a space adjacent to an upper surface of the substrate table and/or a substrate located in a recess of the substrate table, a cover having a planar main body that, in use, extends around a substrate from the upper surface to a peripheral section of an upper major face of the substrate in order to cover a gap between an edge of the recess and an edge of the substrate, and an immersion fluid film disruptor, configured to disrupt the formation of a film of immersion fluid between an edge of the cover and immersion fluid contained by the fluid handling structure during movement of the substrate table relative to the fluid handling structure.

(63) Continuation of application No. 15/182,514, filed on Jun. 14, 2016, now Pat. No. Re. 47,237, which is an application for the reissue of Pat. No. 8,767,169.

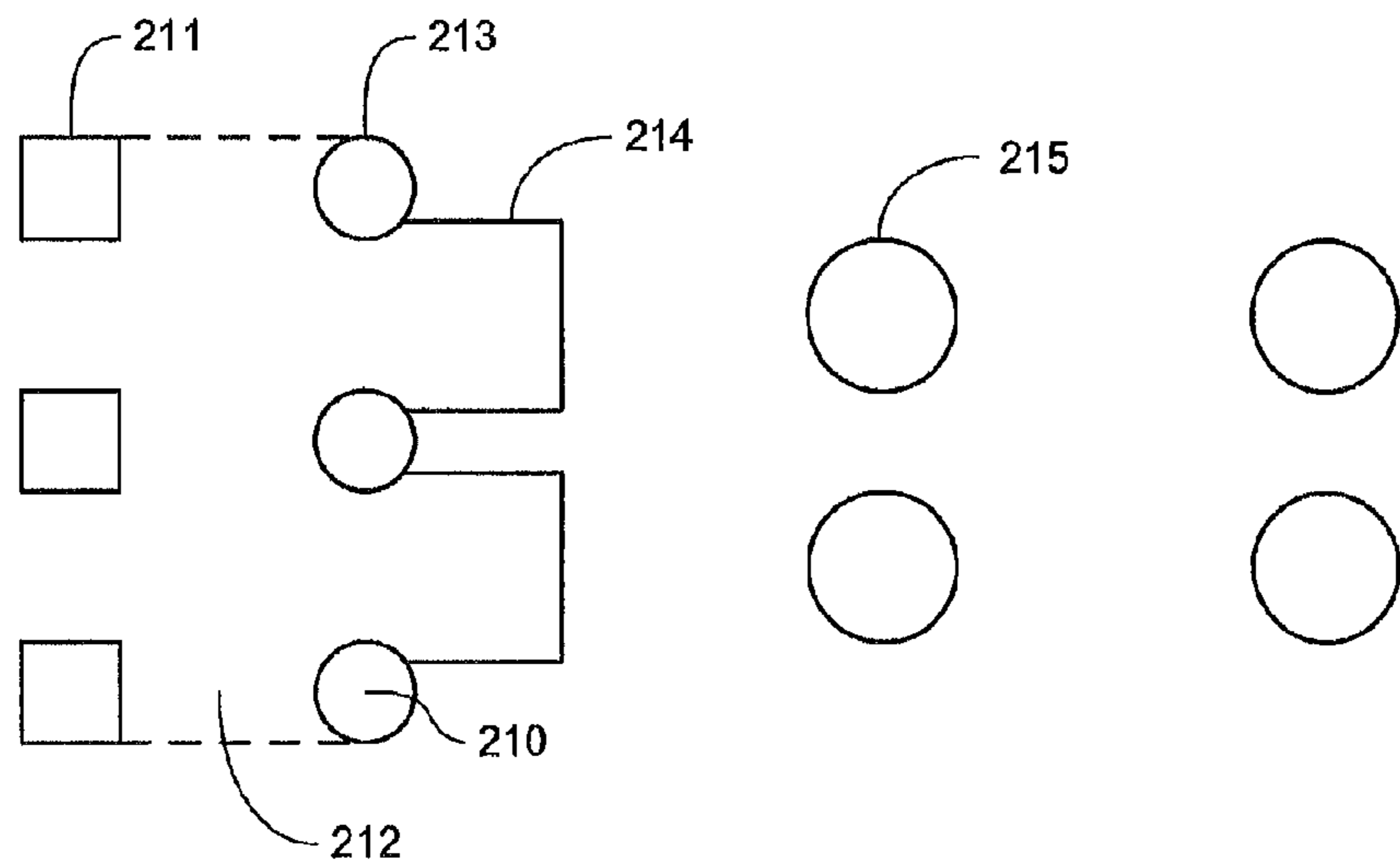
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(51) **Int. Cl.**
G03B 27/32 (2006.01)
G03F 7/20 (2006.01)

(Continued)

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CPC **G03F 7/70341** (2013.01); **G03B 27/52**
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20 Claims, 15 Drawing Sheets



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G03B 27/58 (2006.01)
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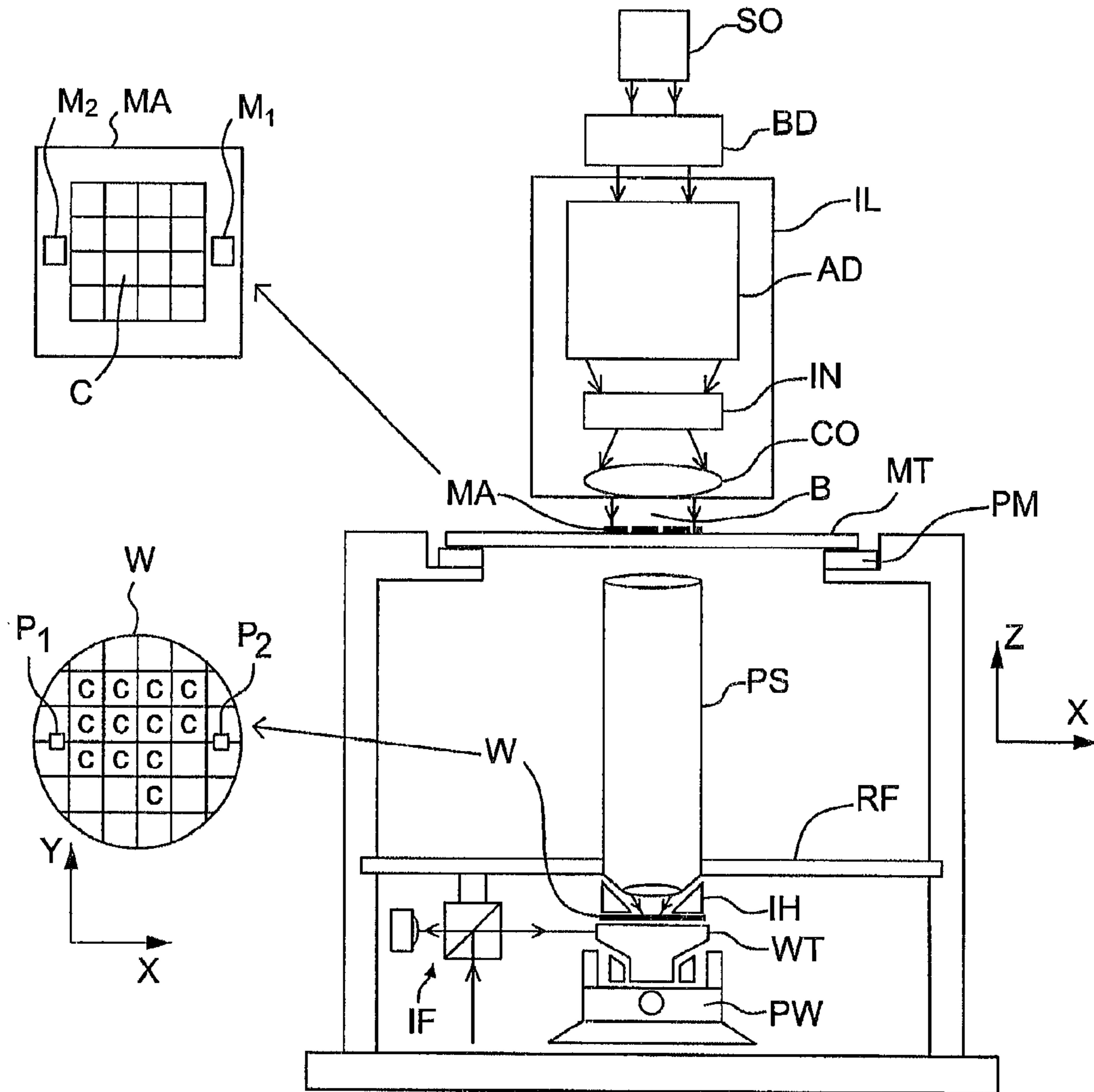


Fig. 1

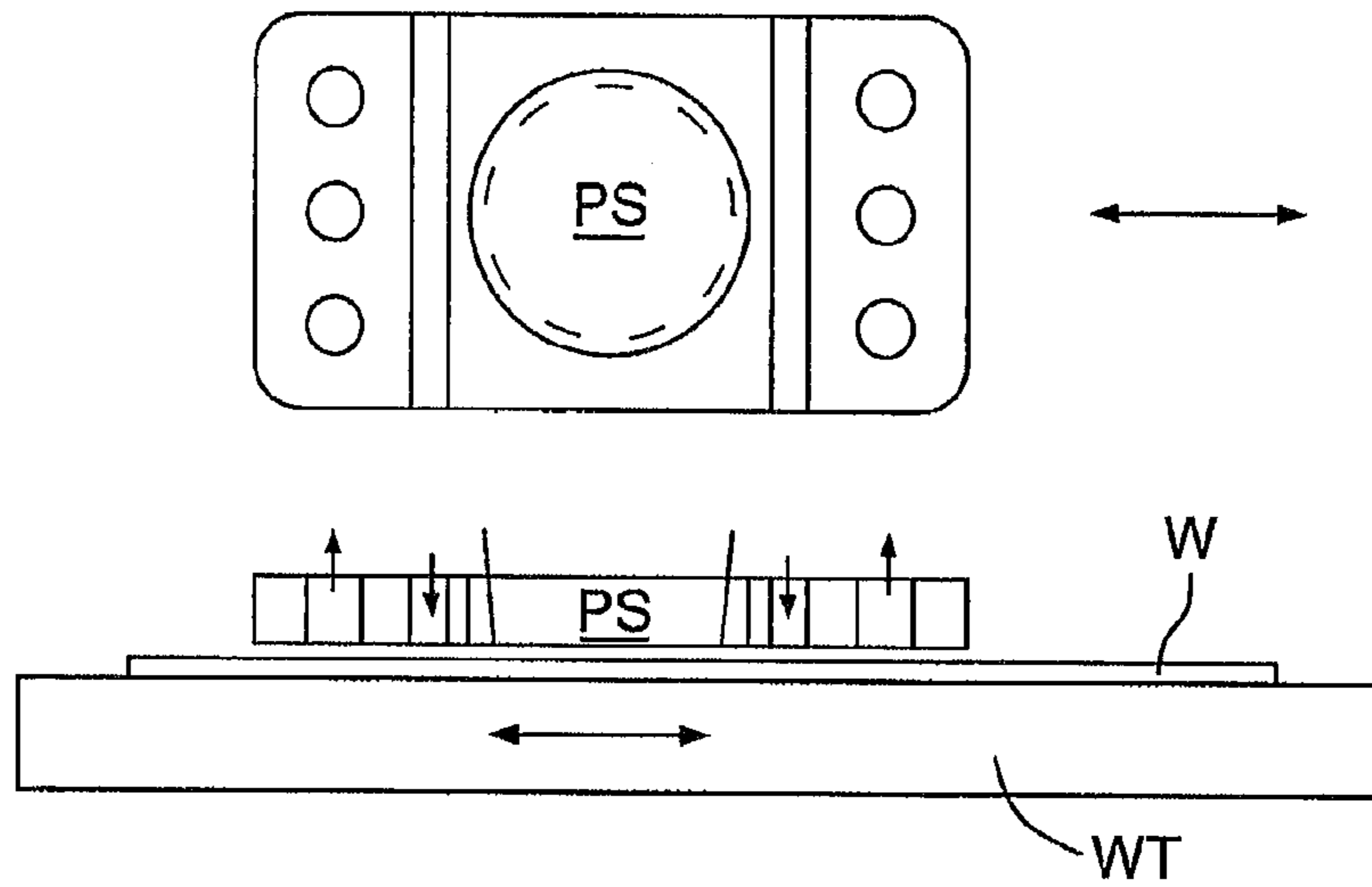
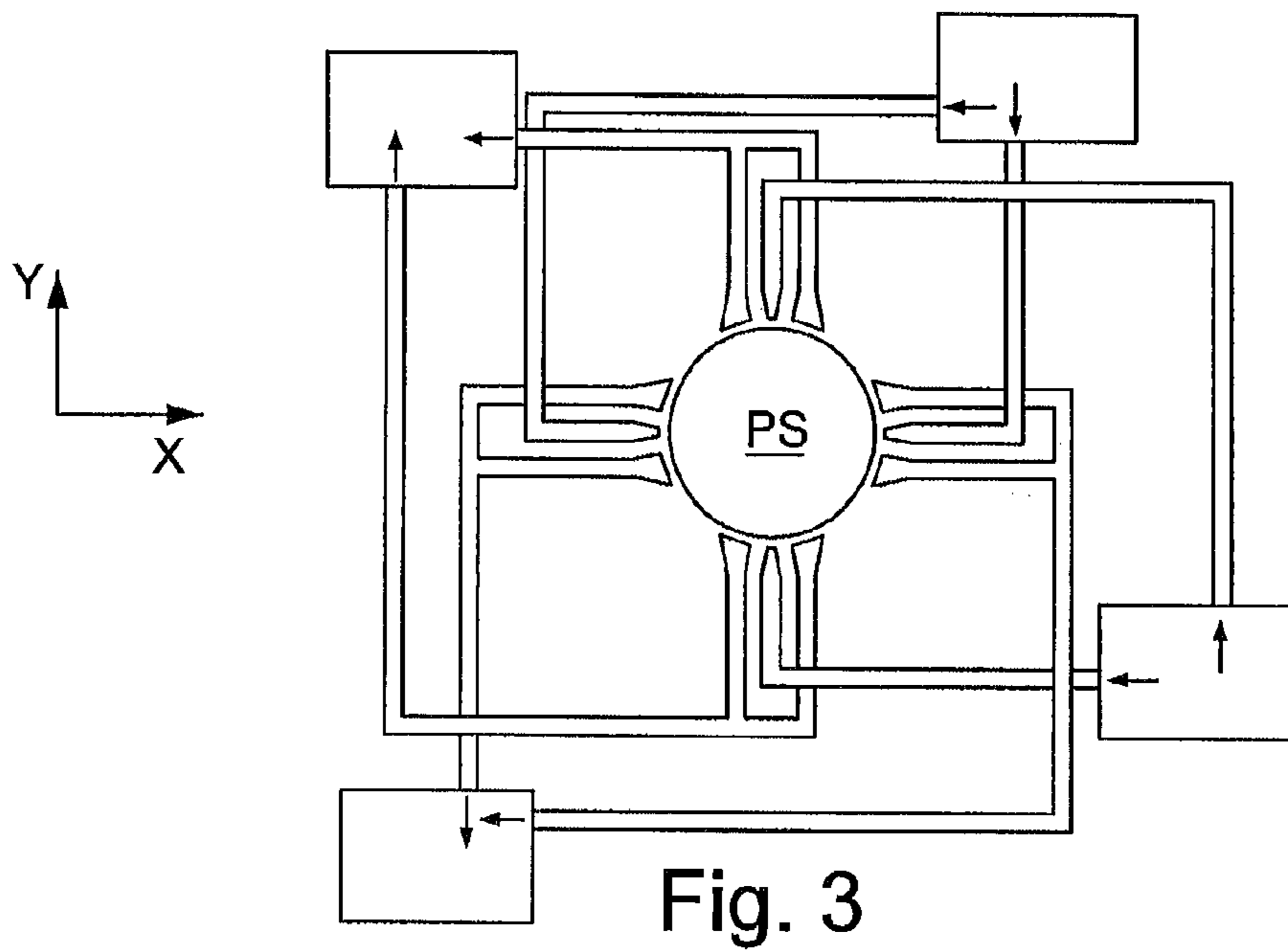
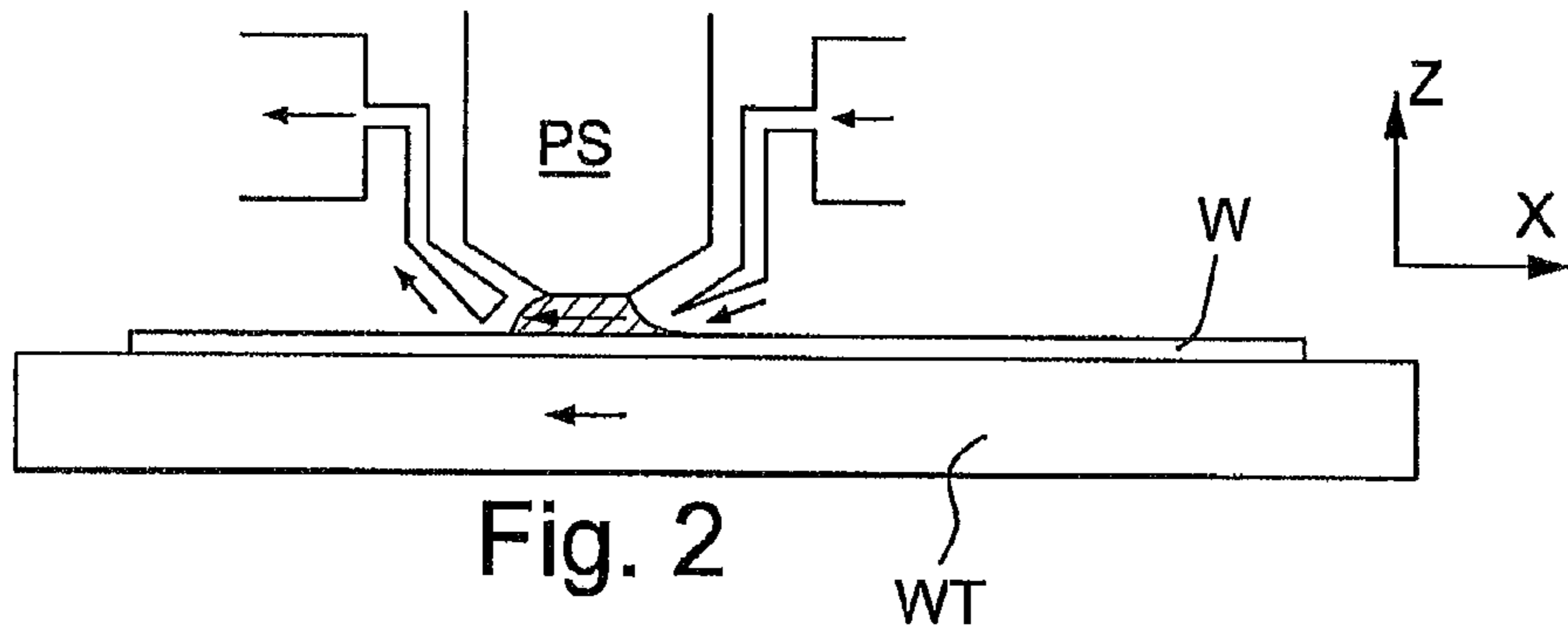


Fig. 4

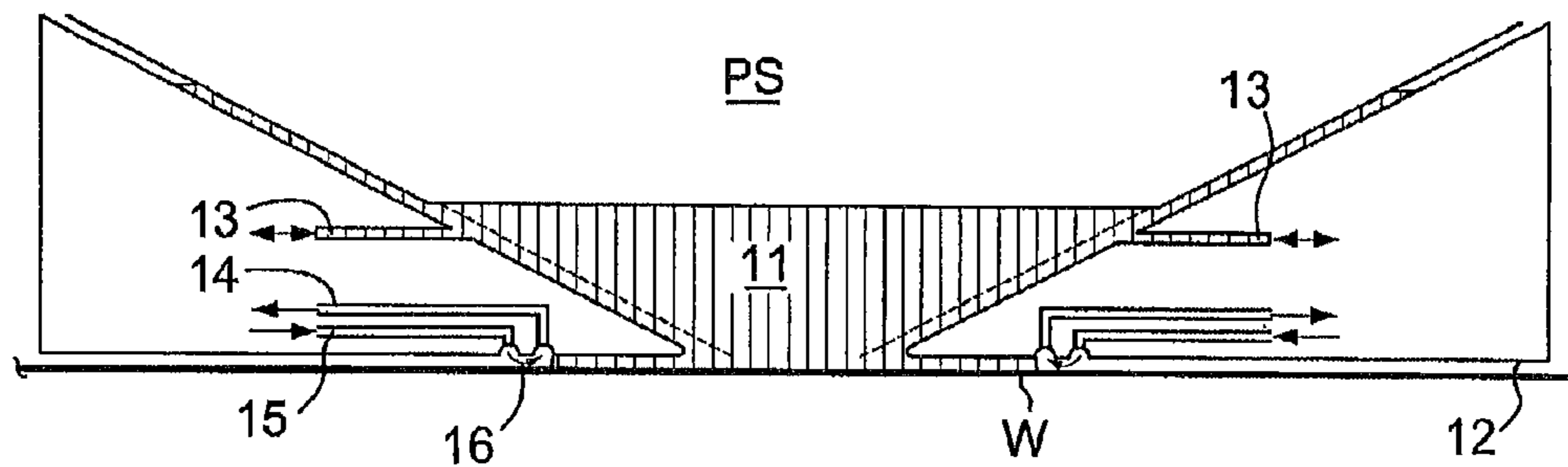


Fig. 5

Fig. 6

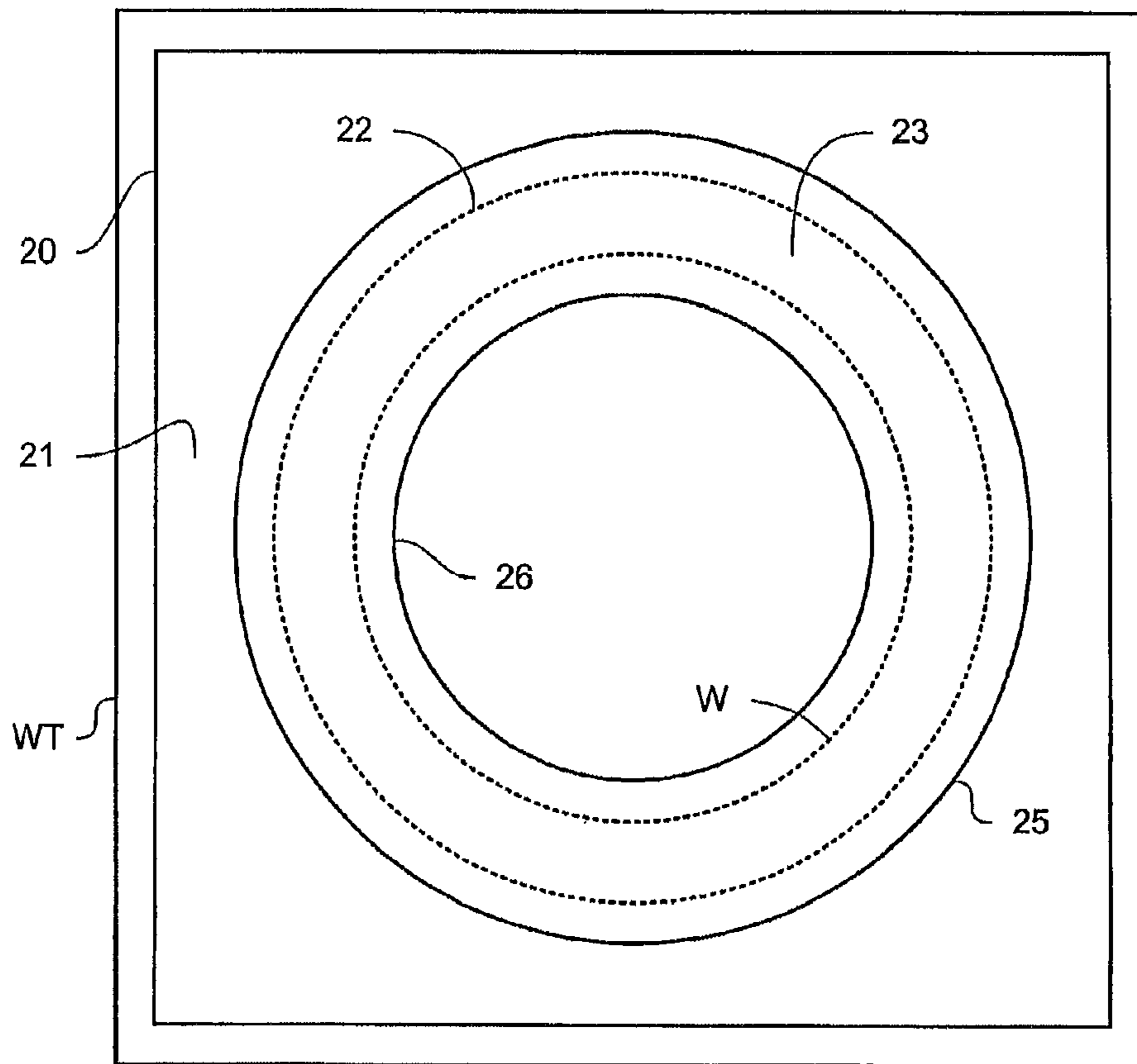


Fig. 7

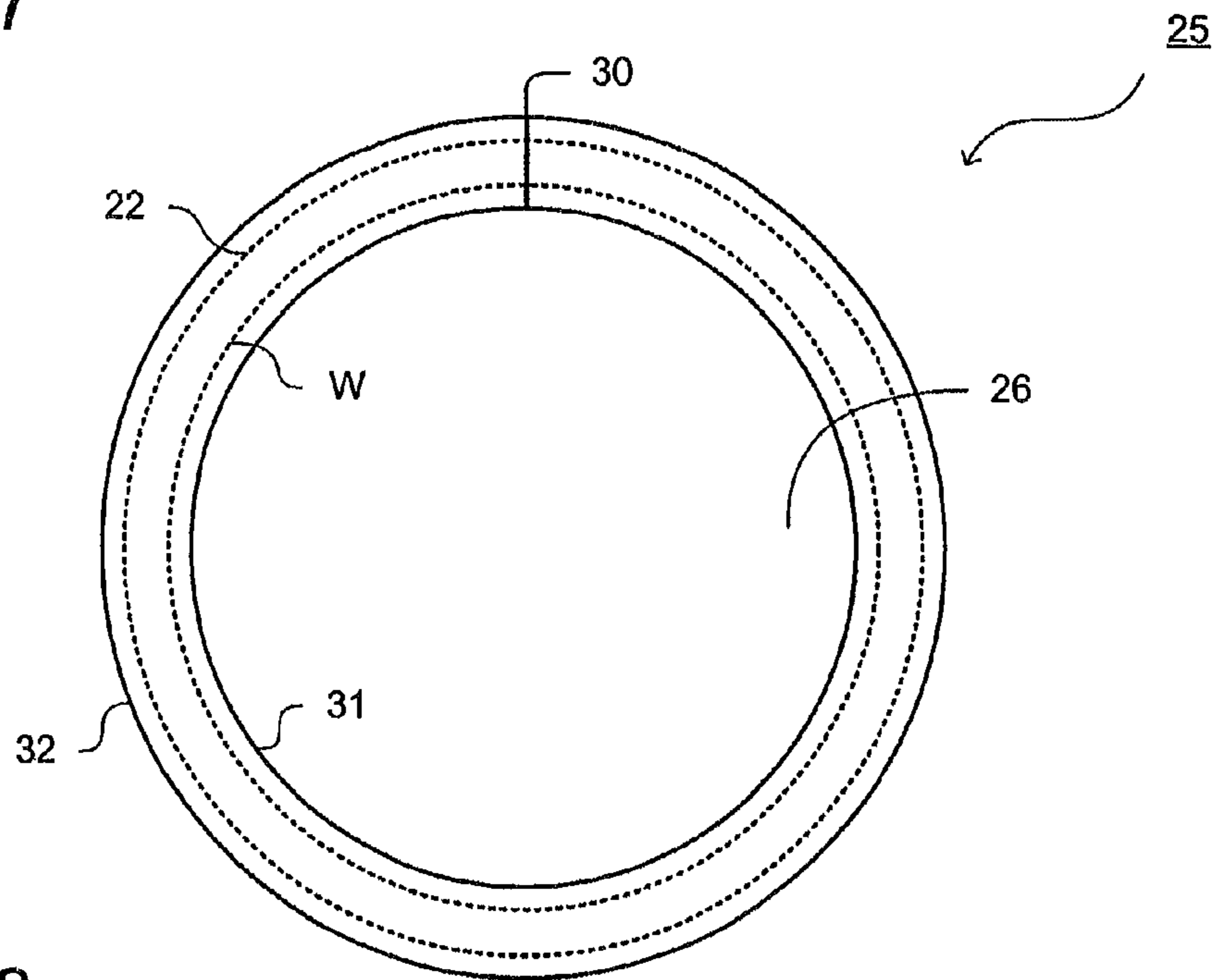


Fig. 8

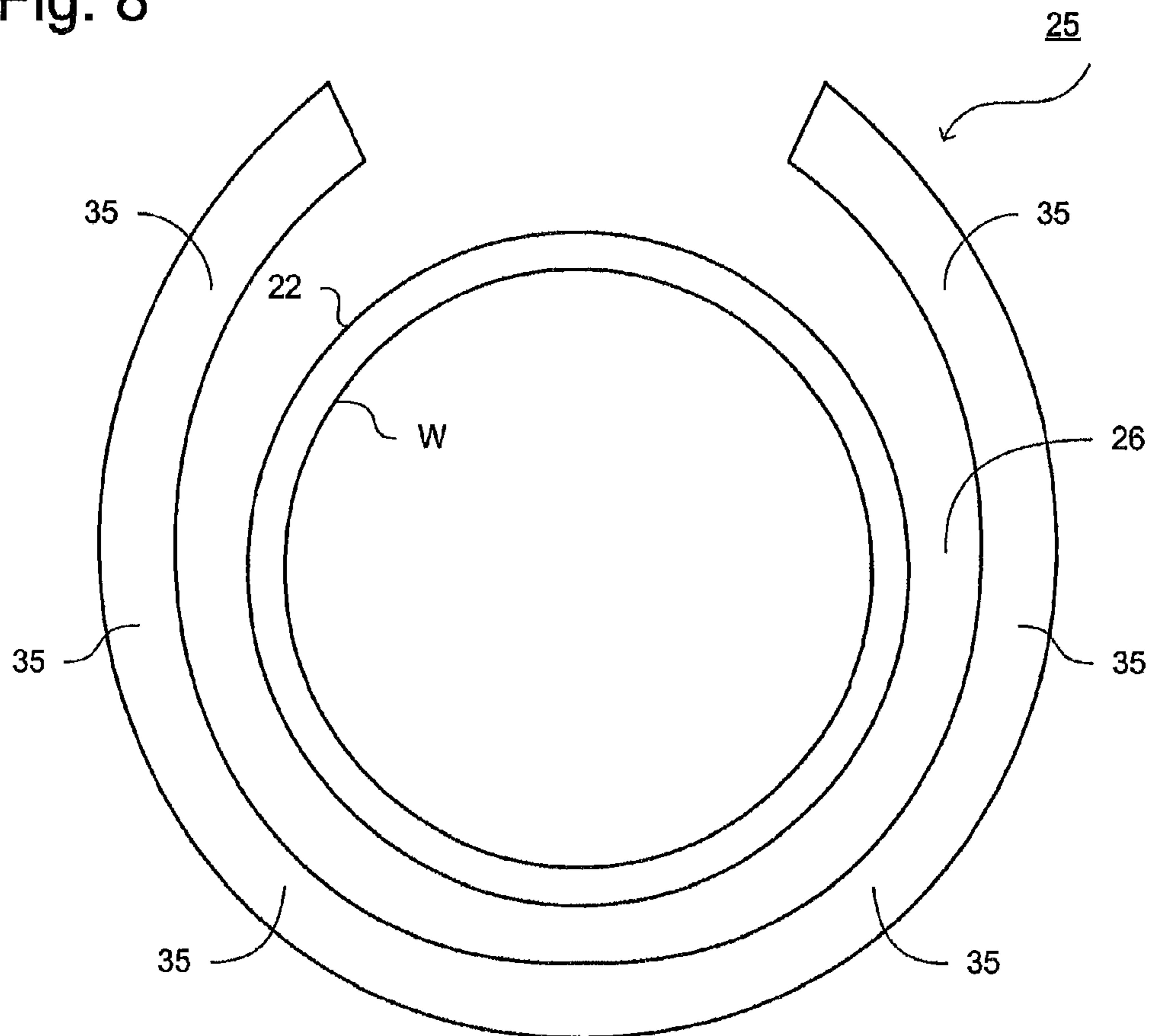


Fig. 9

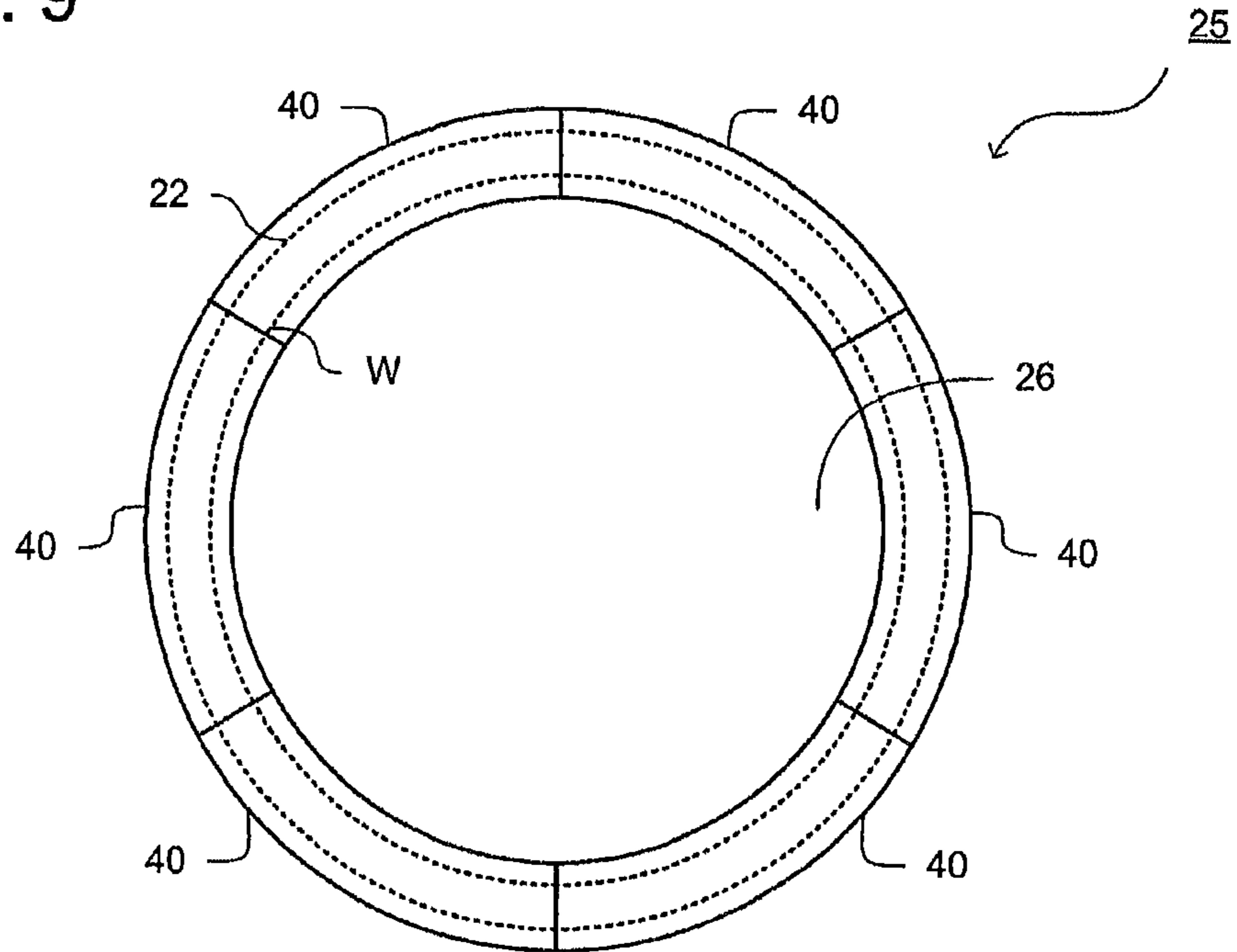


Fig. 10

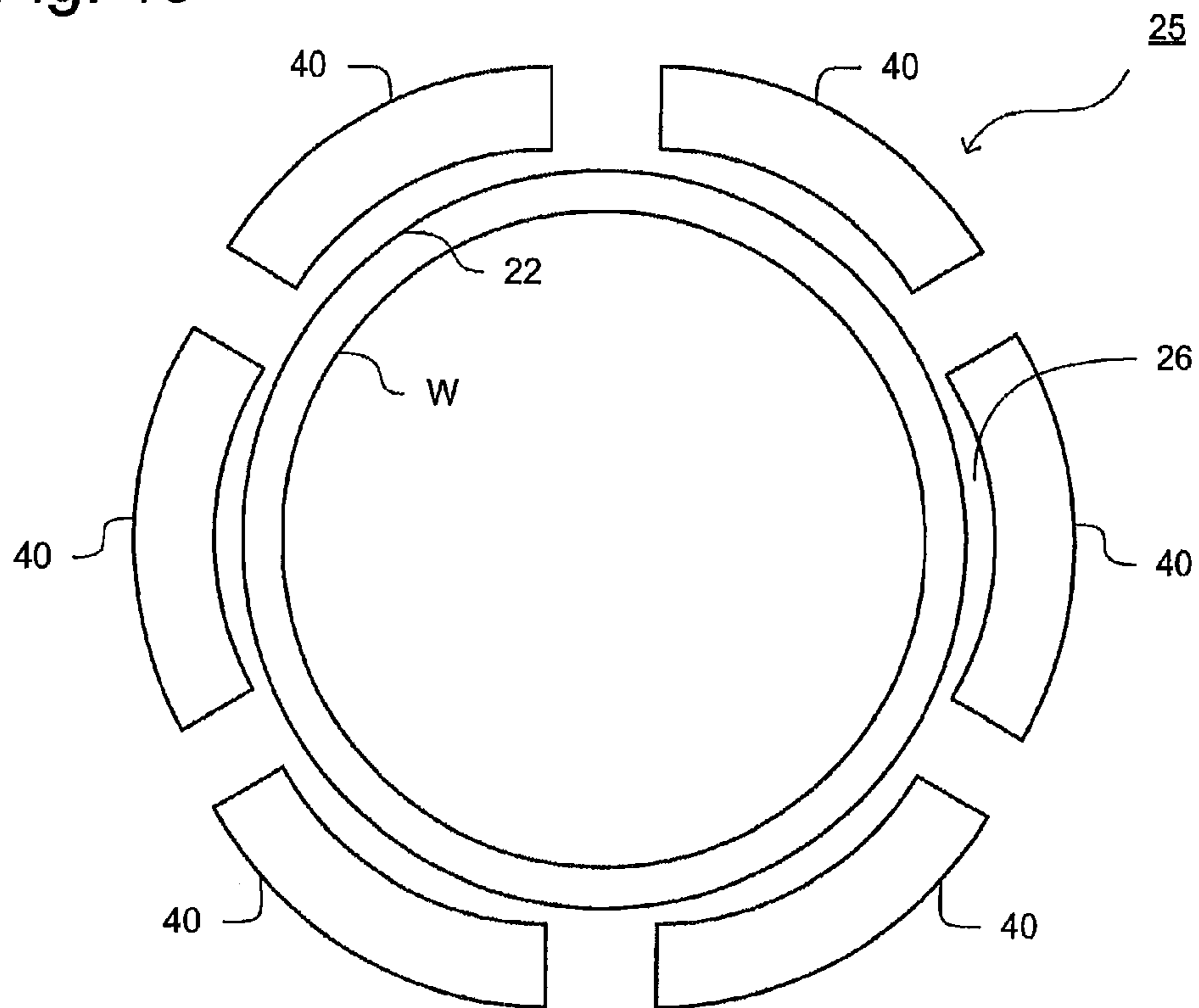


Fig. 11

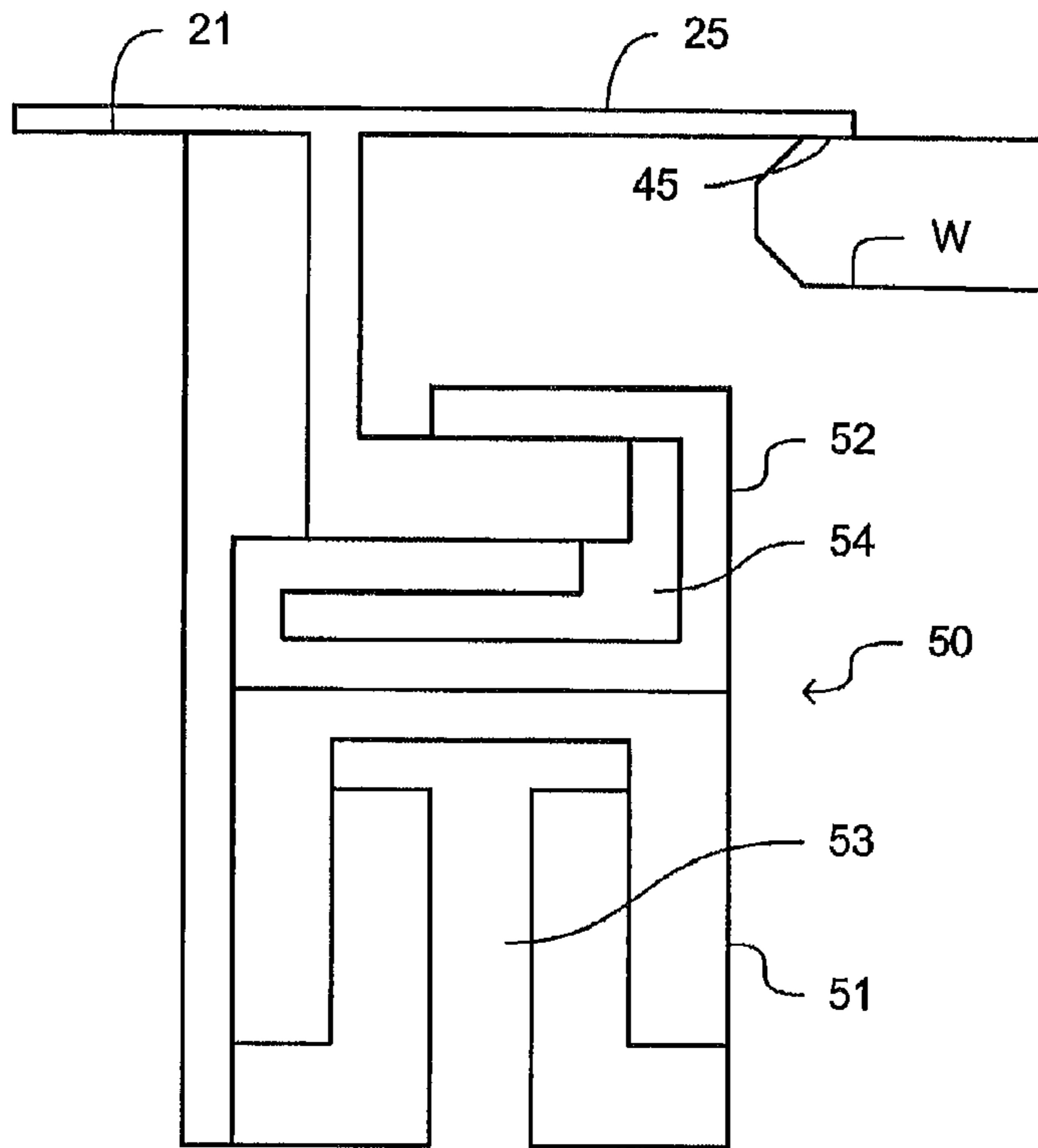


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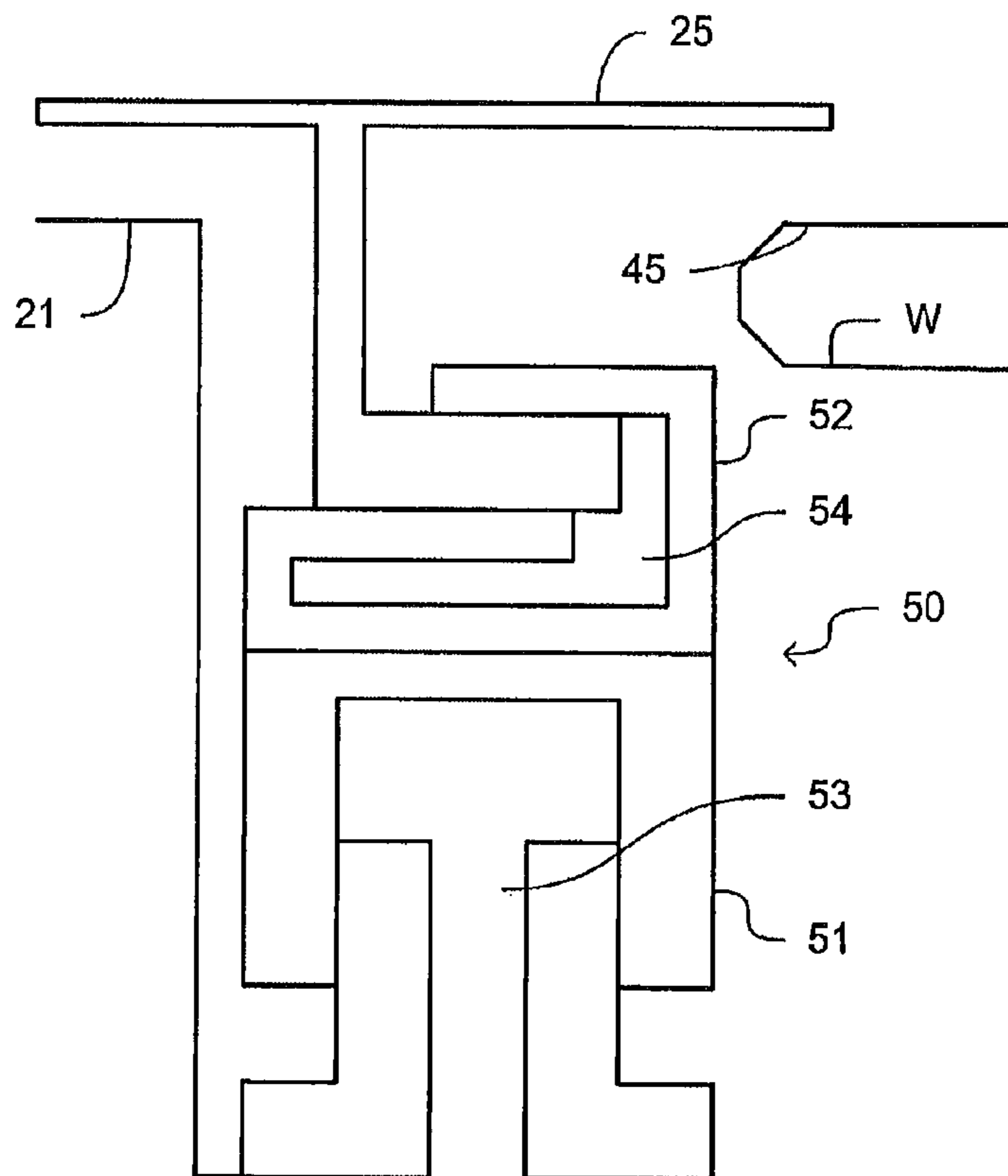


Fig. 13

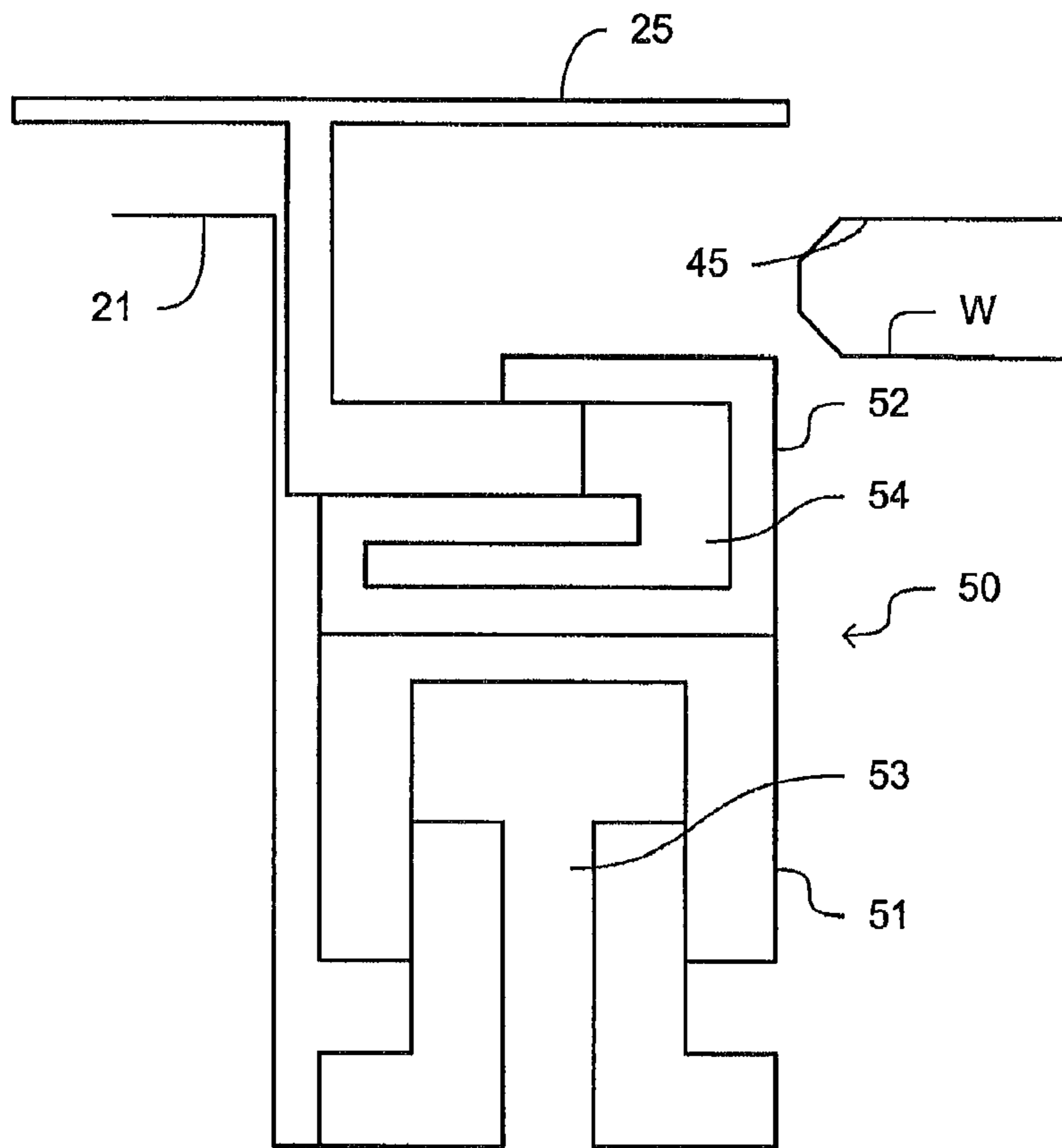


Fig. 14

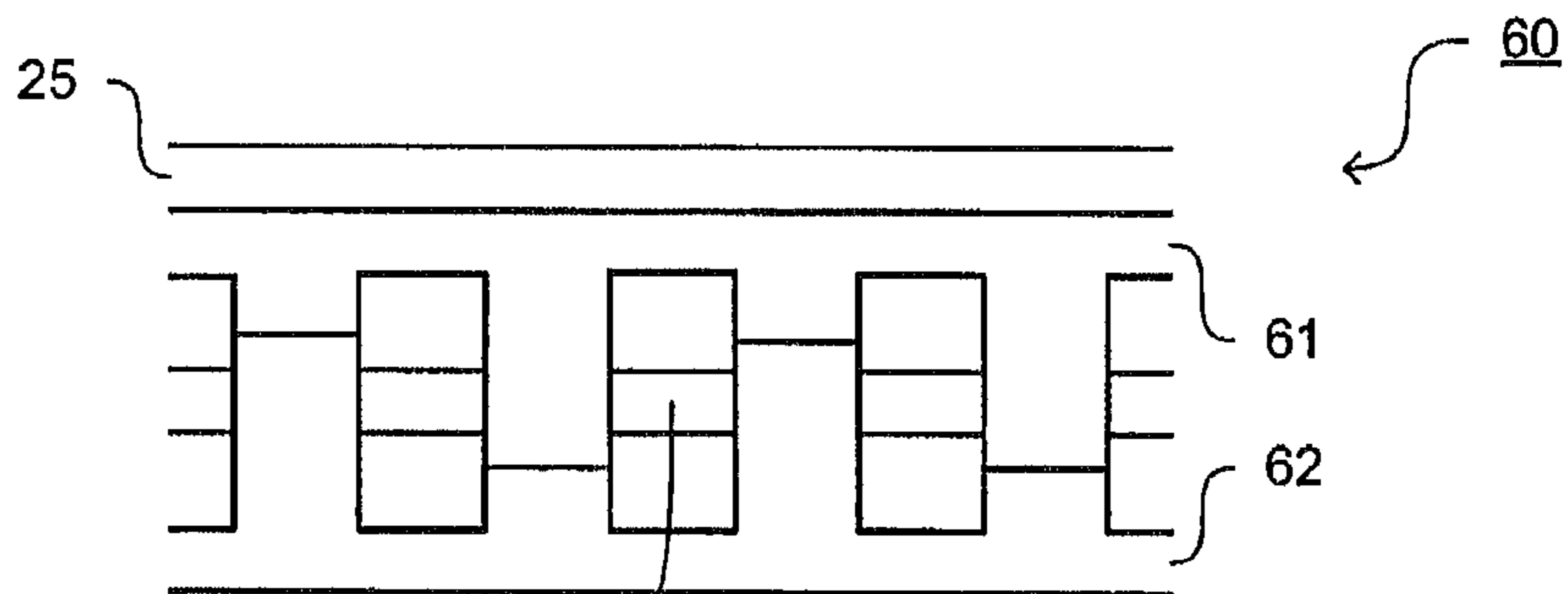


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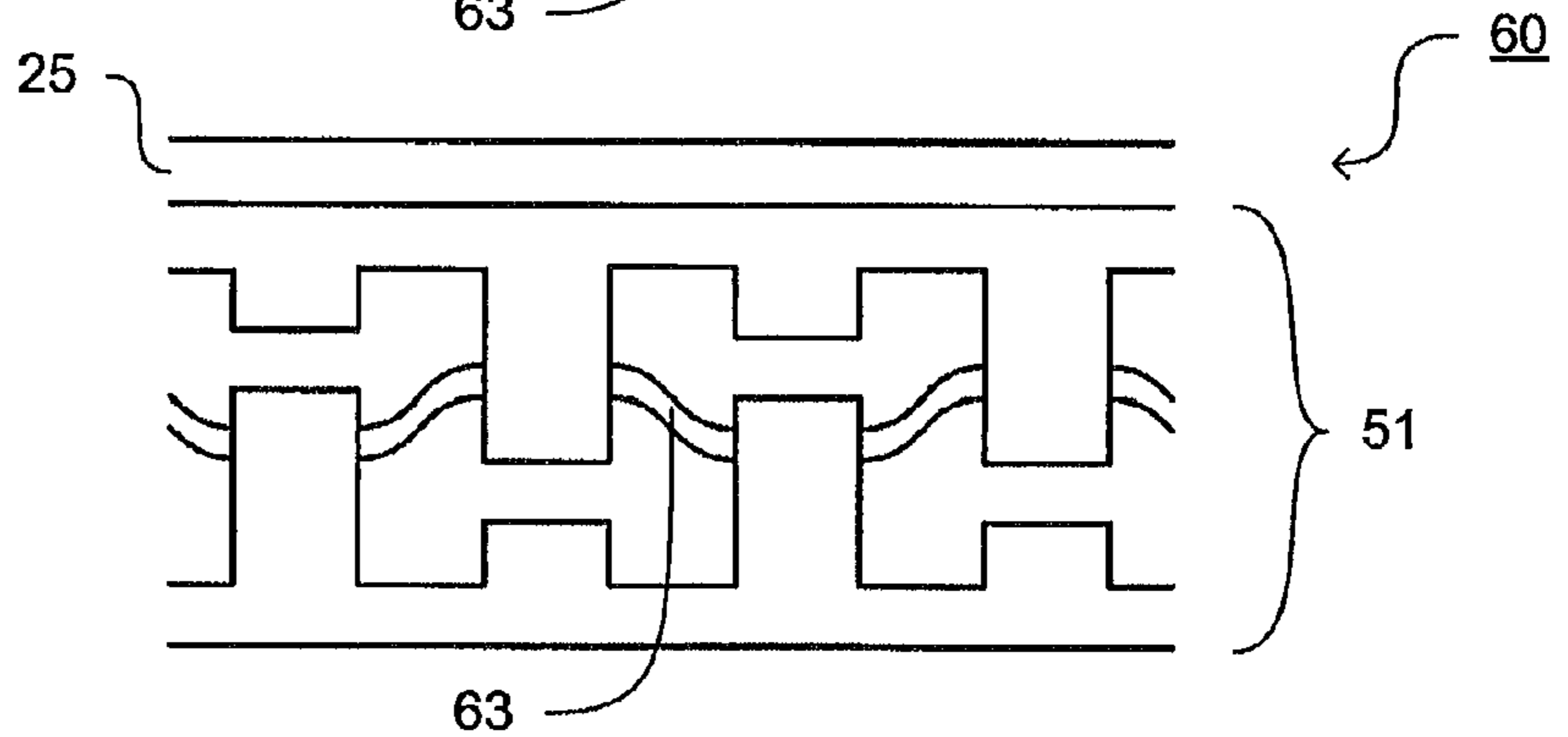


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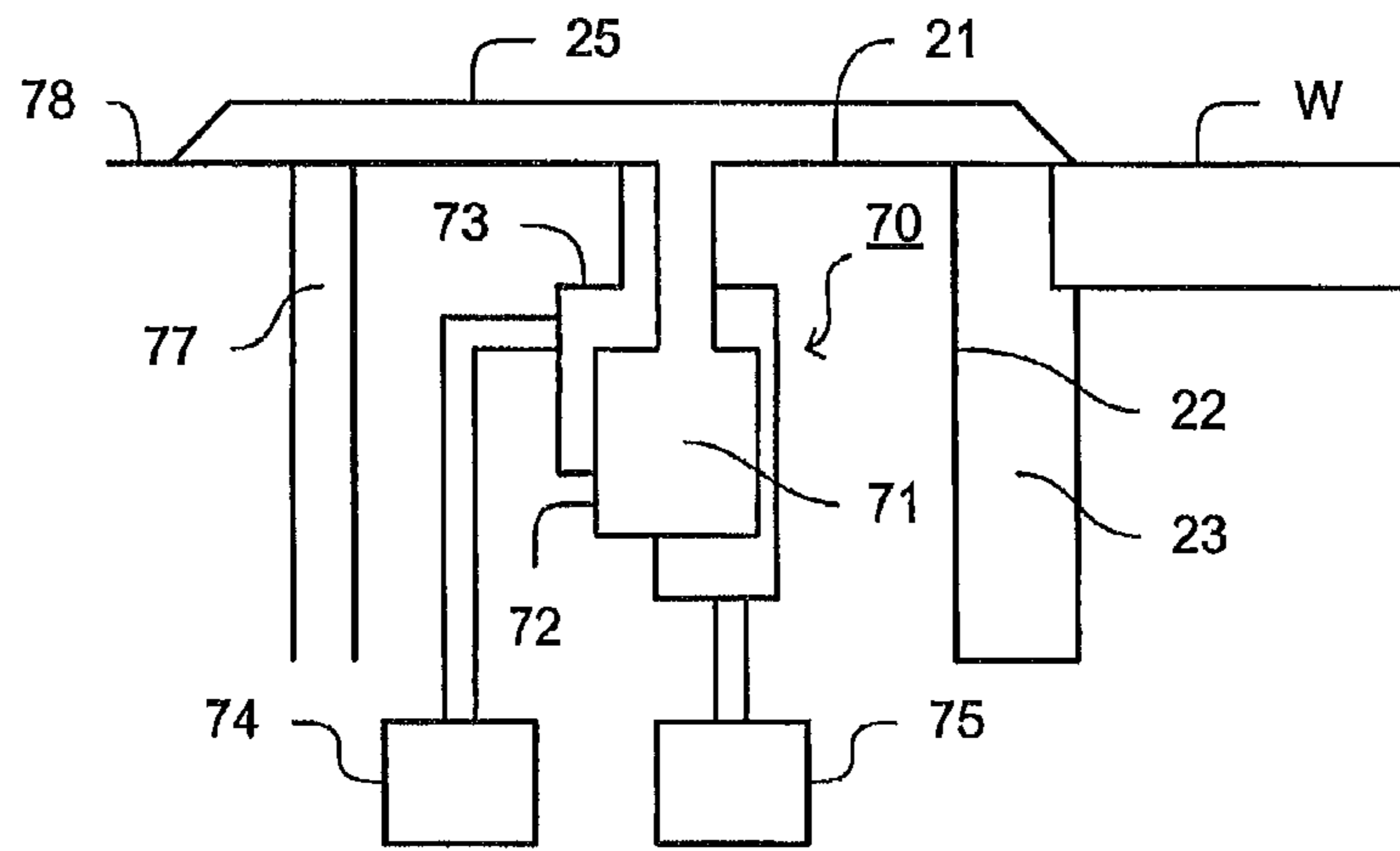


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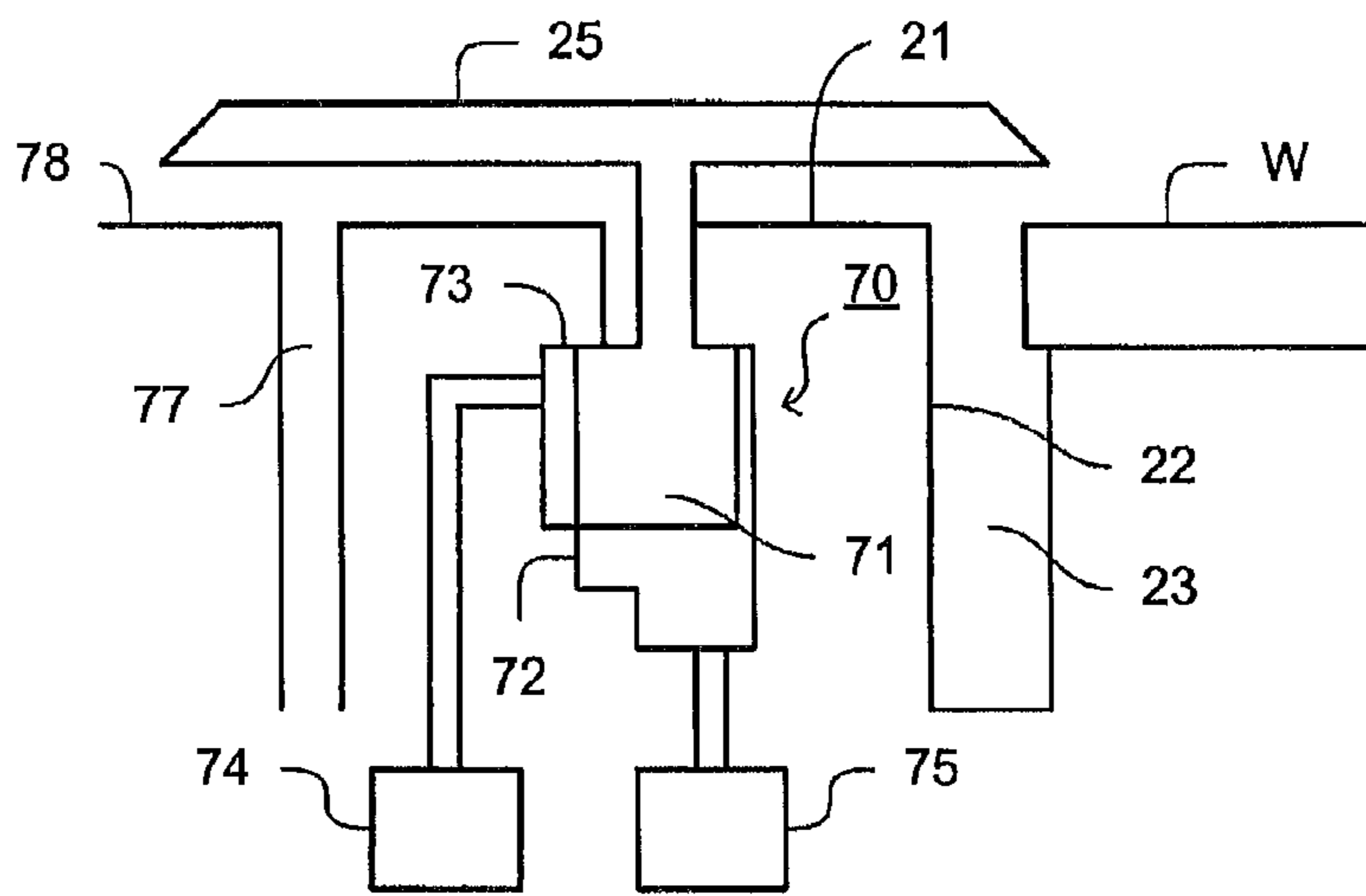


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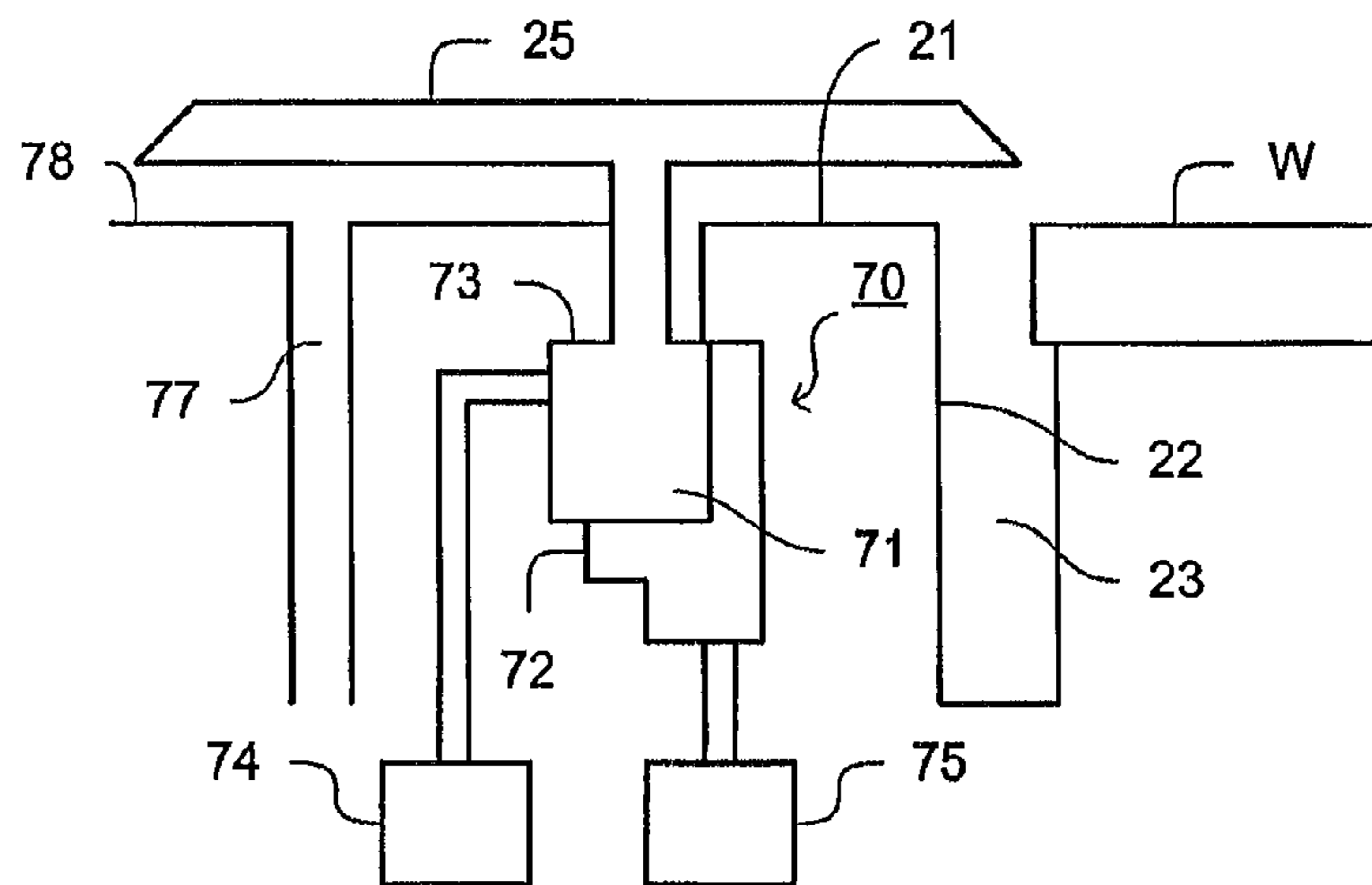


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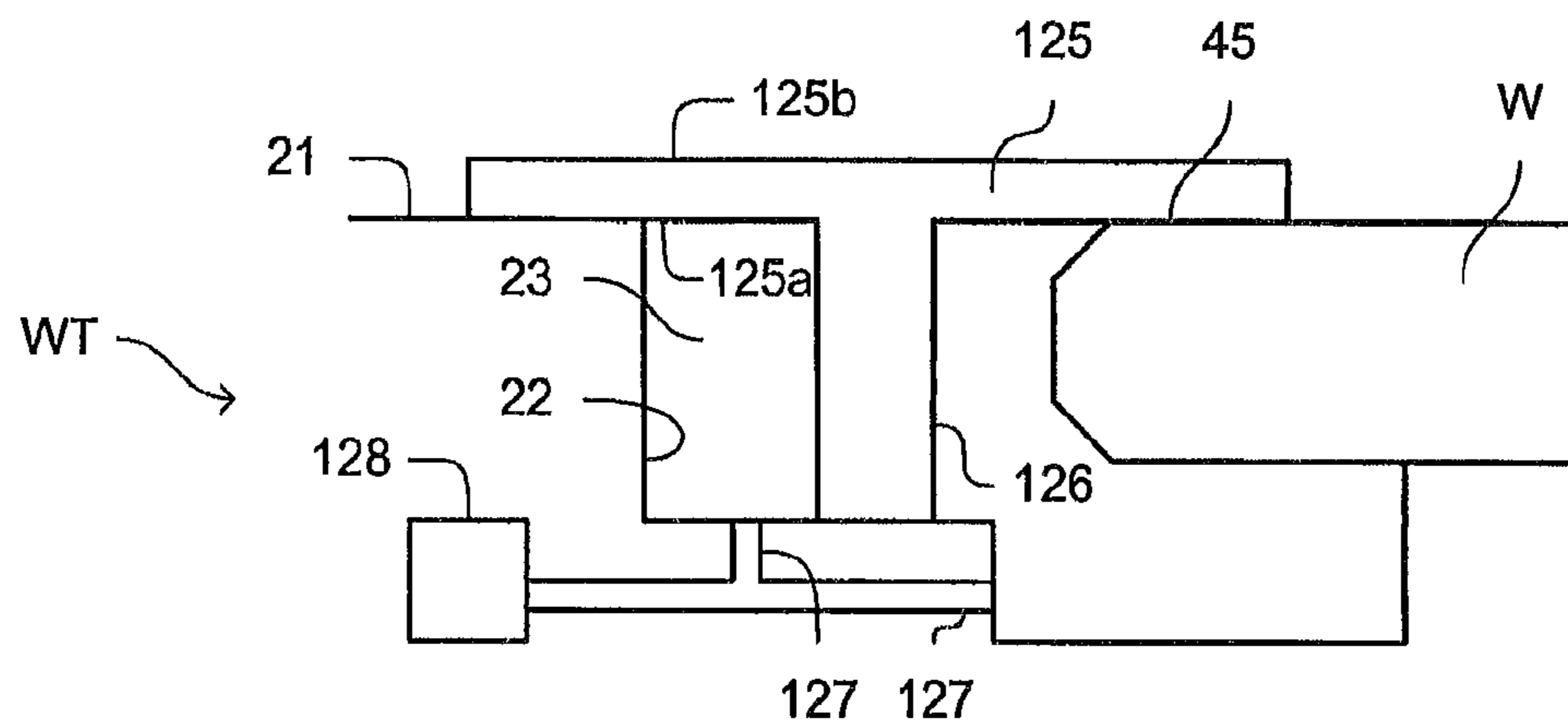


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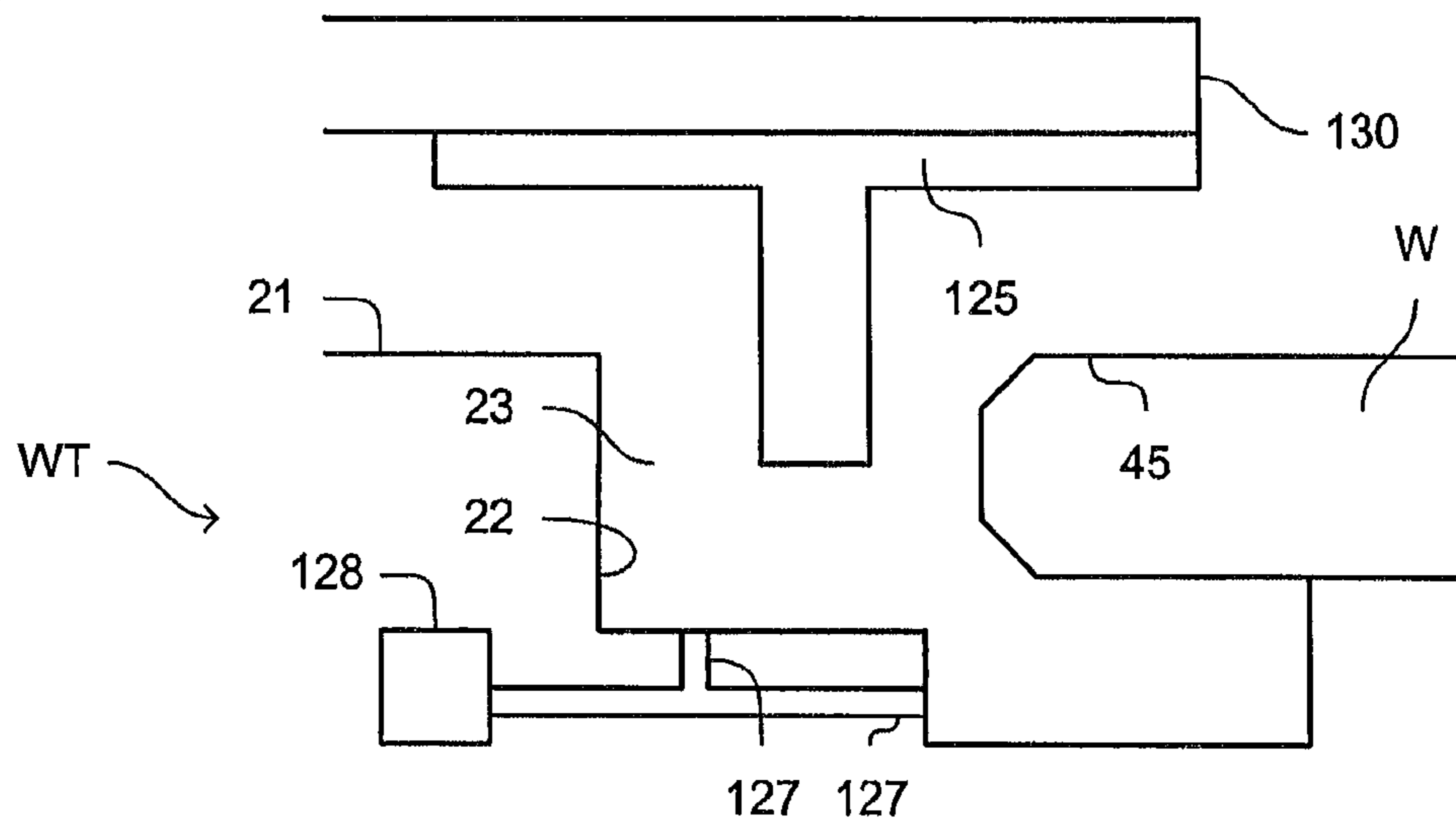


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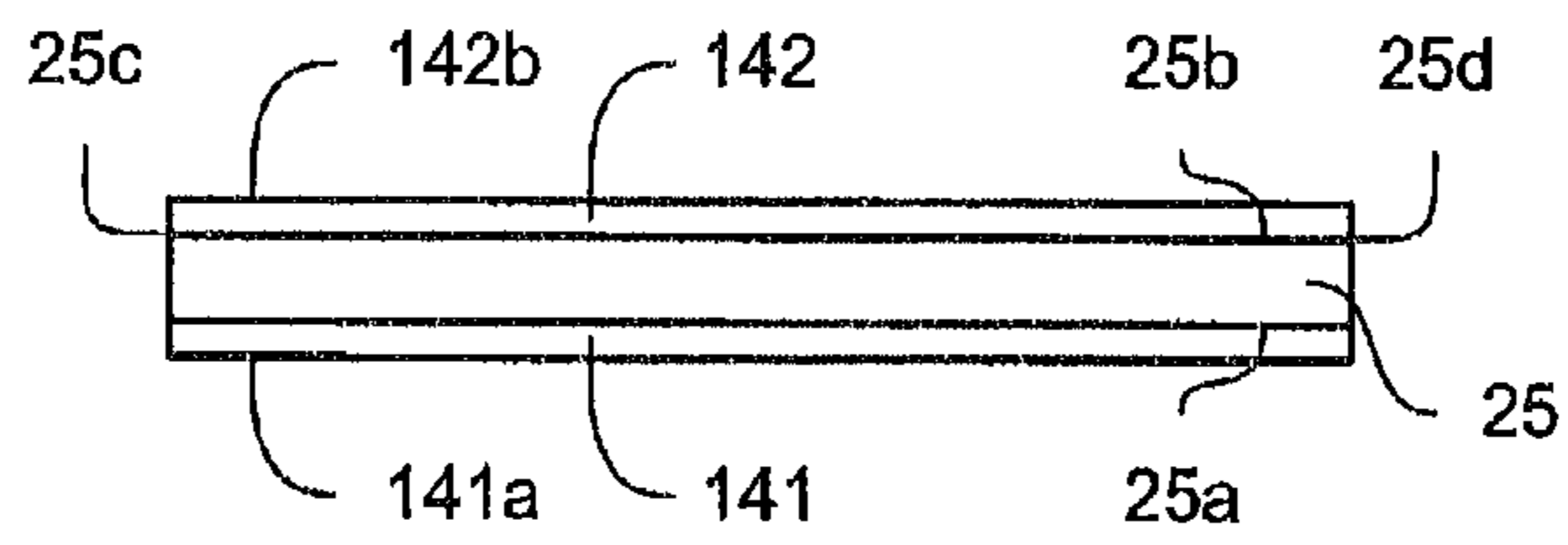


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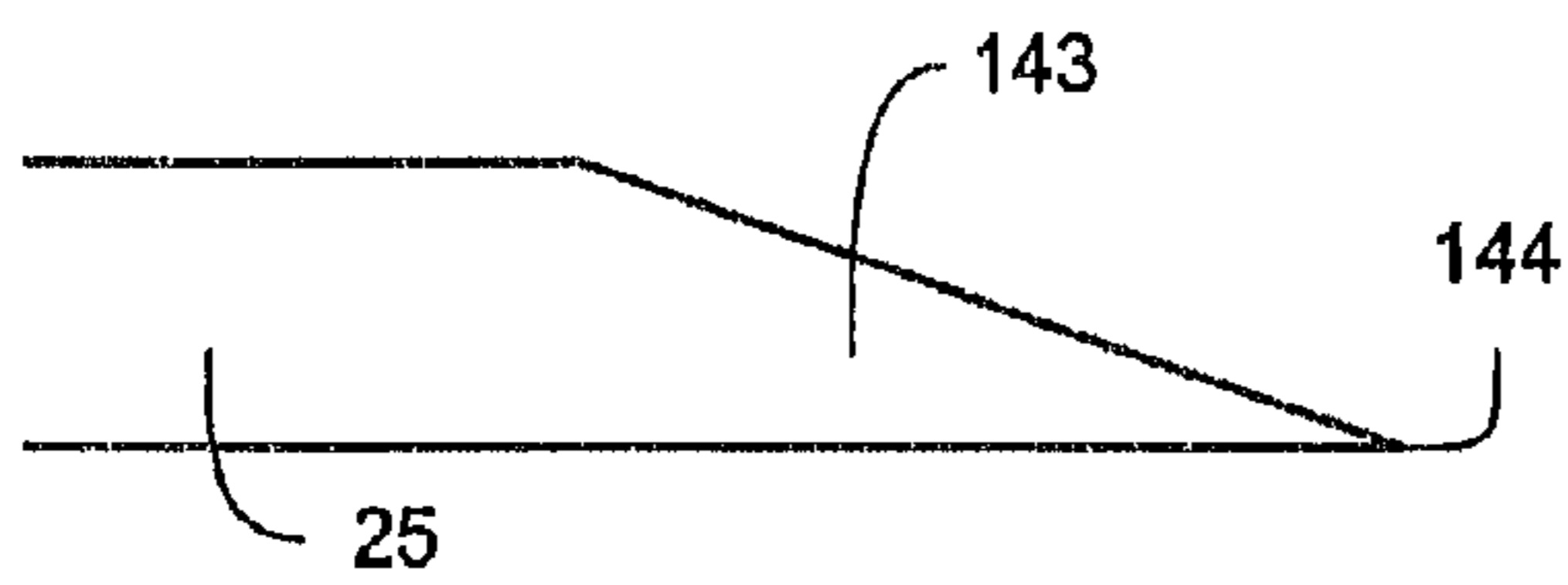


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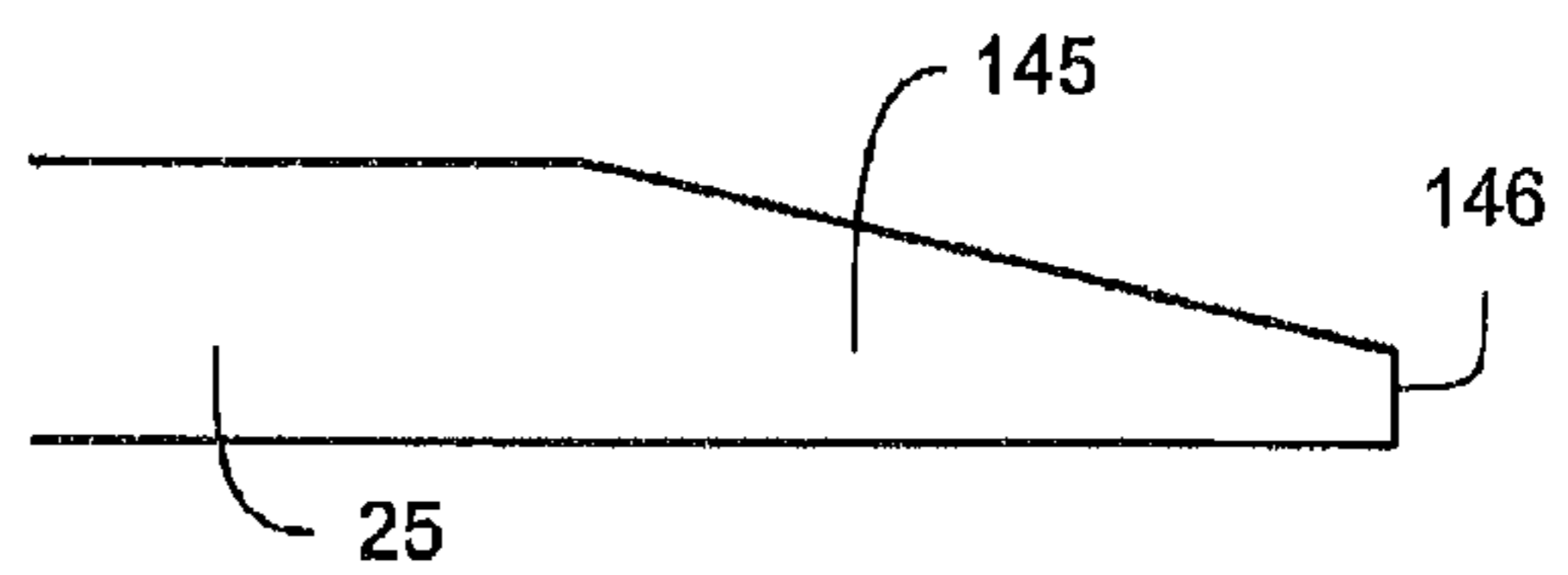


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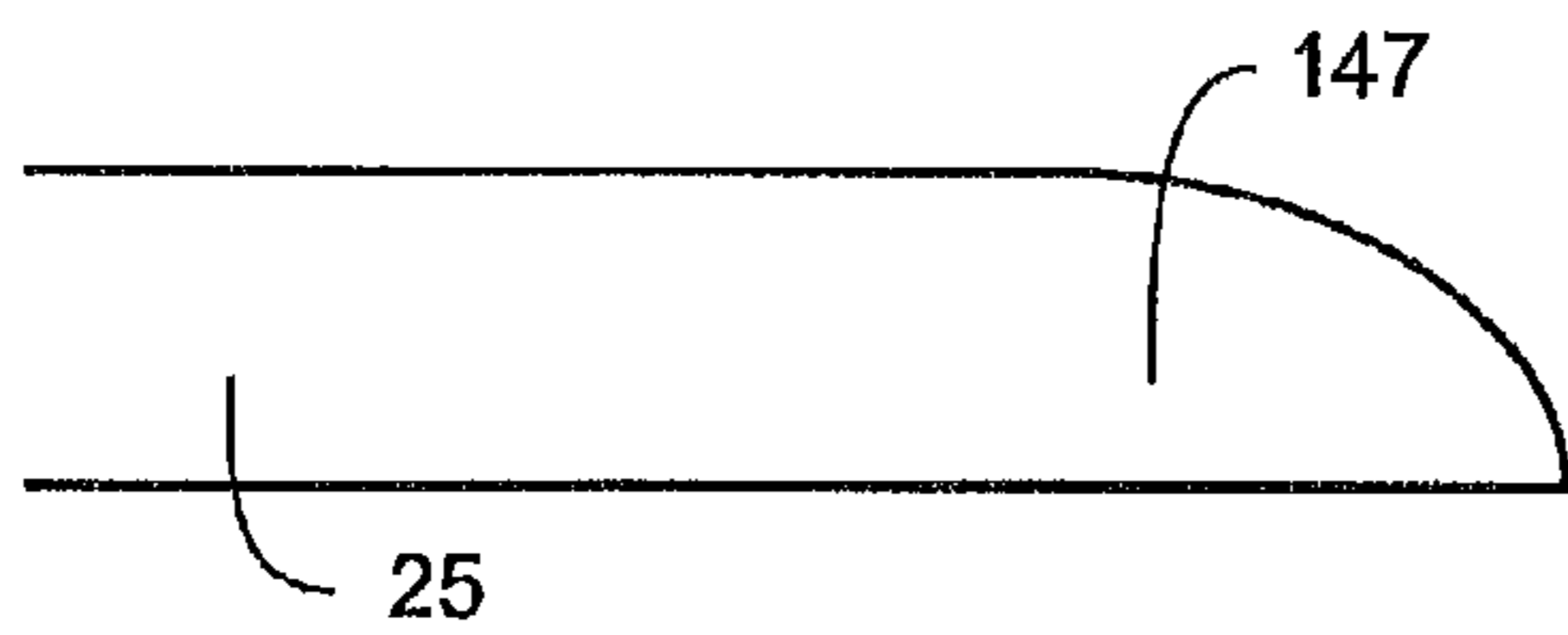


Fig. 25

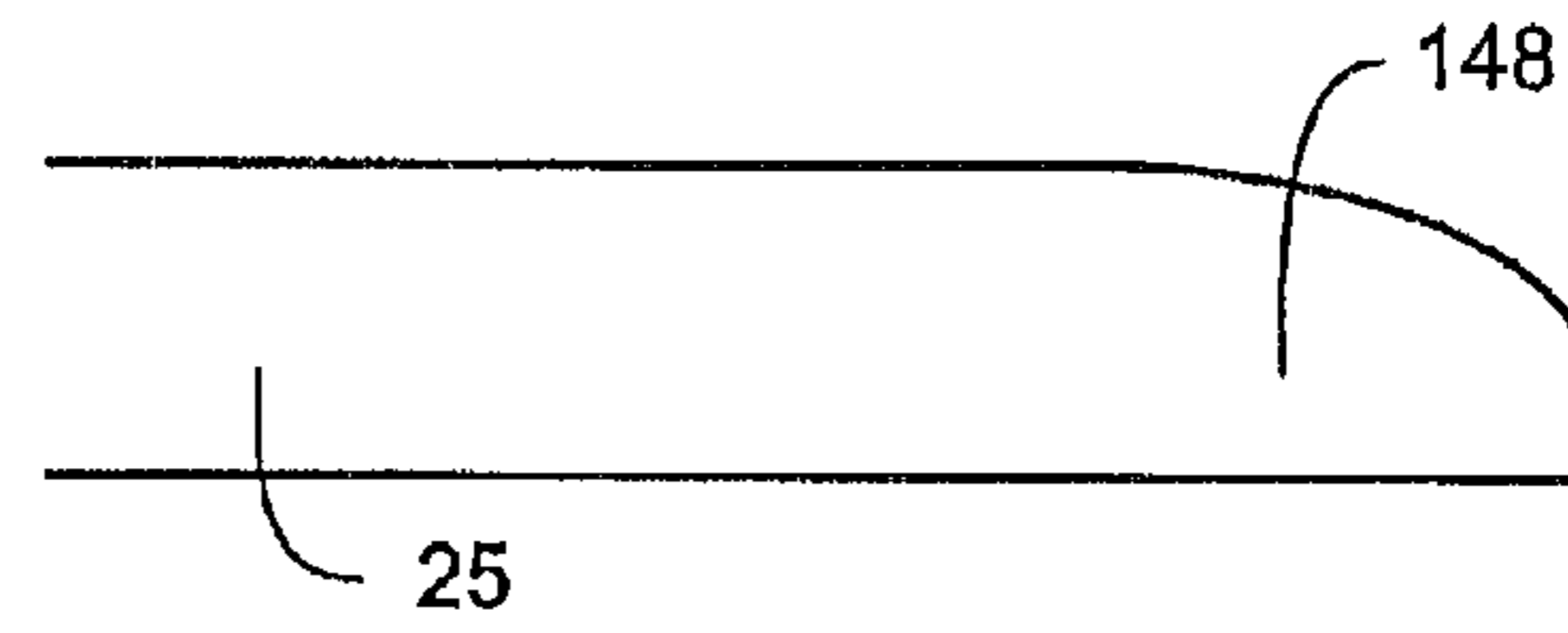


Fig. 26

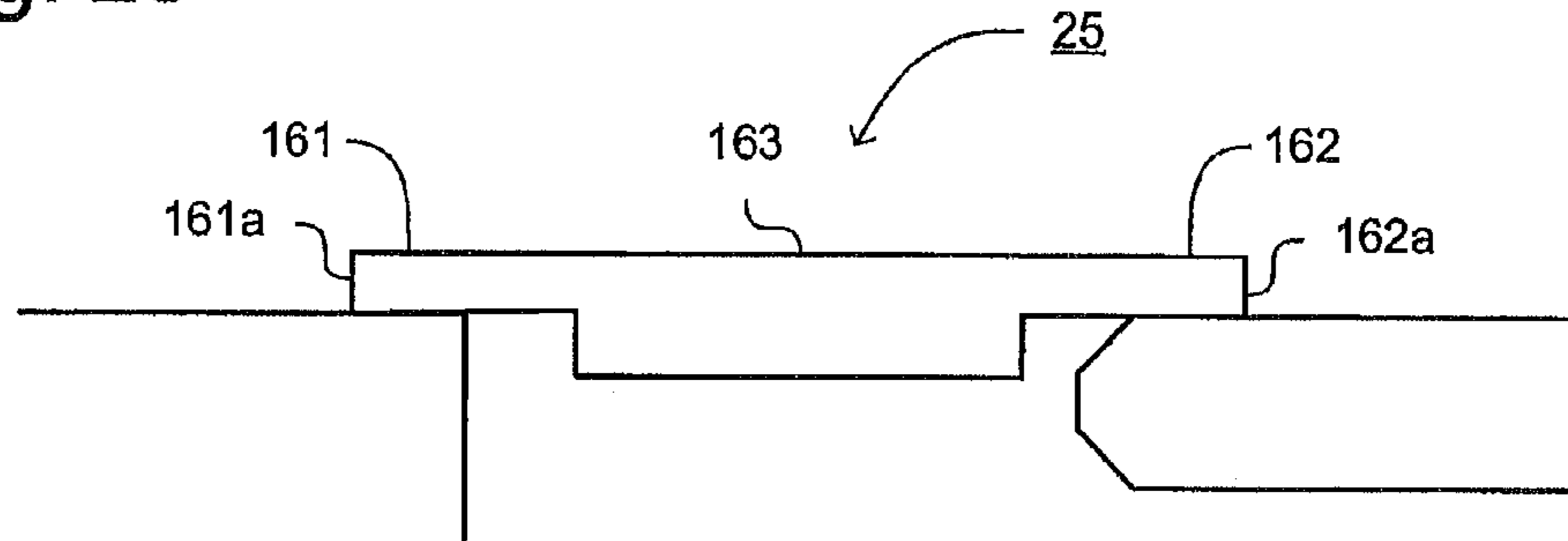


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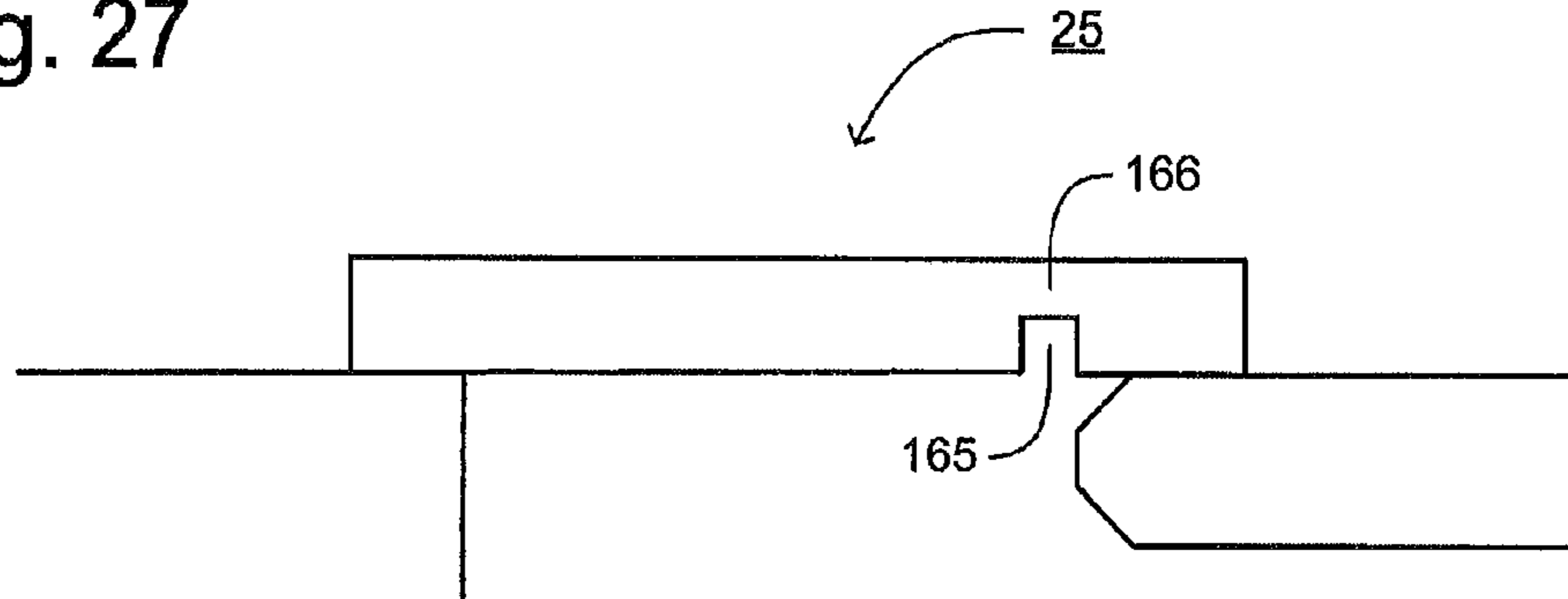


Fig. 28

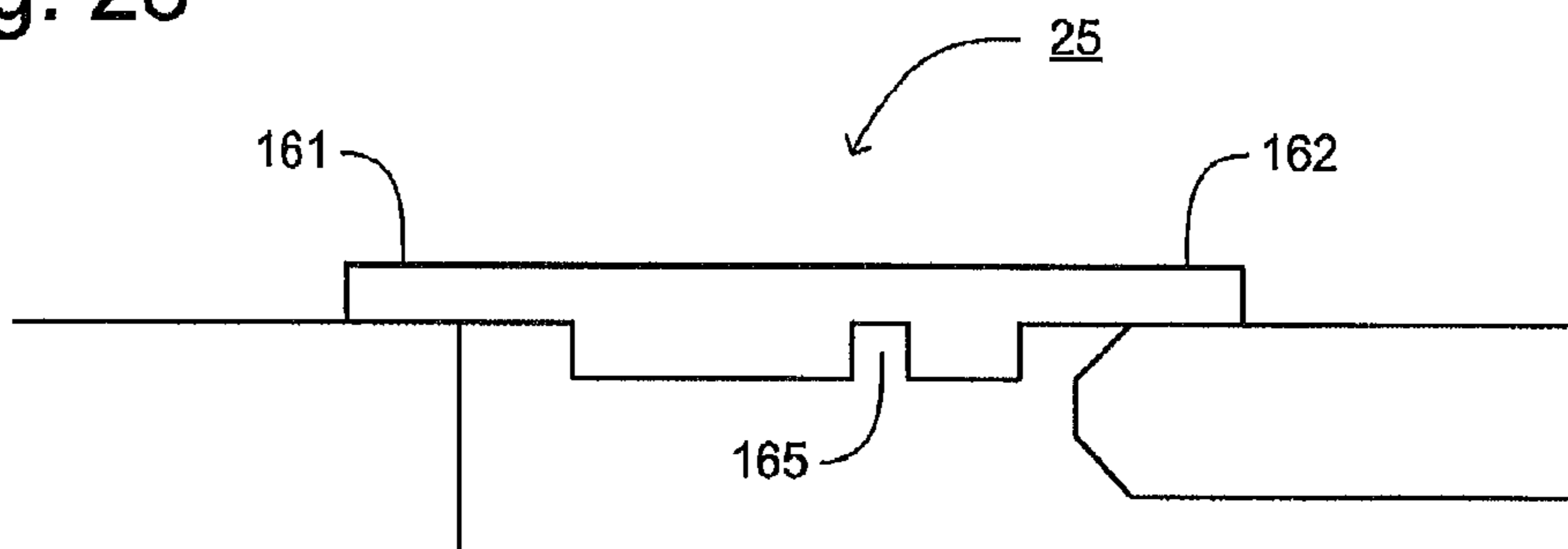


Fig. 29

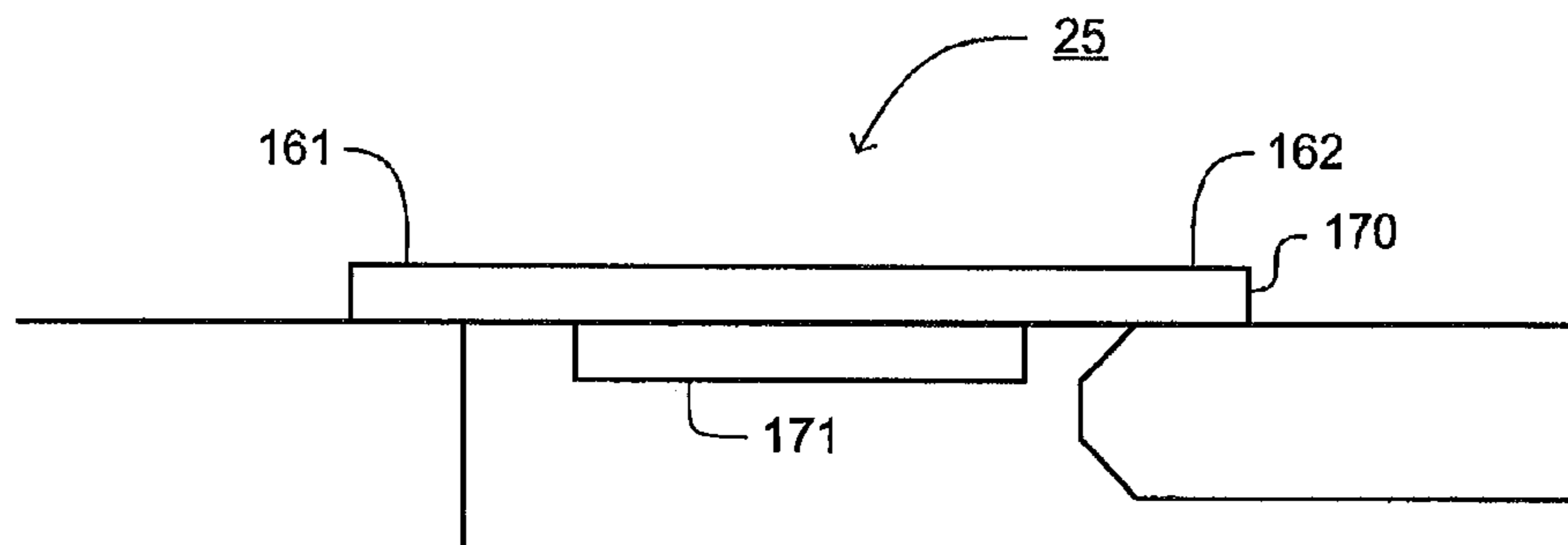


Fig. 30

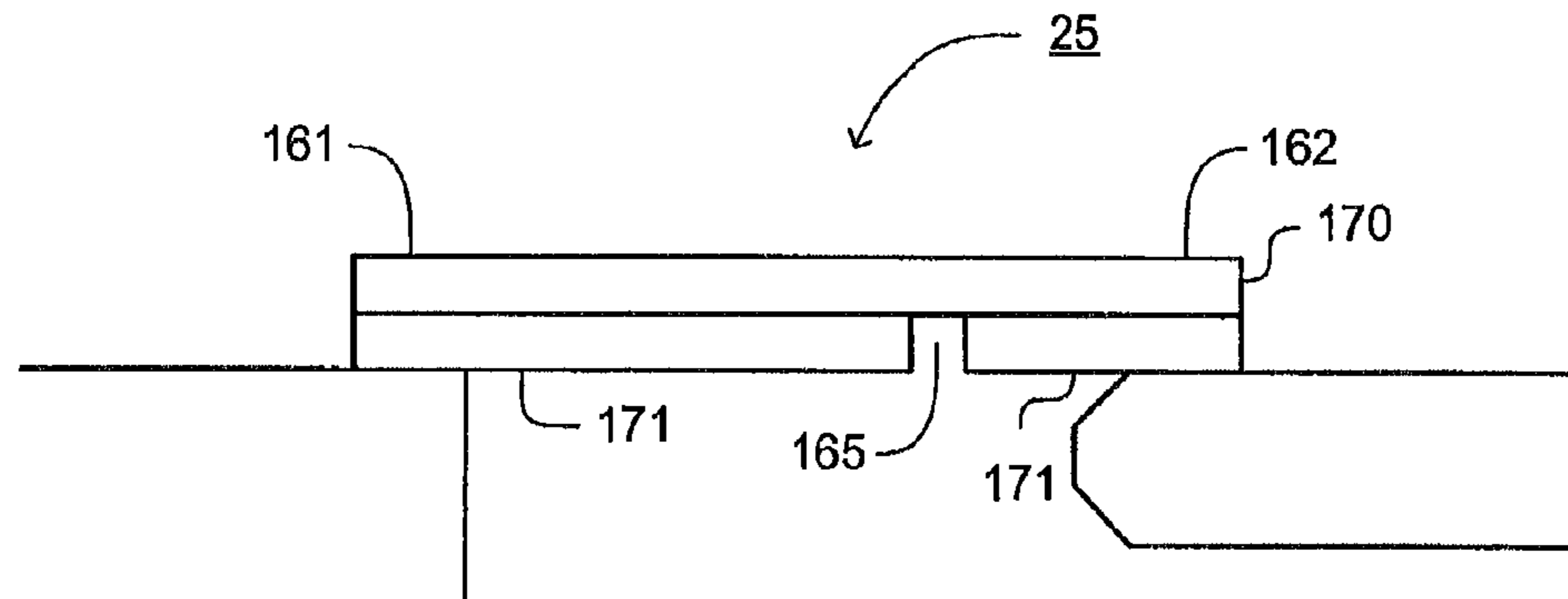


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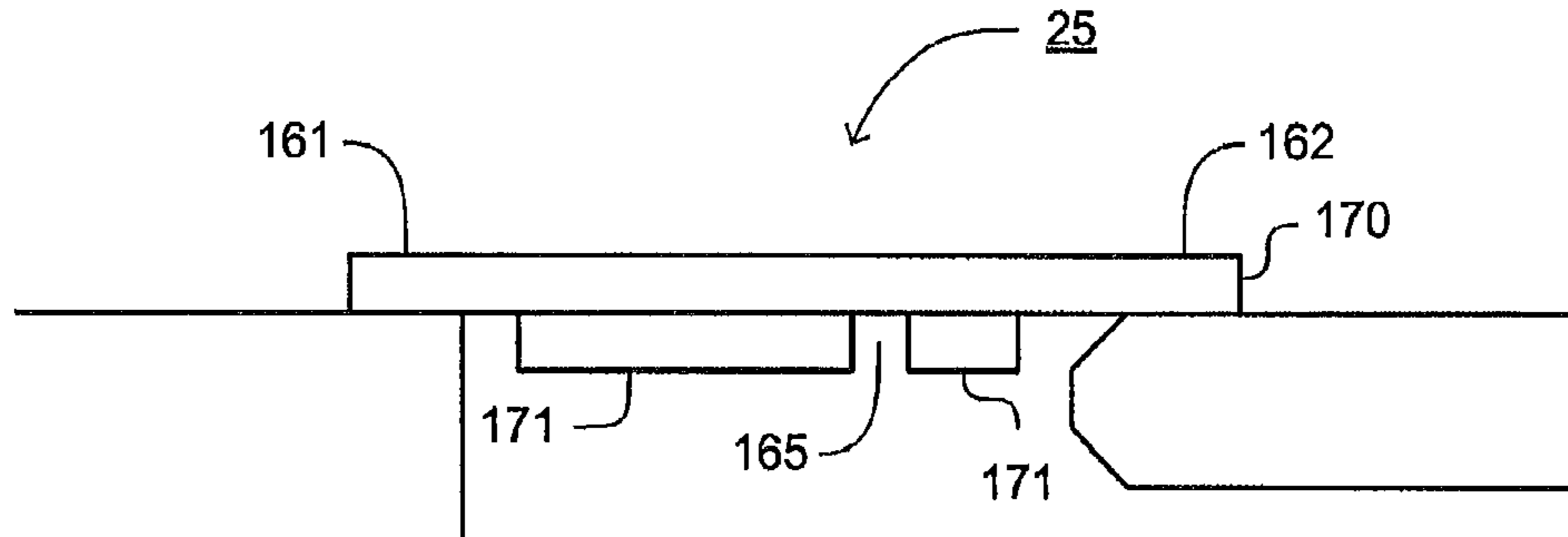


Fig. 32

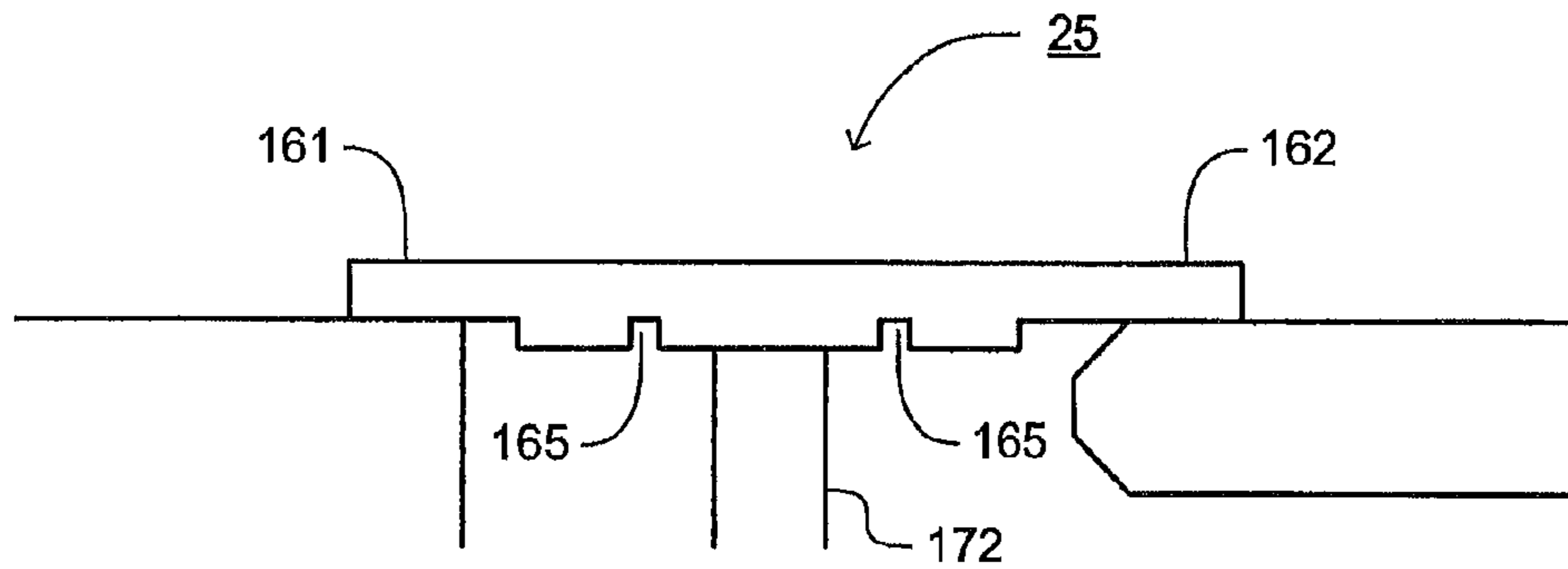


Fig. 33

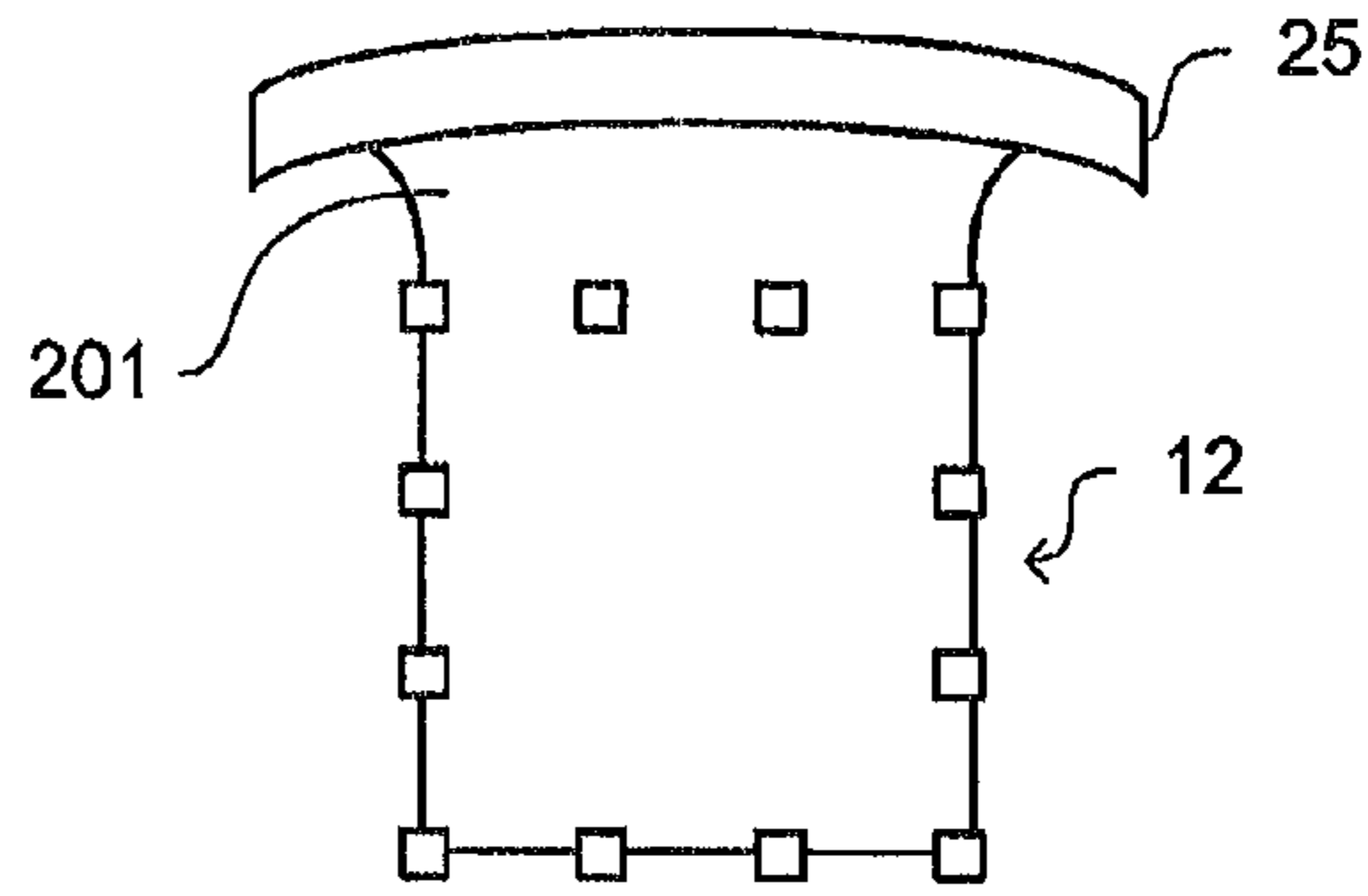


Fig. 34

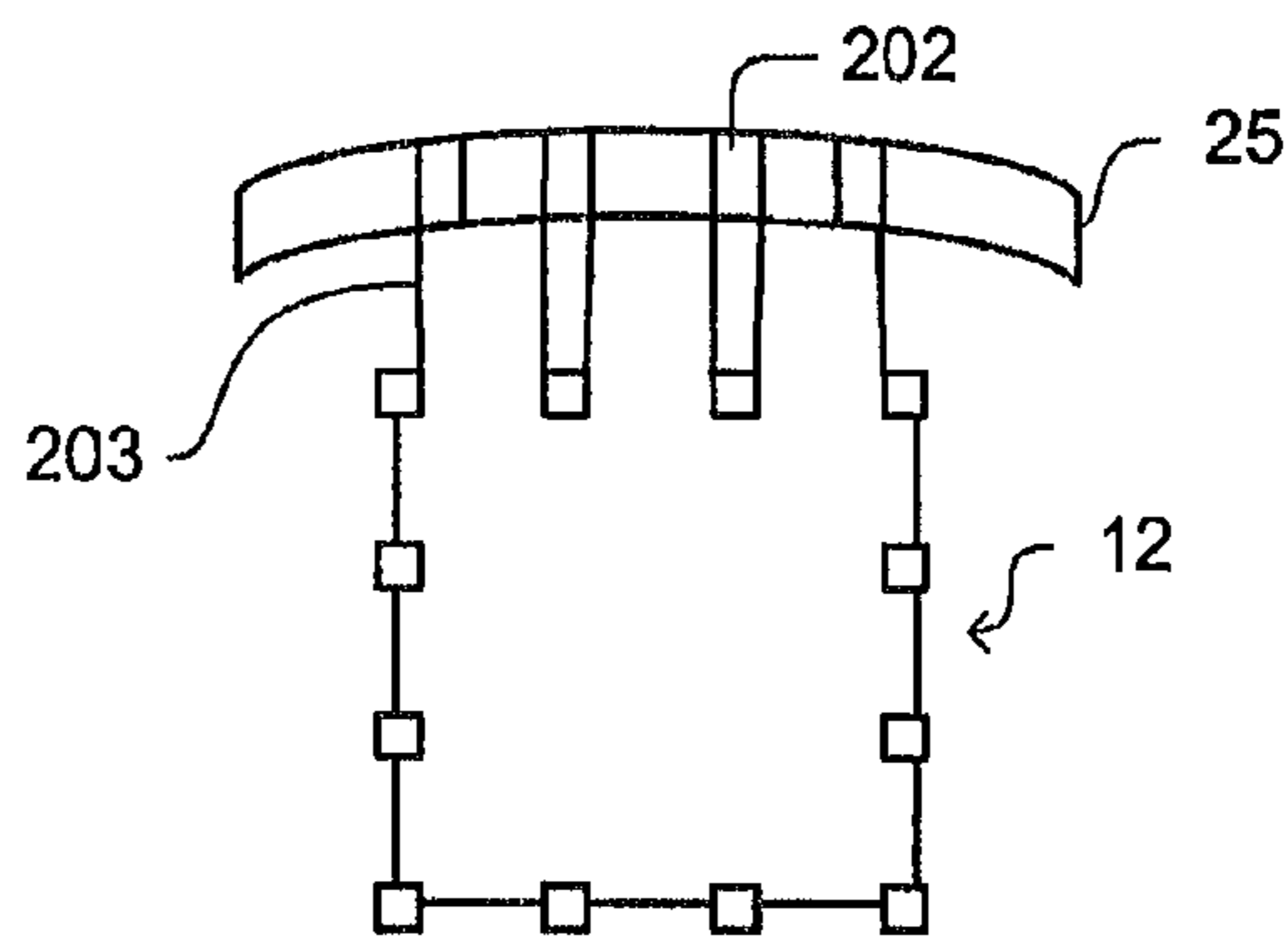


Fig. 35

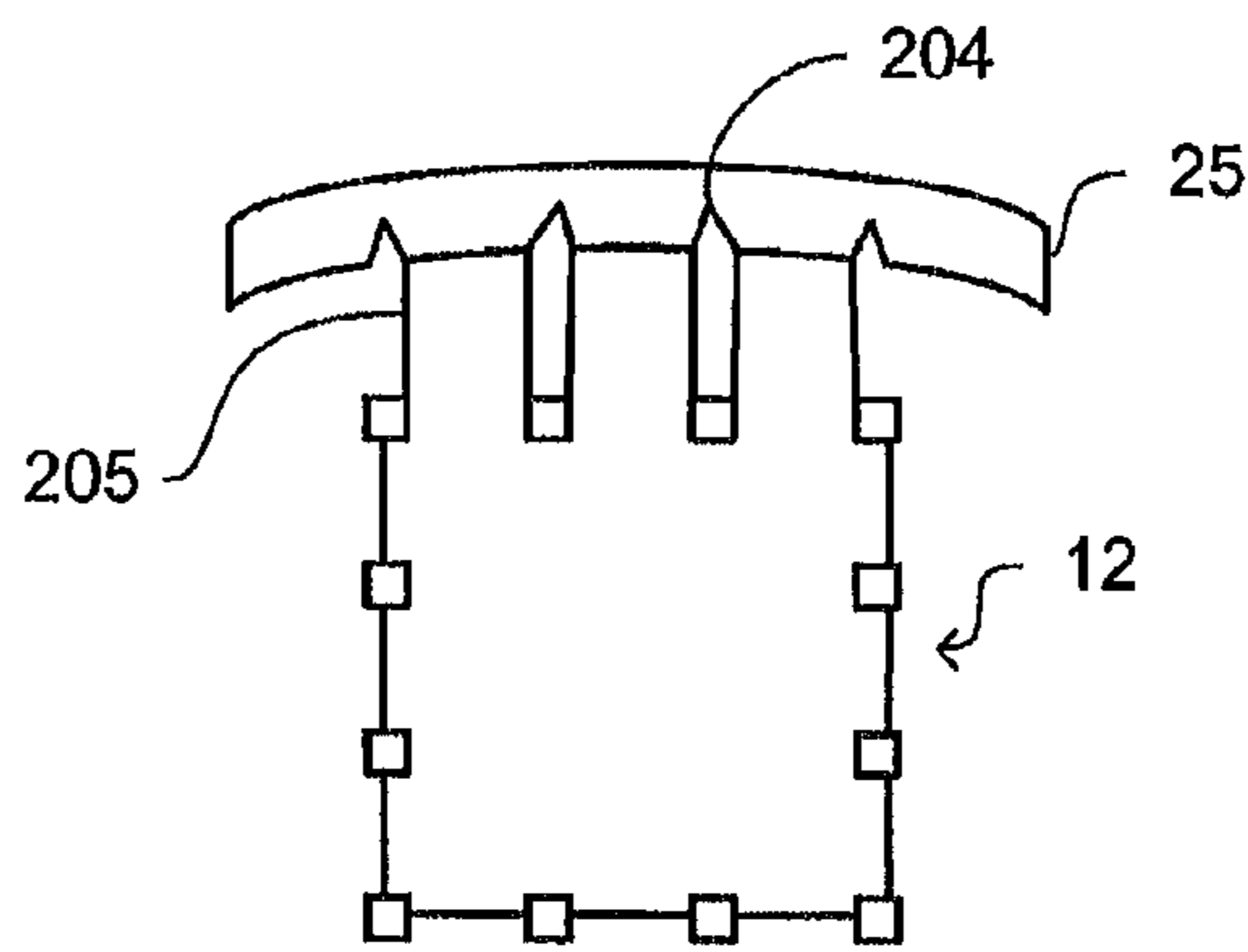


Fig. 36

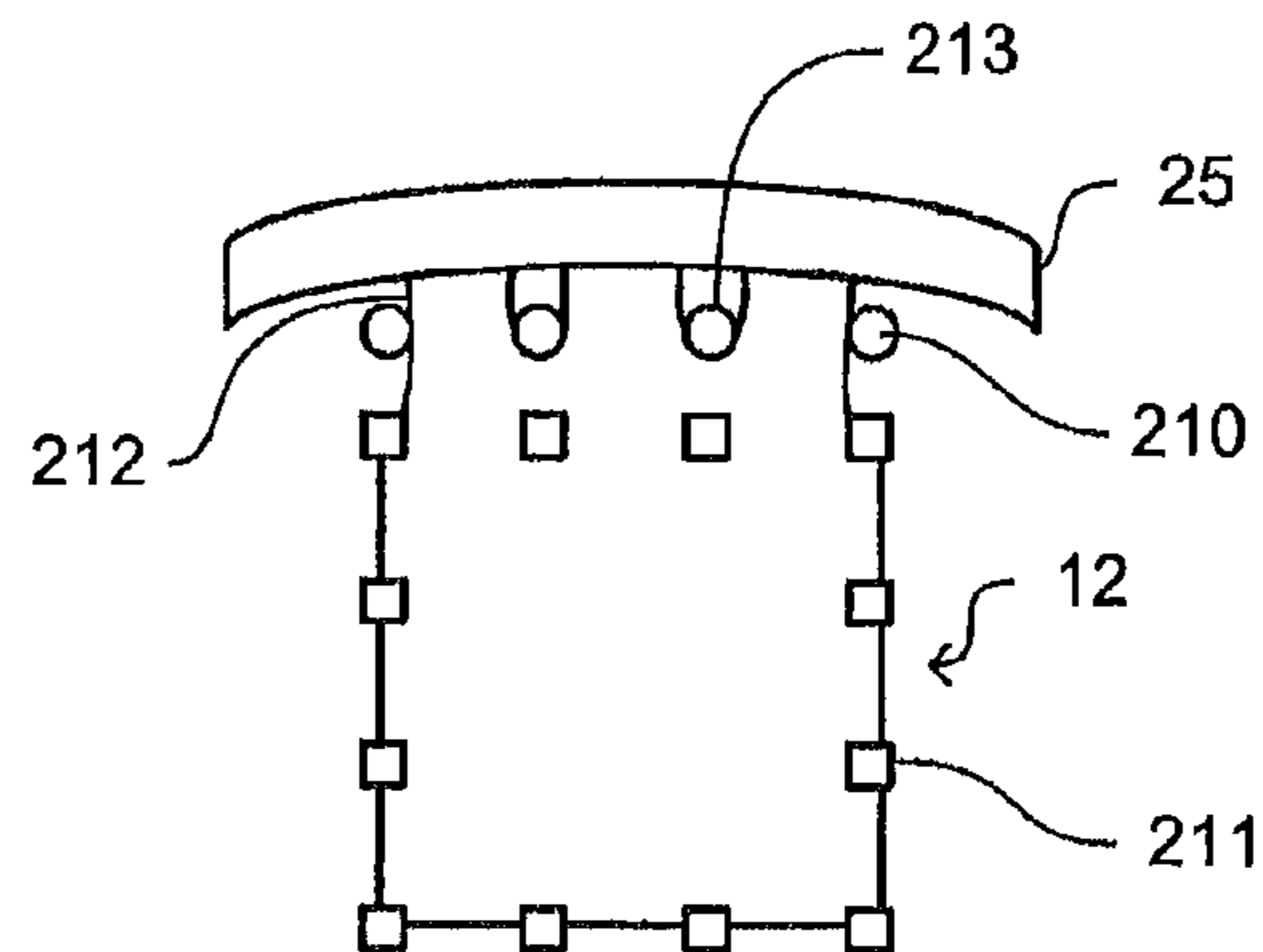


Fig. 37

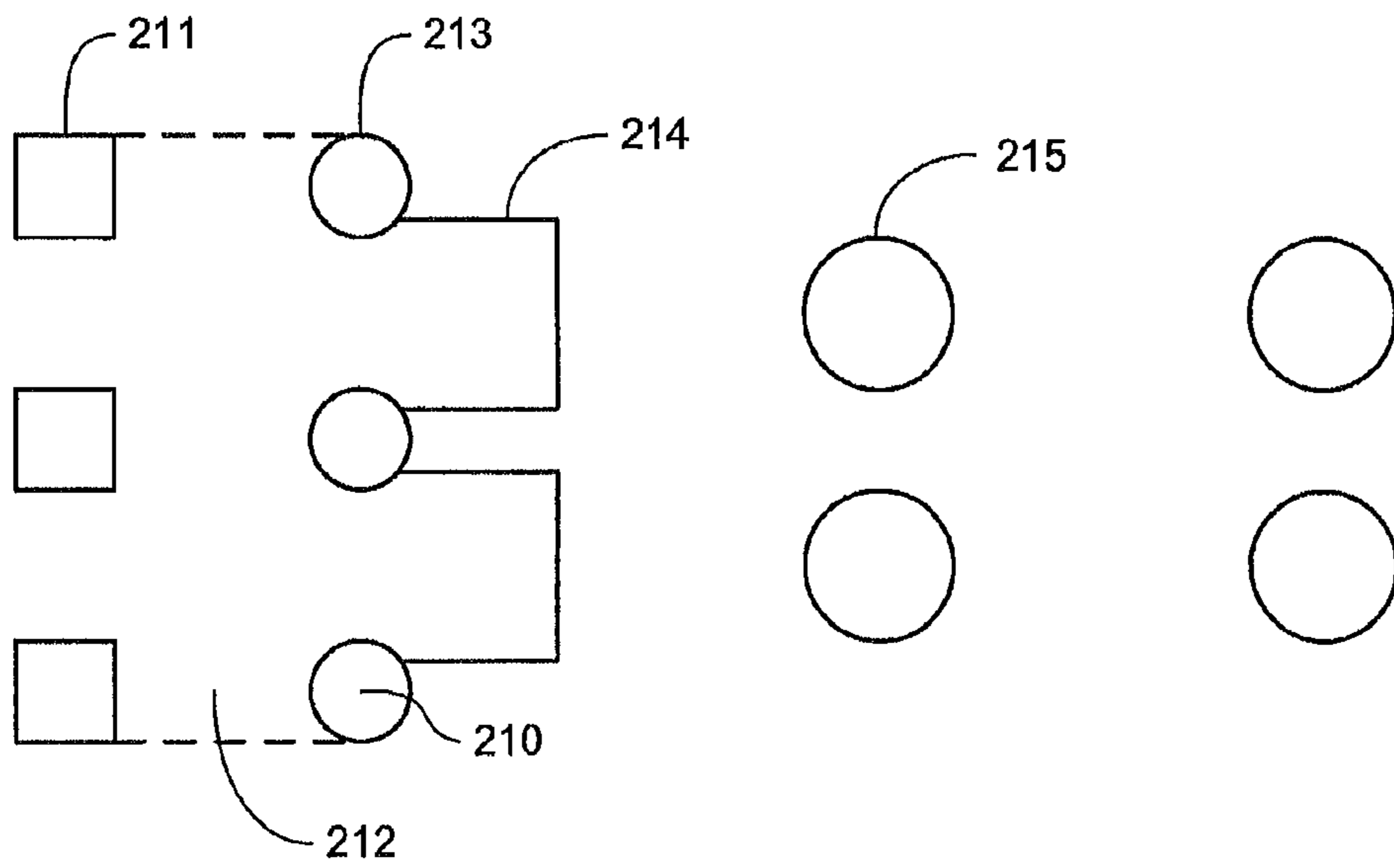


Fig. 38

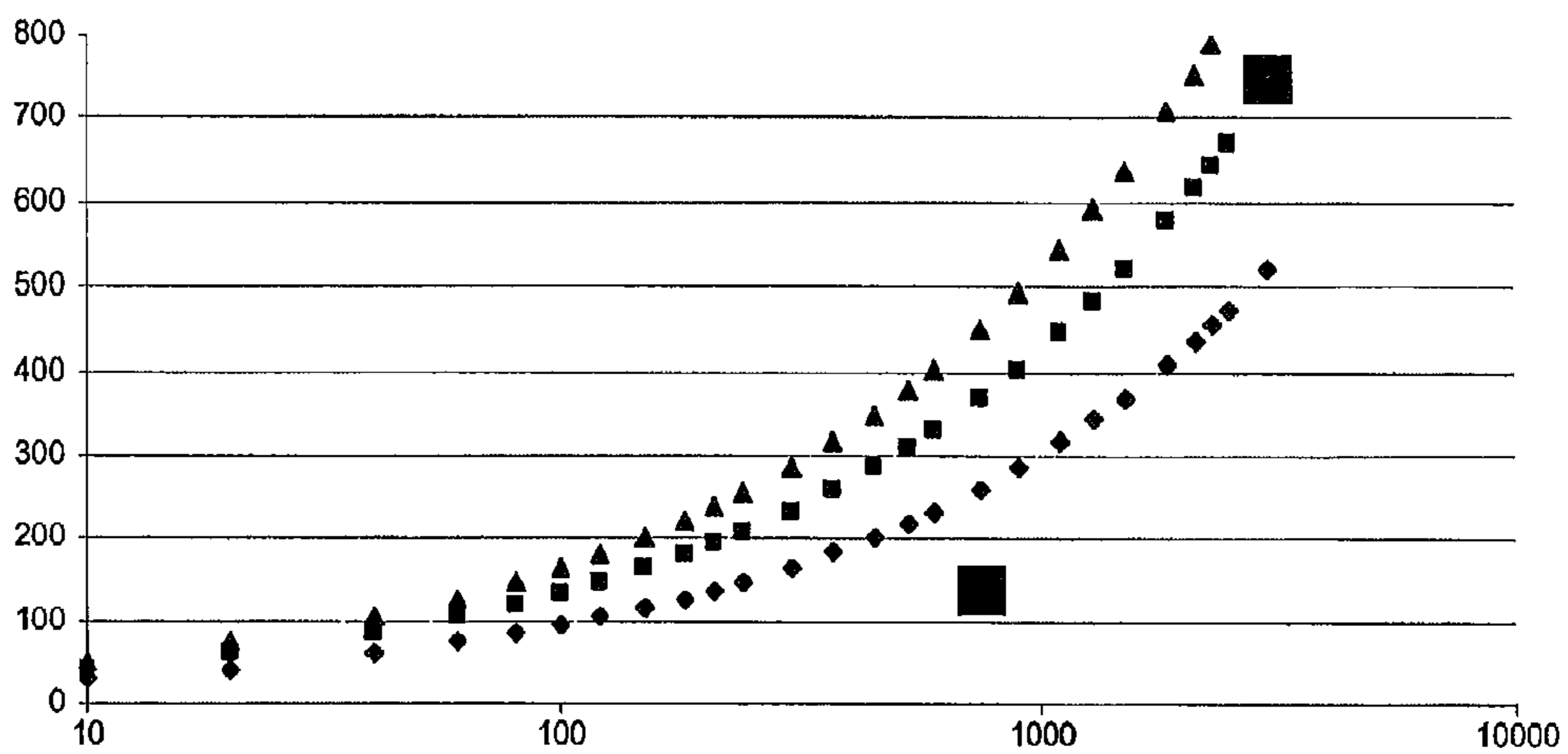


Fig. 39

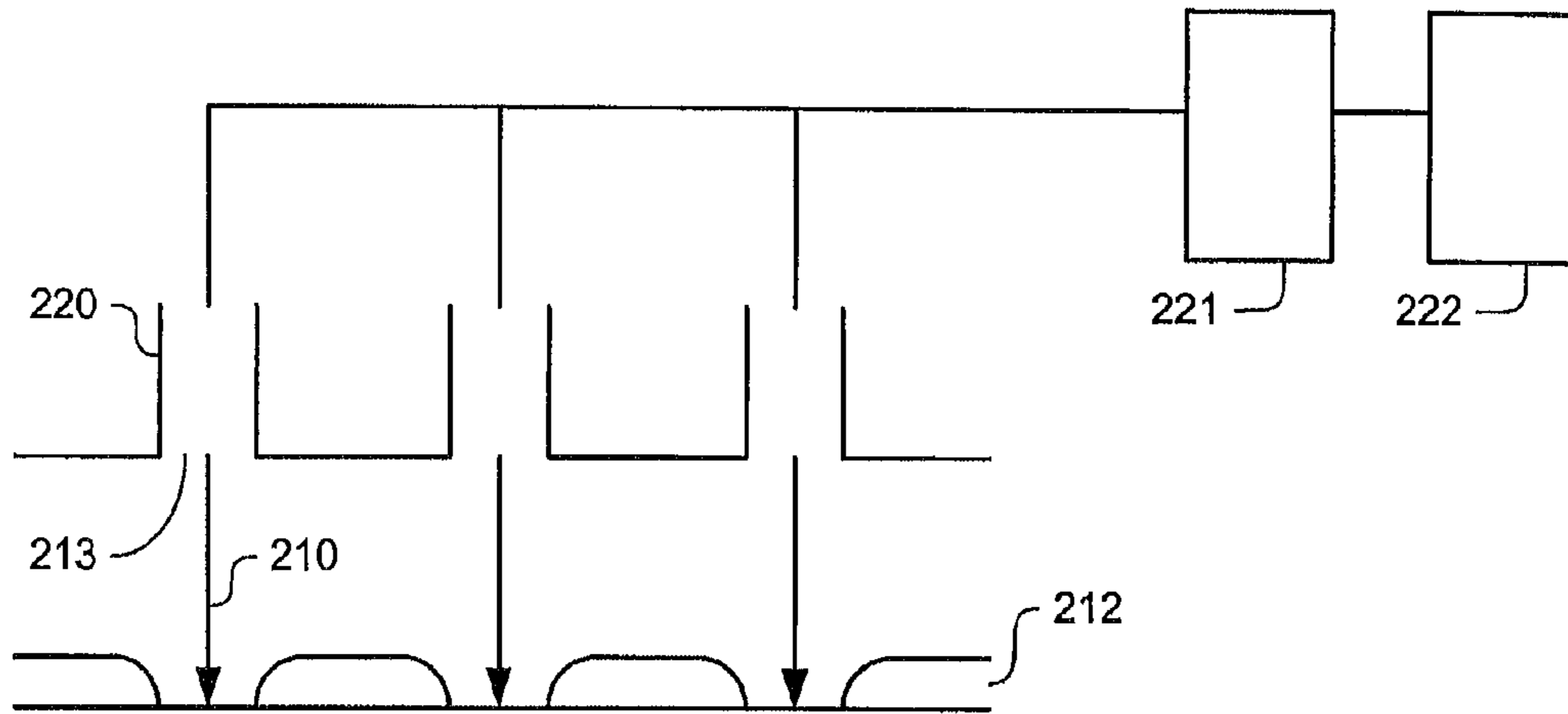
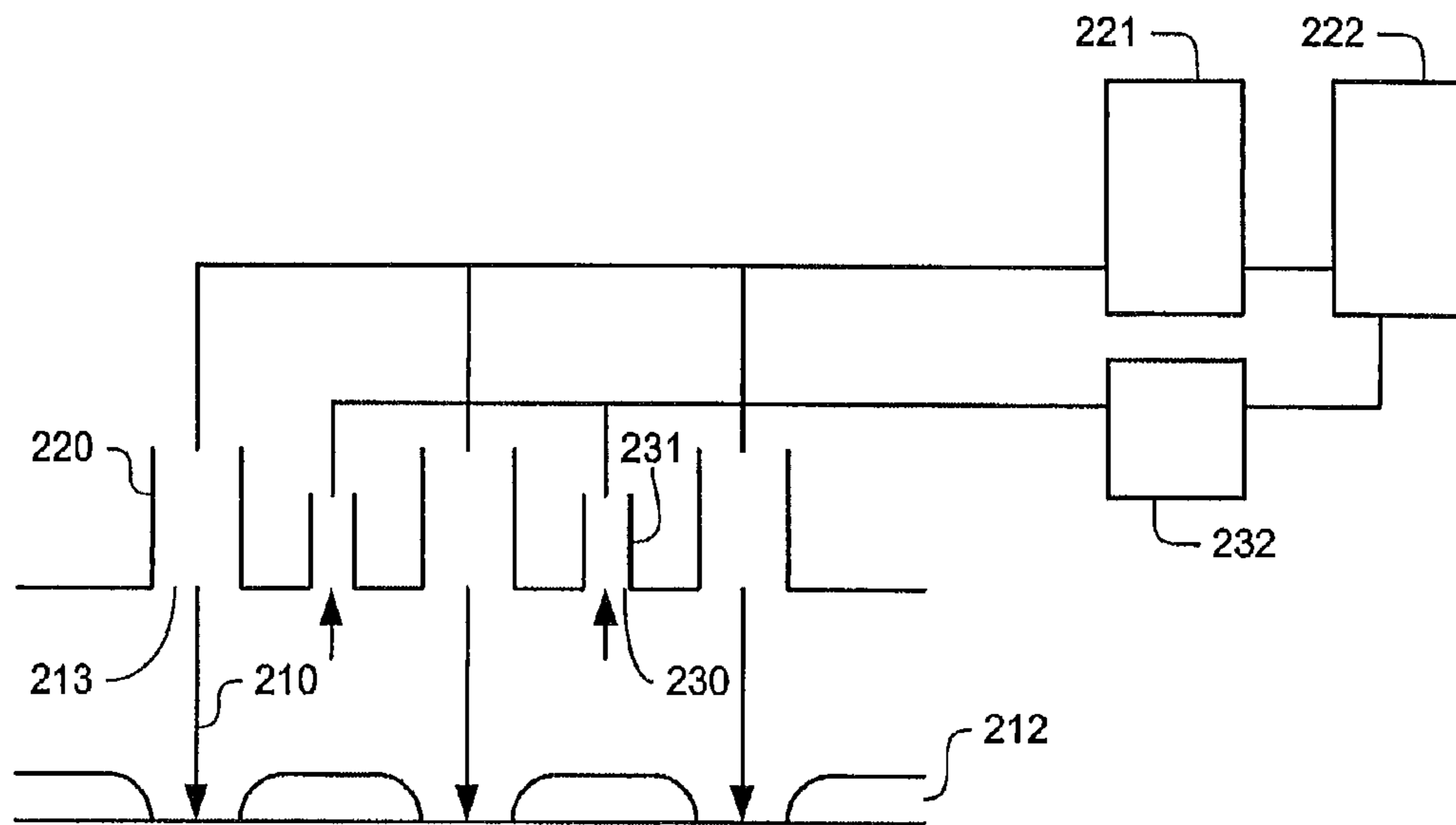


Fig. 40



**LITHOGRAPHIC APPARATUS, FLUID
HANDLING STRUCTURE FOR USE IN A
LITHOGRAPHIC APPARATUS AND DEVICE
MANUFACTURING METHOD**

Matter enclosed in heavy brackets [] appears in the original patent but forms no part of this reissue specification; matter printed in italics indicates the additions made by reissue; a claim printed with strikethrough indicates that the claim was canceled, disclaimed, or held invalid by a prior post-patent action or proceeding.

More than one reissue application has been filed for the reissue of U.S. Pat. No. 8,767,169. The reissue applications are continuation reissue application Ser. No. 16/203,799 (the present application) and reissue application Ser. No. 15/182,514, now allowed, both of which are reissue applications of U.S. Pat. No. 8,767,169.

This application is a continuation reissue patent application of reissue patent application Ser. No. 15/182,514, filed Jun. 14, 2016, which is a reissue application of U.S. patent application Ser. No. 13/109,036, filed May 17, 2011 (now U.S. Pat. No. 8,767,169), which claims priority and benefit under 35 U.S.C. § 119(e) to U.S. Provisional Patent Application No. 61/346,213, filed on May 19, 2010 and to U.S. Provisional Patent Application No. 61/388,972, filed on Oct. 1, 2010. The content of each of the foregoing applications is incorporated herein in its entirety by reference.

FIELD

The present invention relates to a lithographic apparatus, a fluid handling structure for use in a lithographic apparatus and a device manufacturing method.

BACKGROUND

A lithographic apparatus is a machine that applies a desired pattern onto a substrate, usually onto a target portion of the substrate. A lithographic apparatus can be used, for example, in the manufacture of integrated circuits (ICs). In that instance, a patterning device, which is alternatively referred to as a mask or a reticle, may be used to generate a circuit pattern to be formed on an individual layer of the IC. This pattern can be transferred onto a target portion (e.g. comprising part of, one, or several dies) on a substrate (e.g. a silicon wafer). Transfer of the pattern is typically via imaging onto a layer of radiation-sensitive material (resist) provided on the substrate. In general, a single substrate will contain a network of adjacent target portions that are successively patterned. Known lithographic apparatus include so-called steppers, in which each target portion is irradiated by exposing an entire pattern onto the target portion at one time, and so-called scanners, in which each target portion is irradiated by scanning the pattern through a radiation beam in a given direction (the "scanning"-direction) while synchronously scanning the substrate parallel or anti-parallel to this direction. It is also possible to transfer the pattern from the patterning device to the substrate by imprinting the pattern onto the substrate.

It has been proposed to immerse the substrate in the lithographic projection apparatus in a liquid having a relatively high refractive index, e.g. water, so as to fill a space between the final element of the projection system and the substrate. In an embodiment, the liquid is distilled water,

although another liquid can be used. An embodiment of the present invention will be described with reference to liquid. However, another liquid may be suitable, particularly a wetting fluid, an incompressible fluid and/or a fluid with higher refractive index than air, desirably a higher refractive index than water. Fluids excluding gases are particularly desirable. The point of this is to enable imaging of smaller features since the exposure radiation will have a shorter wavelength in the liquid. (The effect of the liquid may also be regarded as increasing the effective numerical aperture (NA) of the system and also increasing the depth of focus.) Other immersion liquids have been proposed, including water with solid particles (e.g. quartz) suspended therein, or a liquid with a nano-particle suspension (e.g. particles with a maximum dimension of up to 10 nm). The suspended particles may or may not have a similar or the same refractive index as the liquid in which they are suspended. Other liquids which may be suitable include a hydrocarbon, such as an aromatic, a fluorohydrocarbon, and/or an aqueous solution.

Submersing the substrate or substrate and substrate table in a bath of liquid (see, for example, U.S. Pat. No. 4,509,852) means that there is a large body of liquid that should be accelerated during a scanning exposure. This may require additional or more powerful motors and turbulence in the liquid may lead to undesirable and unpredictable effects.

Other arrangements which have been proposed include a confined immersion system and an all wet immersion system. In a confined immersion system a liquid supply system provides liquid on only a localized area of the substrate and in between the final element of the projection system and the substrate using a liquid confinement system (the substrate generally has a larger surface area than the final element of the projection system). One way which has been proposed to arrange for this is disclosed in PCT patent application publication no. WO 99/49504.

In an all wet immersion system, as disclosed in PCT patent application publication WO 2005/064405 the immersion liquid is unconfined. In such a system the whole top surface of the substrate is covered in liquid. This may be advantageous because then the whole top surface of the substrate is exposed to the substantially same conditions. This may have an advantage for temperature control and processing of the substrate. In WO 2005/064405, a liquid supply system provides liquid to the gap between the final element of the projection system and the substrate. Liquid is allowed to leak over the remainder of the substrate. A barrier at the edge of a substrate table prevents the liquid from escaping so that it can be removed from the top surface of the substrate table in a controlled way.

The immersion system may be a fluid handling system or apparatus. In an immersion system, immersion fluid is handled by a fluid handling system, structure or apparatus. In an embodiment the fluid handling system may supply immersion fluid and therefore be a fluid supply system. In an embodiment the fluid handling system may at least partly confine immersion fluid and thereby be a fluid confinement system. In an embodiment the fluid handling system may provide a barrier to immersion fluid and thereby be a barrier member, such as a fluid confinement structure. In an embodiment the fluid handling system may create or use a flow of gas, for example to help in controlling the flow and/or the position of the immersion fluid. The flow of gas may form a seal to confine the immersion fluid so the fluid handling structure may be referred to as a seal member; such a seal member may be a fluid confinement structure. The fluid handling system may be located between the projection

system and the substrate table. In an embodiment, immersion liquid is used as the immersion fluid. In that case the fluid handling system may be a liquid handling system. In reference to the aforementioned description, reference in this paragraph to a feature defined with respect to fluid may be understood to include a feature defined with respect to liquid.

In a fluid handling system or liquid confinement structure, liquid is confined to a space, for example within a confinement structure. The space may be defined by the body of the confinement structure, the underlying surface (e.g. a substrate table, a substrate supported on the substrate table, a shutter member and/or a measurement table) and, in the case of a localized area immersion system, a liquid meniscus between the fluid handling system or liquid confinement structure and the underlying structure i.e. in an immersion space. In the case of an all wet system, liquid is allowed to flow out of the immersion space onto the top surface of the substrate and/or substrate table.

In European patent application publication no. EP 1420300 and United States patent application publication no. US 2004-0136494, each hereby incorporated in their entirety by reference, the idea of a twin or dual stage immersion lithography apparatus is disclosed. Such an apparatus is provided with two tables for supporting a substrate. Leveling measurements are carried out with a table at a first position, without immersion liquid, and exposure is carried out with a table at a second position, where immersion liquid is present. Alternatively, the apparatus has only one table.

After exposure of a substrate in an immersion lithographic apparatus, the substrate table is moved away from its exposure position to a position in which the substrate may be removed and replaced by a different substrate. This is known as substrate swap. In a two stage lithographic apparatus, for example ASML's "Twinscan" lithographic apparatus, the substrate tables swap takes place under the projection system.

SUMMARY

In a lithographic apparatus, a substrate is supported on a substrate table by a substrate holder. The substrate holder may be located in a recess of the substrate table. The recess may be dimensioned so that when a substrate is supported by the substrate holder the top surface of the substrate is generally in the same plane as the surface of the substrate table surrounding the substrate. Around the substrate, there may be a gap between an edge of a substrate and an edge of the substrate table. Such a gap may be undesirable in an immersion system of a lithographic apparatus. As the gap moves under the immersion liquid in the space between the final element of the projection system and the underlying surface, the meniscus between the confinement structure and the underlying surface crosses the gap. Crossing the gap may increase the instability of the meniscus. The stability of the meniscus may decrease with increased relative speed, e.g. scanning or stepping speed, between the confinement structure and the substrate table. An increasingly unstable meniscus is a risk to increased defectivity. For example an unstable meniscus may enclose gas as a bubble in the immersion liquid, or may cause a droplet to escape from the immersion space. Such a bubble may be drawn into the space and result in imaging defects. A droplet may be a source of contaminants and a heat load as it evaporates and it may later collide with the meniscus causing a bubble to be drawn in to the space.

One or more problems of crossing the gap may be reduced by the provision of a two-phase extraction system. The two phase extraction system extracts fluid such as immersion liquid and gas (which may be present as a bubble in the liquid) from the gap. Sources of defectivity, such as releasing a bubble into the space or a droplet escaping from the space, may be reduced if not eliminated. However, the provision of such an extraction system may impart a heat load on the substrate table and the substrate. This may have a negative impact on the overlay accuracy of patterns formed on the substrate. The gap may implicitly limit the scan speed that may be used to achieve reliable imaging of a substrate.

It is therefore desirable to provide, for example, a system to increase the stability of the meniscus and reduce defectivity, for example the likelihood of creating a bubble or releasing a droplet.

In an aspect of an invention, there is provided a lithographic apparatus comprising:

- 20 a substrate table having an upper surface and a recess in the upper surface that is configured to receive and support a substrate;
- a fluid handling structure configured to contain immersion fluid in a space adjacent to the upper surface of the substrate table and/or a substrate located in the recess;
- 25 a cover comprising a planar main body that, in use, extends around a substrate from the upper surface to a peripheral section of an upper major face of the substrate in order to cover a gap between an edge of the recess and an edge of the substrate; and
- 30 an immersion fluid film disruptor, configured to disrupt the formation of a film of immersion fluid between an edge of the cover and immersion fluid contained by the fluid handling structure during movement of the substrate table relative to the fluid handling structure, the immersion fluid film disruptor comprising a plurality of discrete gas jets formed on a surface of the fluid handling structure opposite the upper surface of the substrate and/or substrate table.

40 In an aspect of an invention, there is provided a fluid handling structure for a lithographic apparatus that includes a substrate table having a substantially planar upper surface in which is formed a recess that is configured to receive and support a substrate and a cover comprising a substantially planar main body that, in use, extends around the substrate from the upper surface to a peripheral section of an upper major face of the substrate in order to cover a gap between an edge of the recess and an edge of the substrate, the fluid handling structure comprising a plurality of apertures configured to provide a corresponding plurality of discrete gas jets to disrupt the formation of a film of immersion fluid between an edge of the cover and immersion fluid contained by the fluid handling structure during movement of the substrate table relative to the fluid handling structure.

55 In an aspect of an invention, there is provided a device manufacturing method, comprising:

- 60 providing a substrate to a substrate table having an upper surface and a recess in the upper surface that is configured to receive and support the substrate;
- providing a cover comprising a planar main body such that it extends around the substrate from the upper surface to a peripheral section of an upper major face of the substrate in order to cover a gap between an edge of the recess and an edge of the substrate;
- 65 providing an immersion fluid to a space between a final element of a projection system and the substrate and/or a substrate table using a fluid handling structure; and

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providing a plurality of discrete gas jets from a surface of the fluid handling structure that is opposite the upper surface of the substrate and/or substrate table in order to disrupt the formation of a film of immersion fluid between an edge of the cover and immersion fluid contained by the fluid handling structure during movement of the substrate table relative to the fluid handling structure.

BRIEF DESCRIPTION OF THE DRAWINGS

Embodiments of the invention will now be described, by way of example only, with reference to the accompanying schematic drawings in which corresponding reference symbols indicate corresponding parts, and in which:

FIG. 1 depicts a lithographic apparatus according to an embodiment of the invention;

FIGS. 2 and 3 depict a fluid handling structure as a liquid supply system for use in a lithographic projection apparatus;

FIG. 4 depicts a further liquid supply system for use in a lithographic projection apparatus;

FIG. 5 depicts, in cross-section, a liquid confinement structure which may be used in an embodiment of the present invention as a liquid supply system;

FIG. 6 depicts, in plan view, a substrate receiving section according to an aspect of the invention;

FIGS. 7 and 8 depict, in plan view, a cover according to an aspect of the invention in open and closed positions, respectively;

FIGS. 9 and 10 depict, in plan view, a cover according to an aspect of the invention in closed and open positions, respectively;

FIGS. 11, 12 and 13 depict, in cross-section, an actuator system for a cover according to an aspect of the invention in, respectively, the closed position, an intermediate position and the open position;

FIGS. 14 and 15 depict, in cross-section, an arrangement of movement guides that may be used in an actuator system of an aspect of the invention;

FIGS. 16, 17 and 18 depict an actuator system for a cover according to an aspect of the invention in, respectively, a closed position, an intermediate position and an open position;

FIGS. 19 and 20 depict, in cross-section, a cover according to an aspect of the invention;

FIG. 21 depicts, in cross-section, an arrangement of a cover according to an aspect of the invention;

FIGS. 22 to 25 schematically depict possible configurations of the edge of a cover according to an aspect of the invention;

FIGS. 26 to 32 schematically depict, in cross section, arrangements of covers according to an aspect of the invention;

FIG. 33 depicts an arrangement of a cover in use;

FIG. 34 depicts an arrangement of a cover in a system including an immersion fluid film disruptor according to an aspect of the invention;

FIG. 35 depicts an arrangement of a cover in a system including an immersion fluid film disruptor according to an aspect of the invention;

FIG. 36 depicts an arrangement of a cover in a system including an immersion fluid film disruptor according to an aspect of the invention;

FIG. 37 depicts in greater detail a portion of an arrangement as depicted in FIG. 36;

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FIG. 38 depicts a relationship between the jet pitch of an arrangement as depicted in FIG. 36 and the resulting droplet diameter;

FIG. 39 depicts, in cross-section, an arrangement of an immersion fluid film disruptor as depicted in FIG. 36; and

FIG. 40 depicts a variation of the arrangement depicted in FIG. 39.

DETAILED DESCRIPTION

FIG. 1 schematically depicts a lithographic apparatus according to one embodiment of the invention. The apparatus comprises:

an illumination system (illuminator) IL configured to condition a radiation beam B (e.g. UV radiation or DUV radiation);

a support structure (e.g. a mask table) MT constructed to support a patterning device (e.g. a mask) MA and connected to a first positioner P^M configured to accurately position the patterning device MA in accordance with certain parameters;

a substrate table (e.g. a wafer table) WT constructed to hold a substrate (e.g. a resist-coated wafer) W and connected to a second positioner P^W configured to accurately position the substrate W in accordance with certain parameters; and

a projection system (e.g. a refractive projection lens system) PS configured to project a pattern imparted to the radiation beam B by patterning device MA onto a target portion C (e.g. comprising one or more dies) of the substrate W.

The illumination system IL may include various types of optical components, such as refractive, reflective, magnetic, electromagnetic, electrostatic or other types of optical components, or any combination thereof, for directing, shaping, or controlling radiation.

The support structure MT holds the patterning device MA. The support structure MT holds the patterning device MA in a manner that depends on the orientation of the patterning device MA, the design of the lithographic apparatus, and other conditions, such as for example whether or not the patterning device is held in a vacuum environment. The support structure MT can use mechanical, vacuum, electrostatic or other clamping techniques to hold the patterning device. The support structure MT may be a frame or a table, for example, which may be fixed or movable as desired. The support structure MT may ensure that the patterning device MA is at a desired position, for example with respect to the projection system PS. Any use of the terms "reticle" or "mask" herein may be considered synonymous with the more general term "patterning device."

The term "patterning device" used herein should be broadly interpreted as referring to any device that can be used to impart a radiation beam with a pattern in its cross-section such as to create a pattern in a target portion of the substrate. It should be noted that the pattern imparted to the radiation beam may not exactly correspond to the desired pattern in the target portion of the substrate, for example if the pattern includes phase-shifting features or so called assist features. Generally, the pattern imparted to the radiation beam will correspond to a particular functional layer in a device being created in the target portion, such as an integrated circuit.

The patterning device may be transmissive or reflective. Examples of patterning devices include masks, programmable mirror arrays, and programmable LCD panels. Masks are well known in lithography, and include mask types such

as binary, alternating phase-shift, and attenuated phase-shift, as well as various hybrid mask types. An example of a programmable mirror array employs a matrix arrangement of small mirrors, each of which can be individually tilted so as to reflect an incoming radiation beam in different directions. The tilted mirrors impart a pattern in a radiation beam which is reflected by the mirror matrix.

The term "projection system" used herein should be broadly interpreted as encompassing any type of projection system. The types of projection system may include: refractive, reflective, catadioptric, magnetic, electromagnetic and electrostatic optical systems, or any combination thereof. The selection or combination of the projection system is as appropriate for the exposure radiation being used, or for other factors such as the use of an immersion liquid or the use of a vacuum. Any use of the term "projection lens" herein may be considered as synonymous with the more general term "projection system".

As here depicted, the apparatus is of a transmissive type (e.g. employing a transmissive mask). Alternatively, the apparatus may be of a reflective type (e.g. employing a programmable mirror array of a type as referred to above, or employing a reflective mask).

The lithographic apparatus may be of a type having two (dual stage) or more substrate tables (and/or two or more patterning device tables). In such "multiple stage" machines the additional tables may be used in parallel, or preparatory steps may be carried out on one or more tables while one or more other tables are being used for exposure.

Referring to FIG. 1, the illuminator IL receives a radiation beam from a radiation source SO. The source SO and the lithographic apparatus may be separate entities, for example when the source is an excimer laser. In such cases, the source SO is not considered to form part of the lithographic apparatus and the radiation beam is passed from the source SO to the illuminator IL with the aid of a beam delivery system BD comprising, for example, suitable directing mirrors and/or a beam expander. In other cases the source SO may be an integral part of the lithographic apparatus, for example when the source is a mercury lamp. The source SO and the illuminator IL, together with the beam delivery system BD if required, may be referred to as a radiation system.

The illuminator IL may comprise an adjuster AD for adjusting the angular intensity distribution of the radiation beam. Generally, at least the outer and/or inner radial extent (commonly referred to as σ -outer and σ -inner, respectively) of the intensity distribution in a pupil plane of the illuminator IL can be adjusted. In addition, the illuminator IL may comprise various other components, such as an integrator IN and a condenser CO. The illuminator IL may be used to condition the radiation beam, to have a desired uniformity and intensity distribution in its cross-section. Similar to the source SO, the illuminator IL may or may not be considered to form part of the lithographic apparatus. For example, the illuminator IL may be an integral part of the lithographic apparatus or may be a separate entity from the lithographic apparatus. In the latter case, the lithographic apparatus may be configured to allow the illuminator IL to be mounted thereon. Optionally, the illuminator IL is detachable and may be separately provided (for example, by the lithographic apparatus manufacturer or another supplier).

The radiation beam B is incident on the patterning device (e.g., mask) MA, which is held on the support structure (e.g., mask table) MT, and is patterned by the patterning device MA. Having traversed the patterning device MA, the radiation beam B passes through the projection system PS. The

projection system PS focuses the beam B onto a target portion C of the substrate W. With the aid of the second positioner PW and position sensor IF (e.g. an interferometric device, linear encoder or capacitive sensor), the substrate table WT can be moved accurately, e.g. so as to position different target portions C in the path of the radiation beam B. Similarly, the first positioner PM and another position sensor (which is not explicitly depicted in FIG. 1) can be used to accurately position the patterning device MA with respect to the path of the radiation beam B, e.g. after mechanical retrieval from a mask library, or during a scan. In general, movement of the support structure MT may be realized with the aid of a long-stroke module (coarse positioning) and a short-stroke module (fine positioning), which form part of the first positioner PM. Similarly, movement of the substrate table WT may be realized using a long-stroke module and a short-stroke module, which form part of the second positioner PW. In the case of a stepper (as opposed to a scanner) the support structure MT may be connected to a short-stroke actuator only, or may be fixed. Patterning device MA and substrate W may be aligned using patterning device alignment marks M1, M2 and substrate alignment marks P1, P2. Although the substrate alignment marks as illustrated occupy dedicated target portions, they may be located in spaces between target portions (these are known as scribe-lane alignment marks). Similarly, in situations in which more than one die is provided on the patterning device MA, the patterning device alignment marks may be located between the dies.

The depicted apparatus could be used in at least one of the following modes:

In step mode, the support structure MT and the substrate table WT are kept essentially stationary, while an entire pattern imparted to the radiation beam B is projected onto a target portion C at one time (i.e. a single static exposure). The substrate table WT is then shifted in the X and/or Y direction so that a different target portion C can be exposed. In step mode, the maximum size of the exposure field limits the size of the target portion C imaged in a single static exposure.

In scan mode, the support structure MT and the substrate table WT are scanned synchronously while a pattern imparted to the radiation beam B is projected onto a target portion C (i.e. a single dynamic exposure). The velocity and direction of the substrate table WT relative to the support structure MT may be determined by the (de-)magnification and image reversal characteristics of the projection system PS. In scan mode, the maximum size of the exposure field limits the width (in the non-scanning direction) of the target portion C in a single dynamic exposure, whereas the length of the scanning motion determines the height (in the scanning direction) of the target portion C.

In another mode, the support structure MT is kept essentially stationary holding a programmable patterning device, and the substrate table WT is moved or scanned while a pattern imparted to the radiation beam B is projected onto a target portion C. In this mode, generally a pulsed radiation source is employed and the programmable patterning device is updated as desired after each movement of the substrate table WT or in between successive radiation pulses during a scan. This mode of operation can be readily applied to maskless lithography that utilizes programmable patterning device, such as a programmable mirror array of a type as referred to above.

Combinations and/or variations on the above described modes of use or entirely different modes of use may also be employed.

An arrangement to provide liquid between a final element of the projection system PS and the substrate is the so called localized immersion system IH. In this system a liquid handling system is used in which liquid is only provided to a localized area of the substrate. The space filled by liquid is smaller in plan than the top surface of the substrate and the area filled with liquid remains substantially stationary relative to the projection system PS while the substrate W moves underneath that area. Four different types of localized liquid supply systems are illustrated in FIGS. 2-5.

As illustrated in FIGS. 2 and 3, liquid is supplied by at least one inlet onto the substrate, preferably along the direction of movement of the substrate relative to the final element. Liquid is removed by at least one outlet after having passed under the projection system. That is, as the substrate is scanned beneath the element in a $-X$ direction, liquid is supplied at the $+X$ side of the element and taken up at the $-X$ side. FIG. 2 shows the arrangement schematically in which liquid is supplied via inlet and is taken up on the other side of the element by outlet which is connected to a low pressure source. In the illustration of FIG. 2 the liquid is supplied along the direction of movement of the substrate relative to the final element, though this does not need to be the case. Various orientations and numbers of in- and out-lets positioned around the final element are possible; one example is illustrated in FIG. 3 in which four sets of an inlet with an outlet on either side are provided in a regular pattern around the final element. Arrows in liquid supply and liquid recovery devices indicate the direction of liquid flow.

A further immersion lithography solution with a localized liquid supply system is shown in FIG. 4. Liquid is supplied by two groove inlets on either side of the projection system PS and is removed by a plurality of discrete outlets arranged radially outwardly of the inlets. The inlets can be arranged in a plate with a hole in its centre and through which the projection beam is projected. Liquid is supplied by one groove inlet on one side of the projection system PS and removed by a plurality of discrete outlets on the other side of the projection system PS, causing a flow of a thin film of liquid between the projection system PS and the substrate W. The choice of which combination of inlet and outlets to use can depend on the direction of movement of the substrate W (the other combination of inlet and outlets being inactive). In the cross-sectional view of FIG. 4, arrows illustrate the direction of liquid flow in inlets and out of outlets.

Another arrangement which has been proposed is to provide the liquid supply system with a liquid confinement member which extends along at least a part of a boundary of the space between the final element of the projection system and the substrate table. Such an arrangement is illustrated in FIG. 5. The liquid confinement member is substantially stationary relative to the projection system in the XY plane though there may be some relative movement in the Z direction (in the direction of the optical axis). A seal is formed between the liquid confinement and the surface of the substrate. In an embodiment, a seal is formed between the liquid confinement structure and the surface of the substrate and may be a contactless seal such as a gas seal. Such a system is disclosed in United States patent application publication no. US 2004-0207824, hereby incorporated in its entirety by reference.

FIG. 5 schematically depicts a localized liquid supply system with a liquid confinement structure 12. The liquid confinement structure 12 extends along at least a part of a boundary of the space 11 between the final element of the projection system PS and the substrate table WT or substrate W. (Please note that reference in the following text to surface

of the substrate W also refers in addition or in the alternative to a surface of the substrate table WT, unless expressly stated otherwise.) The liquid confinement structure 12 is substantially stationary relative to the projection system PS in the XY plane though there may be some relative movement in the Z direction (in the direction of the optical axis). In an embodiment, a seal is formed between the liquid confinement structure 12 and the surface of the substrate W and may be a contactless seal such as fluid seal, desirably a gas seal.

The liquid confinement structure 12 at least partly contains liquid in the immersion space 11 between a final element of the projection system PS and the substrate W. A contactless seal 16 to the substrate W may be formed around the image field of the projection system PS so that liquid is confined within the space 11 between the substrate W surface and the final element of the projection system PS. The immersion space 11 is at least partly formed by the liquid confinement structure 12 positioned below and surrounding the final element of the projection system PS. Liquid is brought into the space 11 below the projection system PS and within the liquid confinement structure 12 by liquid inlet 13. The liquid may be removed by liquid outlet 13. The liquid confinement structure 12 may extend a little above the final element of the projection system PS. The liquid level rises above the final element so that a buffer of liquid is provided. In an embodiment, the liquid confinement structure 12 has an inner periphery that at the upper end closely conforms to the shape of the projection system PS or the final element thereof and may, e.g., be round. At the bottom, the inner periphery closely conforms to the shape of the image field, e.g., rectangular, though this need not be the case.

In an embodiment, the liquid is contained in the immersion space 11 by a gas seal 16 which, during use, is formed between the bottom of the liquid confinement structure 12 and the surface of the substrate W. Other types of seal are possible, as is no seal (for example in an all wet embodiment) or a seal achieved by capillary forces between the undersurface of the liquid confinement structure 12 and a facing surface, such as the surface of a substrate W, a substrate table WT or a combination of both.

The gas seal 16 is formed by gas, e.g. air or synthetic air but, in an embodiment, N_2 or another inert gas. The gas in the gas seal 16 is provided under pressure via inlet 15 to the gap between liquid confinement structure 12 and substrate W. The gas is extracted via outlet 14. The overpressure on the gas inlet 15, vacuum level on the outlet 14 and geometry of the gap are arranged so that there is a high-velocity gas flow inwardly that confines the liquid. The force of the gas on the liquid between the liquid confinement structure 12 and the substrate W contains the liquid in an immersion space 11. The inlets/outlets may be annular grooves which surround the space 11. The annular grooves may be continuous or discontinuous. The flow of gas is effective to contain the liquid in the space 11. Such a system is disclosed in United States patent application publication no. US 2004-0207824.

Other arrangements are possible and, as will be clear from the description below, an embodiment of the present invention may use any type of localized immersion system.

In a localized immersion system a seal is formed between a part of the liquid confinement structure and an underlying surface, such as a surface of a substrate W and/or substrate table WT. The seal may be defined by a meniscus of liquid between the liquid confinement structure and the underlying surface. Relative movement between the underlying surface and the liquid confinement structure may lead to breakdown

of the seal, for example the meniscus, above a critical speed. Above the critical speed, the seal may break down allowing liquid, e.g. in the form of a droplet, to escape from the liquid confinement structure, or gas, i.e. in the form of a bubble, to be enclosed in the immersion liquid within the immersion space.

A droplet may be a source of defectivity. The droplet may apply a thermal load on the surface which it is located as it evaporates. The droplet may be a source of contamination, in leaving a drying stain after it has evaporated. If the droplet lies in the path on the underlying surface which moves under the projection system, the droplet may contact the meniscus. The resulting collision between the meniscus and the droplet may cause a bubble to form in the liquid. A bubble may be a source of defectivity. A bubble in the immersion liquid may be drawn in to the space between the projection system and the substrate where it may interfere with an imaging projection beam.

Critical speed may be determined by the properties of the underlying surface. The critical speed of a gap relative to the confinement structure may be less than the critical speed for the surface of a relatively planar surface such as a substrate. On increasing the scan velocity above the lowest critical speed for a part of the undersurface, the scan velocity will exceed the critical speed for more of the underlying surface. The problem may be more significant at high scan velocities. However, an increased scan velocity is desirable because throughput increases.

FIG. 6 depicts, in plan view, a substrate table WT that may be used to support a substrate W. The substrate table may have a substantially planar upper surface 21. In the upper surface 21 is a recess 22 that is configured to receive and support a substrate W.

In the recess may be a substrate support which may be a surface of the recess. The surface of the recess 22 may include a plurality of protrusions on which a lower surface of the substrate is supported. The surface of the recess may include a barrier. In the surface of the recess may be formed a plurality of openings. The barrier surrounds the protrusions to define a space beneath the lower surface of the substrate W. The openings are connected to an under-pressure source. When a substrate is located above the openings a space is formed beneath the substrate W. The space may be evacuated by operation of the underpressure. This arrangement may be used in order to secure the substrate W to the substrate table WT.

In an arrangement, the recess may be configured such that the major faces of the substrate, namely the upper face and the lower face, are substantially parallel to the upper surface 21 of the substrate table. In an arrangement, the upper face of the substrate W may be arranged to be substantially coplanar with upper surface 21 of the substrate table.

It should be appreciated that in the present application, terms such as upper and lower may be used in order to define the relative positions of components within the systems described. However, these terms are used for convenience in order to describe the relative positions of the components when the apparatus is used at a particular orientation. They are not intended to specify the orientation in which the apparatus may be used.

As depicted in FIG. 6, a gap 23 may be present between an edge of the substrate W and an edge of the recess 22. According to an aspect of the invention, a cover 25 is provided that extends around the substrate W. The cover 25 extends from a peripheral section of the upper surface of the substrate W (which in an embodiment may be an edge of the substrate) to the upper surface 21 of the substrate table WT.

The cover 25 may entirely cover the gap 23 between the edge of the substrate W and the edge of the recess 22. In addition, an open central section 26 of the cover 25 may be defined by an inner edge of the cover. The open central section 26 may be arranged such that, in use, the cover 25 does not cover portions of the substrate W on which it is intended to project a patterned beam of radiation. The inner edge of the cover may cover portions of the substrate which neighbor the surface of the substrate which is imaged by the patterned projection beam. The cover is located away from those portions of the substrate which are exposed by the patterned projection beam.

As shown in FIG. 6, when the cover 25 is placed on the substrate W, the size of the open central section 26 may be slightly smaller than the size of the upper surface of the substrate W. As shown in FIG. 6, if the substrate W is circular in shape, the cover 25 may be generally annular in shape when viewed in plan view.

The cover 25 may be in the form of a thin cover plate. The cover plate may, for example, be formed from stainless steel. Other material may be used. The cover plate may be coated with Lipocer coating of the type offered by Plasma Electronic GmbH. Lipocer is a coating which may be lyophobic (e.g. hydrophobic) and is relatively resistant to damage from exposure to radiation and immersion liquid (which may be highly corrosive). More information on Lipocer may be found in U.S. Patent Application Publication No. US 2009-0206304, which is hereby incorporated by reference in its entirety.

As schematically depicted in FIG. 21, a lyophobic coating 141, such as a layer of Lipocer, may be applied to the lower surface 25a of the cover 25, namely the surface, that in use, may extend from a peripheral section of the upper surface of the substrate W to the upper surface 21 of the substrate table WT. The provision of such a coating 141 on the lower surface 25a may minimize or reduce the leakage of immersion liquid below the cover 25. For example, the coating 141 may reduce the leakage of immersion liquid between the cover 25 and the upper surface of the substrate W. Minimizing or reducing such immersion liquid leakage may in turn reduce the likelihood of immersion liquid being passed to the underside of the substrate W. This may reduce defects that may be introduced as a result of the so-called back side contamination. Minimizing or reducing immersion liquid leakage may reduce a thermal load on the substrate W.

The coating 141 on the lower surface 25a of the cover 25 may be selected to be an anti-sticking layer. In other words, the coating 141 may be selected to prevent, minimize or reduce adhesion of the cover 25 to the upper surface of the substrate W and/or the upper surface 21 of the substrate table WT. This may prevent or reduce damage to the cover 25, the substrate W and/or the substrate table WT when the cover 25 is removed from the substrate W and the substrate table WT.

The use of a coating 141 on the lower surface 25a of the cover 25 that is lyophobic and/or anti-sticking may prevent or reduce the accumulation of contamination particles on the lower surface of the cover 25. Such contaminant particles could result in damage to any of the cover 25, the substrate W and/or the substrate table WT or provide a source of subsequent defects on the substrate W. Alternatively or additionally, such contaminant particles may prevent a sufficient seal being formed between the cover 25 and the upper surface of the substrate W and/or the upper surface 21 of the substrate table WT, resulting in leakage of the immersion liquid, which may be undesirable. Accordingly, it may be desirable to prevent the accumulation of such contaminant particles.

The lower surface 25a of the cover 25 and/or the lower surface 141a of a coating 141 applied to the lower surface 25a of the cover 25 may be configured to have low surface roughness. For example, for a spray coating, the surface roughness R_A may be less than 1 μm . For a deposited coating the surface roughness R_A may be less than 200 nm. In general, reducing the surface roughness of the lower surface 25a of the cover and/or the lower surface 141a of a coating 141 applied to the lower surface 25a of the cover 25 may reduce stress concentrations on the surface of the substrate W. The surface roughness R_A of parts of the cover 25 in contact with the substrate in use may desirably be less than 200 nm, desirably less than 50 nm, or desirably less than 10 nm.

Ensuring that the surface roughness of the lower surface 25a of the cover 25 and/or the lower surface 141a of a coating 141 applied to the lower surface 25a of the cover 25 is low may also assist in reducing or minimizing leakage of immersion liquid below the cover 25. The cover 25 may be arranged such that the flatness of the lower surface 25a of the cover 25 and/or the lower surface 141a of a coating 141 applied to the lower surface 25a of the cover 25 is maximized. This may provide optimized contact between the cover 25 and the substrate W and/or the substrate table WT, reducing or minimizing immersion liquid leakage.

As schematically depicted in FIG. 21, a coating 142 may alternatively or additionally be provided on the upper surface 25b of the cover 25. The upper surface 25b of the cover 25 or the upper surface 142b of a coating 142 on the upper surface 25b of the cover may be selected for smoothness. This may reduce the likelihood of the meniscus being pinned. For example, the upper surface 25b of the cover 25 or the upper surface 142b of a coating 142 on the upper surface 25b of the cover may be smooth such that the peak to valley distance of the surface is less than 10 μm , desirably less than 5 μm .

The coating 142 on the upper surface 25b of the cover 25 may be selected to be resistant to damage from exposure to radiation and immersion liquid. This may help ensure that the working life of the cover is sufficiently long to prevent unnecessary costs associated with replacing the cover 25, including downtime for the lithographic apparatus. The coating 142 on the upper surface 25b of the cover 25 may be selected to be lyophobic, as discussed above. Such a coating may provide a higher receding contact angle for the immersion liquid. This in turn may permit a higher scan speed. lobe used without, for example, the loss of immersion liquid from the meniscus, as discussed above. As noted above, the coating 142 on the upper surface 25b of the cover 25 may be formed from Lipocer.

It should be appreciated that the coatings 141, 142 on the lower and upper surface 25a, 25b of the cover 25 may be formed from the single layer of material. Alternatively, one or both of the coatings 141, 142 may be formed from a plurality of layers. For example, the layers may be formed from different materials, providing different benefits to the coating 141, 142. It should also be appreciated that the coatings 141, 142 on the lower and upper surfaces 25a, 25b of the cover 25 may be the same or different from each other.

The cover plate may, for example, be 25 μm thick. It may be etched to be locally reduced in thickness, for example at one or more of the edges. In a locally reduced area it may be 10 μm thick. The thickness of part of the cover may be reduced by other processes such as laser ablation, milling and polishing.

As depicted in FIG. 21, the edges 25c, 25d of the cover 25, namely the edges separating the lower and upper sur-

faces 25a, 25b of the cover 25 may be substantially perpendicular to the lower and upper surfaces 25a, 25b of the cover 25. Such an arrangement may be relatively simple to manufacture.

However, in an arrangement as depicted in FIG. 21, the edges 25c, 25d of the cover 25 may form a step on the surface of the substrate W and the upper surface 21 of the substrate table WT. Such a step may be undesirable. In particular, as discussed above, when the substrate W and substrate table WT move relative to the liquid confinement structure, care must be taken to ensure that the seal formed by a meniscus of liquid between the liquid confinement structure and the substrate W and/or substrate table WT does not break down. The introduction of a step on the surface may reduce the critical speed between the liquid confinement structure and the substrate W and/or substrate table WT up to which the liquid confinement structure and/or the substrate W/substrate table WT may move without the seal, for example the meniscus, breaking down.

One or more of the edges 25c, 25d of the cover 25 may be configured to provide a reduced step. For example, as discussed above, the thickness of the cover may be locally reduced at one or more of the edges. For example, one or more of the edges 25c, 25d of the cover may be configured to have a profile as schematically depicted in any one of FIGS. 22 to 25.

As depicted in FIG. 22, an edge of the cover 25 may be configured to have a section 143 in which the cover 25 tapers to a point. Accordingly, such a cover may have no step. However, the extreme edge of the cover 25 may be susceptible to damage.

In an alternative arrangement, as depicted in FIG. 23, the cover 25 may have an edge section 145 that includes a step 146 that is smaller than the thickness of the cover 25 and a tapered section between the step 146 and the main body of the cover 25 that has the full thickness. For example, the main body of the cover 25 may be 25 μm thick and the step 146 may be 10 μm thick. Such an arrangement has a smaller step than a cover that has a perpendicular edge 25c, 25d but may be less susceptible to edge damage than an arrangement as depicted in FIG. 22.

As depicted in FIGS. 22 and 23, the tapered section 143, 145 of the edge of a cover 25 may be configured to linearly increase in thickness relative to the distance from the edge. However, this is not essential. As depicted in FIGS. 24 and 25, which correspond to FIGS. 22 and 23, respectively, the tapered sections 147, 148 may be curved instead. This may avoid the provision of sharp corners, for example between the tapered section and the remainder of the cover 25 or between the tapered section and a reduced step at the edge of the cover 25. Such sharp corners may be a source of instability in the seal, for example the meniscus, between the liquid confinement structure and the underlying surface. Accordingly, avoiding such sharp corners may reduce the likelihood of droplets being lost from the meniscus, reducing possible defectivity as discussed above.

As shown in FIGS. 22 to 25, the lower corner of the cover 25, namely the corner that in use may be in contact with the upper surface of the substrate W and/or the substrate table WT, may be a relatively sharp corner. This may provide a relatively good seal between the cover 25 and the substrate W and/or substrate table WT. However, it should be appreciated that the lower corner may be curved instead. This may reduce the likelihood of damage to the substrate W.

In general avoiding sharp corners on the cover may facilitate the provision of a coating on the cover 25, if desired.

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It should be appreciated that, although FIGS. 22 to 25 depict one edge of a cover 25 with a tapered section and/or a rounded, one or more the edges of the cover 25 may be tapered and/or have one or more rounded corners as discussed above. Furthermore, the edges of a cover 25 may have a different respective arrangements of a tapered section and/or rounded corners.

A further issue that may affect the selection of the arrangement of one or both of the edges 25c, 25d of the cover 25 is the behavior of the immersion liquid when the liquid confinement structure 12 crosses the cover 25. This behavior may also be affected by the configuration of the liquid confinement structure 12 and one or more materials used for the substrate table WT and the cover 25.

For example, when using a liquid confinement structure that does not include a gas knife and a lyophilic (e.g., hydrophilic) substrate table WT and cover 25, liquid film pulling may be present. Liquid film pulling may also occur in other arrangements. Liquid film pulling may lead to liquid loss on the substrate, which is undesirable. In particular, such lost droplets may subsequently collide with the meniscus during further relative movement between the liquid confinement structure 12 and the substrate table WT. These collisions may result in the formation of bubbles in the immersion liquid.

The liquid film pulling may be caused by the movement of the edge of the cover 25 under the meniscus (or vice versa). When a meniscus crosses over a 90° height step, the meniscus velocity would have to be infinite during the step. Such a step occurs at a perpendicular edge 25c, 25d of a cover 25 such as shown in FIG. 21. Infinite meniscus velocity is not actually possible so the meniscus is stretched, resulting in liquid film pulling as depicted in FIG. 33. Subsequently, the liquid film 201 will break up, resulting in liquid loss on the substrate W and/or substrate table WT.

The liquid film pulling may be reduced by use of a tapered edge, for example as depicted in FIG. 22. However, although the liquid film is depinned earlier than in the case of a perpendicular edge, a liquid film may still be pulled. Accordingly, although liquid loss on the substrate and/or substrate table may be reduced, it may remain above a desired level. This may be because it is not possible to form an infinitely sharp tip at the edge of the cover 25. Therefore, there may remain a small edge that is effectively perpendicular at the end of the tip of the edge of the cover 25.

In an embodiment, an immersion liquid film disruptor is provided to stimulate fast break up of the liquid film. This may reduce the liquid loss.

In an embodiment, the immersion liquid film disruptor includes one or more structures that may be applied onto the upper surface and/or edge of the cover 25. This structure causes film instability, resulting in film break up. Such a surface profile may be combined with a cover 25 having a perpendicular edge or any arrangement of tapered edge, as described above.

The structure applied to the upper surface and/or edge of the cover 25 may be in the form of any kind of plural local variations of the surface. For example, elongate features such as ridges and/or channels may be provided. The cross section of such ridges and/or channels may be any appropriate shape. Alternatively or additionally, relatively short features such as pimples and/or dimples may be provided. Such pimples and/or dimples may have any appropriate shape.

FIG. 34 depicts an embodiment, in which a plurality of ridges 202 are provided on the upper surface of the cover 25. As shown, such an arrangement promotes the break up of the

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liquid film 203. Such an arrangement may reduce the likelihood of the meniscus being pinned.

FIG. 35 depicts an embodiment, in which a plurality of channels 204 are provided on the edge of the cover 25. As shown, such an arrangement promotes the break up of the liquid film 204. Such an arrangement may reduce the likelihood of the meniscus being pinned.

In an embodiment, depicted in FIG. 36 and, in more detail, FIG. 37, the immersion liquid film disruptor includes a plurality of discrete gas jets 210 provided by the liquid confinement structure 12. The gas jets 210 are directed onto the liquid film as it starts to form, promoting fast break up of the film 212. Such an arrangement may reduce the likelihood of the meniscus being pinned.

The gas jets 210 may be provided, for example, by a row of apertures 213 formed in the surface of the liquid confinement structure 12 and connected to a gas supply. The apertures may be provided outward of a line of openings 211 that are formed in the surface of the liquid confinement structure and used to extract immersion liquid in order to contain the immersion liquid. In other words, the apertures 213 providing the gas jets 210 may be on the opposite side of a line of openings 211 to the space in which the immersion liquid is contained. For example, the row of apertures 213 may be provided in a line that is substantially parallel to the line of openings 211 used to extract immersion liquid.

Although as depicted in, for example, FIG. 37, an equal number of apertures 213 and openings 211 may be provided for a given section of a line of openings 211, this may not necessarily be the case. The factors determining the appropriate separation of the openings 211 will generally be different from the factors determining the appropriate separation between the apertures 213, resulting in a difference in the number of openings 211 and apertures 213.

In addition, although FIG. 36 depicts an arrangement in which the liquid confinement structure 12 is generally square in plan view, this need not be the case. Furthermore, although as depicted in FIG. 36, the line of openings 211 may either be parallel to, or perpendicular to, the scanning direction of the substrate table WT (and therefore the substrate W and cover 25) relative to the liquid confinement structure 12, this need not be the case. For example, each of the lines of openings 211 may be arranged to be at an angle of 45 degrees to the scanning direction, or any desirable angle. Furthermore, although as depicted in FIG. 36, the lines of openings 211 may be straight, it will be appreciated that this need not be the case. Accordingly, for example, the region of the liquid confinement structure 12 bounded by the openings 211 may be bounded by a plurality of concave lines of openings 211.

In an embodiment, the row of apertures 213 may be provided in a shape that matches the shape of the lines of openings 211. However, this need not be the case and it may be desirable for the line of openings 211 to define a different shape from the line of apertures 213. In particular, at corners of the space bounded by the line of openings 211, a different layout of apertures 213 may be provided than the layout of openings 211.

Although the arrangement depicted in FIGS. 36 and 37 depicts a system to extract the immersion liquid at the edge of the liquid confinement structure 12 as being a plurality of discrete openings 211, in an embodiment, a different arrangement of liquid extraction may be provided. For example, in place of a line of openings 211, a continuous opening may be provided. Furthermore, a continuous opening may be provided in which the surface of the opening in

contact with the immersion liquid is covered by a micro-sieve, such as a porous material.

An advantage of using a plurality of discrete gas jets **210**, rather than a gas knife for example, is that liquid droplets may not be collected between a line of gas jets **210** and a line of openings **211**. Collection of liquid droplets in such an area may be a problem during movement of the substrate table WT relative to the liquid confinement structure. For example, liquid droplets collected in such an area during movement may combine to form large droplets. Such large droplets may, for example, collide with the meniscus, for example when the movement of the substrate table WT relative to the liquid confinement structure **12** reverses direction. Such collisions of droplets with the meniscus may result in the formation of bubbles within the immersion liquid, resulting in image defects.

As explained above, the provision of the plurality of discrete gas jets **210** may break up the film **212** into a plurality of relatively small droplets. The droplets may be small enough not to create bubbles when in collision with the meniscus. It will be appreciated that the film of immersion liquid is drawn from the edge of the cover **25** as the cover **25** relatively moves away from the liquid confinement structure **12** and the meniscus formed between the liquid confinement structure **12** and the top of the substrate W, cover **25** and substrate table WT.

The liquid contained in the film has a volume proportional to the thickness of the film. This in turn may depend on various parameters, including the “fly” height of the liquid confinement structure **12** above the surface of the substrate W and/or substrate table WT and the relative speed of the substrate and/or substrate table WT relative to the liquid confinement structure **12**. The film thickness may depend on various settings of the liquid confinement structure **12** such as one or more flow rates within the liquid confinement structure **12**. In an example, the film thickness may be between approximately 10 μm and 30 μm .

The film **212** of liquid may then be broken up into rivulets **214** by the gas jets **210**. For example, a rivulet **214** may be formed between adjacent gas jets **210** corresponding to adjacent apertures **213**. As depicted in FIG. **37**, the rivulets **214** will subsequently break up to form individual droplets.

As will be appreciated, the width of the rivulets **214** will be related to the volume of the film **212** that corresponds to each rivulet **214**. In turn, this is dependent on the film thickness, as discussed above, and the pitch of the gas jets **210**, namely the separation between the center of adjacent apertures **213**.

The size of the resulting droplets **215** in turn is dependent on the width of the rivulets **214**. Accordingly, the size of the droplets may be minimized by minimizing the width of the rivulet **214** which, for a given film thickness, may in turn be minimized by minimizing the pitch of the gas jets **210**, namely the separation of the apertures **213**.

FIG. **38** depicts the results of a theoretical analysis of the relationship between the jet pitch and the droplet diameter for different film thicknesses, together with the results of two experiments. The vertical axis represents the droplet diameter in μm and the horizontal axis represents the jet pitch in μm . The two experimental results are depicted by the large squares, the results of the analysis for films with a thickness of 10 μm are depicted by the small diamond markers, the results of the analysis for films with a thickness of 20 μm are depicted by the small square markers and the results of the analysis for films with a thickness of 30 μm are depicted by the small triangular markers. This confirms that it is desirable to minimize the jet pitch.

However, one may not simply minimize the jet pitch to the smallest size that may be machined. This is because it is desirable to ensure that the gas jets **210** remain as discrete gas jets and may therefore break up the liquid film **212**.

As the gas jet pitch decreases, there is an increasing tendency for the gas jets **210** to merge and, effectively, form a gas knife. The minimum usable gas jet pitch, namely the gas jet pitch at which the gas jets **210** remain sufficiently discrete that they may break up the liquid film **212**, may depend upon the “fly” height of the liquid confinement structure **12**, the diameter of the apertures **213** and the velocity of the gas jets **210**. In particular, the ratio of the “fly” height to the diameter of the apertures may be a significant factor.

As the “fly” height increases relative to the diameter of the apertures **213**, the greater the tendency for the gas jets **210** to merge together for a given gas jet pitch. For an arrangement in which the “fly” height is 1.5 to 2 times the diameter of the apertures **213**, the gas jets may remain sufficiently separate to function to break up the liquid film **212** when the ratio of the gas jet pitch to the diameter of the apertures **213** is approximately 1.5.

For example, the centers of adjacent apertures may be in the range from approximately 100 μm to 1 mm, for example approximately 750 μm . The diameter of the apertures **213** may, for example, be in the range of from approximately 50 μm to 150 μm , for example 100 μm .

As noted above, the speed of gas flow in the gas jets **210** may affect the performance of the gas jets in breaking up the liquid film **212**. In addition to affecting the gas jet pitch that may be used without the gas jets **210** merging, the velocity of the gas flow in the gas jets may also directly affect the size of the resulting droplets.

In an embodiment, the gas speed may be in the range of from approximately Ma 0.3 to Ma 0.6, for example approximately Ma 0.5.

Although as discussed above, it may be desirable to arrange the gas jets **210** in order to prevent them from merging to form a gas knife, it may be desirable to provide a gas knife in addition. In an embodiment, a gas knife may be provided, for example along a line parallel to the line of apertures **213** and on the opposite side of line of apertures **213** from the line of openings **211**.

In an embodiment, the separation between a line of openings **211**, that are formed in the surface of the liquid confinement structure and used to extract immersion liquid, and a line of apertures **213** providing gas jets **210** may be, for example, approximately 0.5 mm to 3 mm, for example approximately 1.5 mm.

FIG. **39** schematically depicts in cross section a plurality of gas jets **210** provided by a row of apertures **213**. As shown, each aperture **213** may be connected by a gas conduit **220** to a gas supply **221** including a gas source. The gas source may, for example, provide a supply of clean air or nitrogen.

The gas supply may be controlled, for example, by a controller **222**. The controller **222**, by means of the gas supply **221**, may control the gas flow to each of the apertures **213**. The controller **222** may be used to turn on the gas jets **210** only when required. For example, during normal use of a lithographic apparatus, the gas jets **210** may be not provided but when the liquid confinement structure **12** crosses the cover **25**, when liquid pulling may occur, the gas jets **210** are provided. Alternatively or additionally, for example, the controller **222** may be able, by use of one or more appropriate control valves and/or control of the gas source, to control the gas velocity in the gas jets **210**.

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Furthermore, the controller **222** may be able, by use of one or more appropriate control valves and/or appropriate control of the gas source, to select one or more apertures **213** to be used to form gas jets **210**. Accordingly, for example, in use, gas jets **210** may be provided by one set of apertures **213** and not provided by a second set of apertures **213**. For example, when the liquid confinement structure **12** crosses the cover **25**, only the apertures **213** on one side of the liquid confinement structure **12** may be used to provide gas jets **210**.

FIG. **40** depicts a variation of the embodiment depicted in FIG. **39**. Only the differences are discussed. As shown, the embodiment depicted in FIG. **40** includes a plurality of openings **230**, each provided between an adjacent pair of apertures **213**. The openings **230** may be connected by a suitable gas conduit **231** to an underpressure source **232**. The underpressure source may be controlled by the controller **222**, as shown, or may be provided with a separate controller.

The underpressure source **232** may be controlled in order to provide extraction through the openings **230** when the adjacent apertures **213** are used to provide gas jets **210**. Provision of such an arrangement may enable the gas jet pitch to be reduced without increasing the likelihood of the gas jets **210** merging together.

In an embodiment, the upper surface **25b** of the cover **25** or the upper surface **142b** of a coating **142** on the upper surface **25b** of the cover **25** may be configured to be as flat as possible. This may further reduce any instabilities of the meniscus discussed above, reducing the likelihood of droplets being lost from the meniscus and subsequent defects as discussed above.

In an embodiment, the cover may be a part of the substrate table. An actuator system may be provided to move the cover between at least closed and open positions. In the closed position, the cover **25** may be in contact with the upper surface of a substrate **W** within the recess **22**. In the closed position, the cover **25** may be in contact with the upper surface **21** of the substrate table **WT**. In the closed position, the cover **25** may cover the gap **23** between the edge of the substrate **W** and the edge of the recess **22**.

The cover **25** may be configured so that, as the gap passes underneath the immersion space **11**, with respect to the immersion liquid in the space, the gap is closed. By closing the gap, the stability of the meniscus in crossing the gap may be improved. In an embodiment, the cover forms a seal with one or both of the upper surface of a substrate **W** within the recess **22** and the upper surface **21** of the substrate table **WT**. A cover **25** that provides a seal with both the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT** may prevent immersion liquid from passing into the gap **23**. The cover may reduce the inflow of immersion liquid into the gap **23**. The cover may help reduce, if not prevent, the flow of bubbles into the space **11** as a consequence of the gap passing underneath the space **11**.

In the open position, the cover **25** may be moved away from its location at the closed position relative to the surface of the recess **22**. When a substrate is supported by the surface of the recess **22**, the cover **25** may be set apart from the substrate **W**. The open position may be arranged such that, when the cover **25** is in the open position, the substrate **W** may be unloaded from the substrate table **WT**. If a substrate **W** is not present in the recess **22**, a substrate **W** may be loaded onto the substrate table **WT**.

In an embodiment, the actuator system may be configured such that, in moving the cover **25** from the closed position to the open position, it enlarges the open central section **26**

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of the cover **25**, as depicted in FIG. **8**. In such a process, the open central section **26** of the cover **25** may be enlarged sufficiently that the open central section **26** is larger than the upper surface of the substrate **W** in the open position. The open central section **26** of the cover **25** may be enlarged sufficiently for the substrate **W** to be able to pass through the central open section **26** of the cover **25**.

In an embodiment, a substrate **W** may be loaded onto, or unloaded from, a substrate table by moving the cover **25** to the open position and passing the substrate **W** through the central open portion **26** of the cover **25**. In the case of loading a substrate **W** to a substrate table **WT**, once the substrate **W** has passed through the open central section **26** of the cover **25**, the substrate **W** may be received in the recess **22** of the substrate table **WT**. Subsequently, the cover **25** may be moved by the actuator system to the closed position, in which it covers the gap **23** between the edge of the substrate **W** and the edge of the recess **22** in which the substrate **W** is supported.

The actuator system may be configured such that, in moving the cover **25** to the open position, a plurality of portions of the cover **25** are moved in different respective directions relative to each other. This arrangement may be used in order to enlarge the open central section **26** of the cover **25** in moving to the open position.

In an embodiment, the actuator system may be configured to elastically deform at least a part of the cover **25**. For example, the actuator system may elastically deform at least a part of the cover **25** when the actuator moves the plurality of portions of the cover **25** in respective different directions in order to enlarge the open central section **26**.

FIGS. **7** and **8** depict, in plan view, a cover **25** according to an embodiment of the invention in the closed and open positions, respectively. As shown, the cover **25** may be generally annular in shape in plan view. The inner periphery **31**, e.g. circumference, of the cover **25** may define the open central section **26** of the cover **25** when it is in the closed position. A break in the generally annular shape of the cover **25** may be provided between the inner periphery, e.g., circumference, **31** and the outer periphery, e.g., circumference, **32** of the cover **25**.

In an arrangement such as that depicted in FIGS. **7** and **8**, the cover **25** has a plurality of portions **35** each of which are moveable by the actuator system in respective different directions. In moving the plurality of portions **35** the open central section **26** of the cover **25** may be enlarged or reduced. The plurality of portions may be combined together to form a single integral cover. However, as depicted in FIG. **8**, the provision of the break **30** across the periphery, e.g., circumference, of the cover **25** may facilitate the elastic deformation of the cover **25** in order to enlarge the central open section **26**.

Although the arrangement of FIGS. **7** and **8** includes a break **30** from the inner periphery **31** to the outer periphery **32** of the cover **25**, this is not essential.

Additional breaks may be provided in order to facilitate the enlargement, e.g., by elastic deformation, of the cover **25** in order to enlarge the open central section **26** of the cover **25** according to this aspect of the invention.

The provision of any of the covers disclosed herein may have a variety of additional benefits for a substrate table within a lithographic apparatus in addition to the reduction of defects caused by bubbles and/or the reduction of bubbles, as described above.

The cleaning of the substrate table **WT** and the immersion system may be reduced. This, in turn, may reduce the down time of the lithographic apparatus.

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A cover may reduce the transfer of contaminants from the upper surface of the substrate W to the lower surface of the substrate W. This may reduce defects that may be introduced as a result of the so-called back side contamination.

The provision of a cover covering the gap between the edge of the substrate W and the edge of the recess 22 may enable the edge of the substrate W to traverse the projection system and immersion system at a higher speed than is otherwise possible. This may increase the throughput of the lithographic apparatus.

The provision of a cover may obviate the need for an extraction system in order to remove immersion liquid and bubbles from the gap between the edge of the substrate W and the edge of the recess 22. This may reduce the heat load applied to the substrate table WT. The thermal stability of the substrate table WT may improve. The overlay accuracy of patterns formed on the substrate W may consequently improve.

An extraction system for the gap between the edge of the substrate W and the edge of the recess 22 may be a two-phase extractor. This type of extractor may produce flow induced vibrations. Therefore, the provision of a cover, which may result in such an extractor being obsolete (not being required), may reduce the vibrations within the substrate table WT.

The provision of a cover may result in a simpler system overall than a system that uses an extractor for the gap between the edge of the substrate W and the edge of the recess 22, as disclosed above. The provision of a cover over the gap 23 may reduce the cost of goods of the apparatus as a whole.

It should be appreciated that the provision of a cover according to an aspect of the invention may eliminate the need for an extraction system at the gap between the edge of the substrate W and the edge of the recess 22, as discussed above. However, a cover according to an aspect of the present invention may be used in conjunction with an extraction system. The benefits discussed above may still apply because the requirements of the extraction system may be reduced.

FIGS. 9 and 10 depict, in plan view, an arrangement of a cover 25 according to an embodiment of the invention. The cover depicted in FIGS. 9 and 10 is similar to the cover depicted in FIGS. 7 and 8 and, for brevity, only the differences will be discussed in detail.

As shown, the cover 25 is formed from a plurality of discrete sections 40. In the closed position, the sections 40 are arranged to abut adjacent sections 40 of the cover 25 in order to form a single cover 25. For example, as shown in FIG. 9, for a circular substrate W, when each of the discrete sections 40 of the cover 25 abut each other in the closed position, the combination of the discrete sections 40 provides a cover 25 having a generally annular shape.

The actuator system is configured such that it can move portions of the cover 25 in different directions in order to move the cover from the closed position to the open position. In the case of a cover 25 such as that depicted in FIGS. 9 and 10, each such portion of the cover 25 is one of the discrete sections 40. The actuator system moves each of the discrete sections 40 of the cover 25 in a respective different direction.

When the cover 25 is in the open position, the discrete sections 40 of the cover 25 may be set apart from each other, providing the enlarged open central section 26 through which the substrate W may pass as described above.

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FIGS. 11, 12 and 13 depict, in cross-section, an actuator system that may be used in an aspect of the invention in, respectively, the closed position, an intermediate position and the open position.

As shown FIG. 11, in the closed position, each portion of the cover 25 is positioned on, and extends between, a peripheral portion 45 of the upper surface of the substrate W and the upper surface 21 of the substrate table WT. In moving the cover 25 from the closed position to the open position, the actuator system 50 may be configured such that each portion of the cover 25 is first moved in a direction substantially perpendicular to the upper surface of the substrate W and the upper surface 21 of the substrate table WT.

FIG. 12 depicts a portion of the cover 25 in an intermediate position between the closed and open positions after an initial movement, as described above.

In moving from the open position to the closed position, the cover 25 may be moved to the intermediate position shown in FIG. 12 such that the cover 25 may subsequently be moved to the closed position only by a movement in a direction substantially perpendicular to the upper surface of the substrate W and the upper surface 21 of the substrate table WT.

Such an arrangement may beneficially ensure that, when the cover 25 is in contact with the substrate W or close to the substrate W, the relative movement of the cover 25 to the substrate W is only in a direction that is substantially perpendicular to the upper surface of the substrate W. This may prevent or reduce the generation of contaminant particles at the edge of the substrate W. This may prevent or reduce the movement of pre-existing contaminant particles at the edge of the substrate W towards the upper surface of the substrate W on which a pattern is to be formed. On contacting the substrate by moving the cover in a direction substantially perpendicular to the surface of the substrate W, a force applied to the substrate W is applied in a direction substantially perpendicular to the substrate W. As the force is applied around the periphery of the substrate W, the force applied is substantially uniform. Distortions in the substrate W caused by the application of the force are thereby reduced, if not minimized. Forces in the plane of the substrate W by application of the cover 25 are reduced or minimized, limiting the movement of the substrate W in the recess. Position errors by applying the cover 25 to the edge of the substrate W may be reduced, if not prevented.

The actuator system 50 may be configured such that it can move each of the portions of the cover 25 between the intermediate position depicted in FIG. 12 and the open position depicted in FIG. 13 by moving each of the portions of the cover 25 in a direction that is substantially parallel to the upper surface of the substrate W and the upper surface 21 of the substrate table WT.

As shown in FIGS. 11, 12 and 13, the actuator system 50 may include an actuator stage 51 that is configured to provide movement of the cover 25 in a direction substantially perpendicular to the upper surface of the substrate W and the upper surface 21 of the substrate table WT, for example in a vertical direction. The actuator stage 51 may be referred to as a transverse actuator stage.

The actuator system 50 may include an actuator stage 52 configured to provide movement of the cover 25 in a direction substantially parallel to the upper surface of the substrate W and the upper surface 21 of the substrate table WT, for example in a horizontal direction. The actuator stage 52 may be referred to as a lateral actuator stage.

It will be appreciated that, although the use of pneumatic actuators as depicted may be beneficial, alternative actuators

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may be used for one or both of the actuator stages **51, 52**. For example, an electrostatic actuator and/or an electromagnetic actuator may be used.

The actuator stage **51** may be configured in order to ensure that substantially the only movement provided is in the direction substantially perpendicular to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT**. The actuator stage **51** may include one or more movement guides. The one or more movement guides are configured to permit relative movement of the components of the actuator stage **51** in the direction substantially perpendicular to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT**. However, the movement guide reduces or minimizes the movement of the component of the actuator stage **51** in a direction substantially parallel to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT**.

FIGS. **14** and **15** depict, in cross-section, an arrangement of movement guides that may be used in order to help ensure that the actuator stage **51** only provides movement in a particular direction. Such a direction may be a direction substantially perpendicular to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT**. FIG. **14** depicts a movement guide **60** when the cover **25** is in the closed position. FIG. **15** depicts the movement guide **60** when the cover **25** is in the open position.

As shown, the actuator stage **51** includes first and second components **61,62**. The first and second components **61,62** may be moved relative to one another in the direction substantially perpendicular to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT** by means of the actuator provided as described above. Elastic hinges **63** are provided between the first and second components **61,62** of the actuator stage **51**. The elastic hinges permit movement of the first and second components **61,62** in a direction substantially perpendicular to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT**. The elastic hinges are configured to restrict movement in a direction substantially perpendicular to this desired direction of movement.

It will be appreciated that an alternative or additional movement guide may be used. However, the use of one or more such elastic hinges as described above may be beneficial because this form of movement guide does not have, or desirably minimizes, frictional forces. Frictional forces may reduce the reproducibility of the force that is applied on the upper surface of the substrate **W** when the cover **25** is moved to the closed position.

FIGS. **16, 17** and **18** depict a further actuator system that may be used with an aspect of the present invention. FIG. **16** depicts the actuator system **70** when the cover **25** is in the closed position. FIG. **17** depicts the actuator system **70** in an intermediate position. FIG. **18** depicts the actuator system **70** when the cover **25** is in the open position.

The actuator system **70** depicted in FIGS. **16, 17** and **18** may provide a simpler actuation system than that depicted in FIGS. **11, 12** and **13**. Separate actuator stages are not required. Instead, each portion of the cover **25** is connected to a piston **71** that is mounted within a system of movement guides **72,73** within the substrate table **WT**.

A movement guide **72** may, in cooperation with the piston **71**, be used to move the cover **25** from the closed position in a direction substantially perpendicular to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT** to the intermediate position. A movement guide **73** may be arranged such that, in conjunction with the piston **71**, it moves the cover **25** in a direction substantially

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parallel to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT**. In order to move the cover **25** between the closed and open positions, the gas pressure on one or both sides of the piston **71** may be changed by connecting one or both of the movement guides **72,73** to an appropriate underpressure or over-pressure source **74,75**.

The cover **25** may be configured such that in the closed position it not only covers the gap **23** between the edge of the substrate **W** and the edge of the recess **22** in the substrate table but it covers a further gap **77**. For example, an additional gap may exist between the actuator system and a part of the substrate table further away from the substrate holder such as an additional component **78**. The additional component **78** may be a component of a sensor system used in order to monitor the position and/or displacement of the substrate table **WT** relative to the projection system.

FIGS. **19** and **20** depict, in cross-section, an embodiment of the invention in which a different arrangement of cover **125** is provided to cover the gap **23** between the edge of the substrate **W** and the edge of the recess **22** in the substrate table **WT** in which the substrate **W** is supported. In particular, a cover **125** of an embodiment of the invention may be configured to be moved away from the substrate table **WT** to permit loading/unloading a substrate **W** to/from the recess **22** in the substrate table **WT**. In such an arrangement it is not necessary to enlarge an open central section of the cover **125** in moving the cover **125** to the open position.

In common with the arrangements discussed above, the cover **125** is arranged in the form of a thin plate of material that surrounds the edge of the substrate **W**. The cover **125** extends from a peripheral area **45** of the upper surface of the substrate **W** to the upper surface **21** of the substrate receiving section. Openings **127** for gas outlets may be provided that are connected to an under-pressure source **128**. The pressure in a space on the lower side **125a** of the cover **125** may be lower than the gas pressure on the upper side **125b** of the cover **125**. The pressure difference may be used in order to secure the cover **125** and substantially prevent any movement of the cover **125** during use.

In order to prevent or reduce deformation of the cover **125**, the cover may include one or more supports **126** that extend from the lower surface **125a** of the cover **125** to the bottom of the recess **22** when the cover **125** is located on top of a substrate **W** in the recess **22**.

In order to move the cover **125** in order to permit loading and unloading of a substrate **W**, a cover handling system **130** such as a robot arm may be provided. The cover handling system **130** may be specifically configured such that the movement of the cover **125** when the cover **125** is in contact with the substrate **W** or close to the substrate **W** is only in a direction that is substantially perpendicular to the upper surface of the substrate **W** and the upper surface **21** of the substrate table **WT**.

As discussed above, in embodiments of the invention, for example those depicted in FIGS. **11** to **18**, all actuator system may be provided that moves the cover **25** from an open position, in which a substrate **W** may be loaded to the substrate table **WT** and/or a substrate **W** may be unloaded from a substrate **WT**, to a closed position, in which the cover **25** extends from the upper surface **21** of the substrate table **WT** to the periphery of the substrate **W**. In the closed position, the cover **25** may be in physical contact with the peripheral section of the substrate **W** and the upper surface **21** of the substrate table **WT**, in particular if the cover **25** is to form a seal. Such physical contact could result in damage of one or more of the cover **25**, the substrate **W** and/or the

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upper surface **21** of the substrate table WT. Accordingly, an appropriate control system for the actuator system may be provided.

In an embodiment of the invention, a controller is provided in order to control the actuator system that positions the cover **25**. In order to help ensure that the cover is accurately moved relative to the substrate W and/or substrate table WT, the controller may use data that represents the height of the upper surface of at least the peripheral section of the substrate W relative to the upper surface **21** of the substrate table WT (or vice versa). Such data may, for example, be previously acquired in a metrology station, which may be part of the lithographic apparatus or part of a lithography system including the lithographic apparatus.

Based on the data representing the height of the upper surface of the peripheral section of the substrate W relative to the upper surface **21** of the substrate table WT (or vice versa), the controller may determine the position to which the cover **25** should be moved in order to provide a desired contact between the cover **25** and the upper surface of the substrate W and the upper surface **21** of the substrate table WT.

An appropriate feedback mechanism may be provided for the controller to control the actuator system to move the cover **25** to the desired position determined by the controller.

The controller may be configured, for example, to help ensure that the position of the cover **25** in the closed position is sufficiently close to or in contact with the upper surface of the peripheral section of the substrate W to prevent, reduce or minimize leakage of the immersion liquid. Alternatively or additionally, the controller may be configured to help ensure that, when the cover **25** is in the closed position, the force exerted on the upper surface of the peripheral section of the substrate W by the lower surface of the cover **25** is within a given range. For example, it may be desirable to ensure that the force is less than a certain value in order to prevent or reduce the likelihood of damage to the substrate W. Alternatively or additionally, it may be desirable to ensure that the force exerted on the upper surface of the peripheral section of the substrate W by the lower surface of the cover **25** exceeds a certain value in order to ensure that sufficient contact is made in order to control the leakage of immersion liquid below the cover **25**.

In an embodiment of the invention, the data representing the height of the upper surface of the peripheral section of the substrate W relative to the upper surface **21** of the substrate table WT (or vice versa) may provide data for the relative height at a plurality of locations around the peripheral section of the substrate W. From such data, the controller may be able to determine the desired position of respective portions of the cover **25** at a plurality of locations around the edge of the substrate W.

In an embodiment of the invention, the actuator system may be correspondingly configured to be able to adjust the height of the cover **25** independently at a plurality of locations around the cover **25**. In such an arrangement, local variations of the height of the upper surface of the substrate W and/or substrate table WT may be taken into account in controlling the positioning of the cover **25** in the closed position. This may in turn assist in preventing or reducing immersion liquid leakage and/or damage to the substrate W, the substrate table WT and/or the cover **25**.

As identified above, when the cover **25** is moved to the closed position, it may exert a force on the upper surface of the peripheral section of the substrate W. It should be appreciated that this force may be exerted regardless of the arrangement of the control system for the actuator system

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used to move the cover **25**. The force exerted on the substrate W may be sufficient to cause a movement of the upper surface of the substrate W, for example due to deformation of the substrate and/or due to deformation of the support section of the substrate table WT that supports the substrate W. Such movement of the upper surface of the substrate W may be undesirable because it may result in errors in the pattern formed on the substrate W.

In an embodiment of the invention, the cover **25** may be provided with a region that is relatively flexible, namely has a lower stiffness than the remainder of the cover. Such a relatively flexible section may be configured such that, when the cover **25** is moved to the closed position, any forces exerted on the cover and/or any inaccuracies in the positioning of the cover relative to the substrate W and/or substrate table WT results in a deformation of the relatively flexible section of the cover rather than a deformation of the substrate W or the support section of the substrate table WT that supports the substrate.

FIGS. **26** to **30** depict schematically, in cross-section, arrangements of covers **25** of an embodiment of the present invention having relatively flexible sections. As shown in FIGS. **26** to **28**, a cover **25** may be formed from a single section of material and one or more relatively flexible sections may be provided in which the thickness of the cover is reduced. For example, as depicted in FIG. **26**, one or more of the edge sections **161,162** of the cover **25** may have smaller thickness than the thickness of the remainder **163** of the main body of the cover **25**. The sections **161,162** of reduced thickness will accordingly be less stiff than the remainder **163** of the main body of the cover **25**.

The sections **161,162** of reduced thickness of the cover **25** may extend around the cover **25**, for example along the entirety of the inside and/or outside edge of the cover **25**. It will also be appreciated that in some arrangements, only one edge of the cover **25** will have a section of reduced thickness in order to provide a relatively flexible section.

It will be appreciated that such arrangements may be combined with embodiments discussed above in which the edge of the cover **25** is tapered. In this case, it will be appreciated that the edges **161a, 162a** of the reduced thickness sections **161, 162** may be tapered. Similarly, the edges of the covers depicted in FIGS. **27** to **32**, described below may be tapered. However, for brevity, this is not discussed in detail for each embodiment discussed below.

As depicted in FIG. **27**, a relatively flexible section of the cover **25** may be provided by the formation of a groove **165** in the lower surface of the cover **25**. The groove **165** results in an associated portion **166** of the cover **25** that has a reduced thickness and therefore reduced stiffness. It will be appreciated that the groove **165** may extend around the cover **25**. Accordingly, in use, the groove **165** may be positioned above the gap between the edge of the substrate W and the edge of the recess in the substrate table WT, extending around the full periphery of the substrate.

Although FIG. **27** depicts an arrangement in which a single groove **165** is provided in the lower surface of the cover **25**, it will be appreciated that a plurality of grooves may be provided in order to increase the flexibility of a section of the cover **25**. However, in general, it is desirable to retain sufficient sections of the main body of the cover **25** with relatively high stiffness, namely sections of the cover having the full thickness, in order to help ensure that the cover **25** does not deform excessively in use.

As depicted in FIG. **28**, the arrangements depicted in FIGS. **26** and **27** may be combined. In other words, a cover **25** may have a section of reduced thickness **161,162** at one

or more of the edges of the cover 25 and may also be provided with one or more grooves 165 on the lower surface of the cover 25.

In corresponding further arrangements, as depicted in FIGS. 29 to 31 respectively, the main body of the cover 25 may be formed from a planar section of material 170 attached to at least one support section of material 171. The combination of the planar section of material 170 and the support section of material 171 provides sections of the main body of the cover 25 having full thickness and, accordingly, relatively high stiffness. Sections of the main body of the cover 25 that are formed from the planar material 170 that is not supported by support sections of material 171 provide sections of the cover 25 of reduced thickness 161,162 that have relatively low stiffness. Likewise, gaps between two support sections of material 171 provide grooves 165 that provide relatively flexible sections of the cover 25.

Although not depicted in FIGS. 20 to 31, it will be appreciated that the covers 25 of this aspect of the invention may include supports such as those discussed above, including supports to connect the cover 25 to an actuator system.

FIG. 32 depicts an embodiment of the present invention, in which the main body of the cover 25 is supported by one or more supports 172. As shown, the cover 25 has a reduced thickness section 161,162 at either edge of the cover 25, providing relatively flexible sections of the cover 25. In addition, grooves 165 are provided in the lower surface of the cover 25. The grooves 165 are positioned such that they each extend around the cover 25 in a position between a respective edge of the cover 25 and the position of the one or more supports 172. Accordingly, the grooves 165 provide additional relatively flexible sections of the cover 25. It will be appreciated that in variations of this arrangement, one or more of the relatively flexible sections of the cover 25 may be omitted.

Although specific reference may be made in this text to the use of lithographic apparatus in the manufacture of ICs, it should be understood that the lithographic apparatus described herein may have other applications in manufacturing components with microscale, or even nanoscale features, such as the manufacture of integrated optical systems, guidance and detection patterns for magnetic domain memories, flat-panel displays, liquid-crystal displays (LCDs), thin-film magnetic heads, etc. The skilled artisan will appreciate that, in the context of such alternative applications, any use of the terms "wafer" or "die" herein may be considered as synonymous with the more general terms "substrate" or "target portion", respectively. The substrate referred to herein may be processed, before or after exposure, in for example a track (a tool that typically applies a layer of resist to a substrate and develops the exposed resist), a metrology tool and/or an inspection tool. Where applicable, the disclosure herein may be applied to such and other substrate processing tools. Further, the substrate may be processed more than once, for example in order to create a multi-layer IC, so that the term substrate used herein may refer to a substrate that already contains multiple processed layers.

The terms "radiation" and "beam" used herein encompass all types of electromagnetic radiation, including ultraviolet (UV) radiation (e.g. having a wavelength of or about 365, 248, 193, 157 or 126 nm).

The term "lens", where the context allows, may refer to any one or combination of various types of optical components, including refractive and reflective optical components.

To operate one or more movements of a component of the present invention, such as an actuator, there may be one or

controllers. The controllers may have any suitable configuration for receiving, processing, and sending signals. For example, each controller may include one or more processors for executing the computer programs that include machine-readable instructions for the methods described above. The controllers may include data storage medium for storing such computer programs, and/or hardware to receive such medium.

While specific embodiments of the invention have been described above, it will be appreciated that the invention may be practiced otherwise than as explicitly described. For example, the embodiments of the invention may take the form of a computer program containing one or more sequences of machine-readable instructions describing a method as disclosed above, or a data storage medium (e.g. semiconductor memory, magnetic or optical disk) having such a computer program stored therein. Further, the machine readable instruction may be embodied in two or more computer programs. The two or more computer programs may be stored on one or more different memories and/or data storage media. The computer programs may be suitable for controlling a controller referred to herein.

One or more embodiments of the invention may be applied to any immersion lithography apparatus, in particular, but not exclusively, those types mentioned above, whether the immersion liquid is provided in the form of a bath, only on a localized surface area of the substrate, or is unconfined on the substrate and/or substrate table. In an unconfined arrangement, the immersion liquid may flow over the surface of the substrate and/or substrate table so that substantially the entire uncovered surface of the substrate table and/or substrate is wetted. In such an unconfined immersion system, the liquid supply system may not confine the immersion liquid or it may provide a proportion of immersion liquid confinement, but not substantially complete confinement of the immersion liquid.

A liquid supply system as contemplated herein should be broadly construed. In certain embodiments, it may be a mechanism or combination of structures that provides a liquid to a space between the projection system and the substrate and/or substrate table. It may comprise a combination of one or more structures, one or more liquid inlets, one or more gas inlets, one or more gas outlets, and/or one or more liquid outlets that provide liquid to the space. In an embodiment, a surface of the space may be a portion of the substrate and/or substrate table, or a surface of the space may completely cover a surface of the substrate and/or substrate table, or the space may envelop the substrate and/or substrate table. The liquid supply system may optionally further include one or more elements to control the position, quantity, quality, shape, flow rate or any other features of the liquid.

Moreover, although this invention has been disclosed in the context of certain embodiments and examples, it will be understood by those skilled in the art that the present invention extends beyond the specifically disclosed embodiments to other alternative embodiments and/or uses of the invention and obvious modifications and equivalents thereof. In addition, while a number of variations of the invention have been shown and described in detail, other modifications, which are within the scope of this invention, will be readily apparent to those of skill in the art based upon this disclosure. For example, it is contemplated that various combination or sub-combinations of the specific features and aspects of the embodiments may be made and still fall within the scope of the invention. Accordingly, it should be understood that various features and aspects of the disclosed

embodiments can be combined with or substituted for one another in order to form varying modes of the disclosed invention. Thus, it is intended that the scope of the present invention herein disclosed should not be limited by the particular disclosed embodiments described above, but should be determined only by a fair reading of the claims that follow.

The descriptions above are intended to be illustrative, not limiting. Thus, it will be apparent to one skilled in the art that modifications may be made to the invention as described without departing from the scope of the claims set out below.

The invention claimed is:

[1. A lithographic apparatus comprising:

a substrate table having an upper surface and a recess in the upper surface that is configured to receive and support a substrate;

a fluid handling structure configured to contain immersion fluid in a space adjacent to the upper surface of the substrate table and/or a substrate located in the recess;

a cover comprising a planar main body that, in use, extends around a substrate from the upper surface to a peripheral section of an upper major face of the substrate in order to cover a gap between an edge of the recess and an edge of the substrate;

an immersion fluid film disruptor, configured to disrupt the formation of a film of immersion fluid between an edge of the cover and immersion fluid contained by the fluid handling structure during movement of the substrate table relative to the fluid handling structure, the immersion fluid film disruptor comprising a structure in or on a surface of the fluid handling structure opposite the upper major surface of the substrate and/or the upper surface of the substrate table, to form a plurality of discrete gas jets; and

a controller, configured to control supply of gas to the structure such that the jets of gas are provided when at least part of the structure is in the region of the cover and the jets of gas are not provided when the at least part of the structure is not in the region of the cover.]

[2. The lithographic apparatus according to claim 1, wherein the structure comprises a plurality of apertures, formed in the surface of the fluid handling structure, to provide the gas jets.]

[3. The lithographic apparatus according to claim 2, wherein the apertures are each configured to provide a jet of gas onto the film of immersion liquid as it forms.]

[4. The lithographic apparatus according to claim 2, wherein the surface of the fluid handling structure comprises a line of openings, surrounding the space in which immersion fluid is contained, configured to extract immersion fluid in order to contain the immersion fluid in the space; and the plurality of gas jets are provided outwardly of the line of openings.]

[5. The lithographic apparatus according to claim 4, wherein the plurality of apertures providing the gas jets are arranged along a second line, parallel to the line of openings.]

[6. The lithographic apparatus according to claim 2, wherein the controller is configured such that it can control the supply of gas to a first group of one or more apertures independently from a second group of one or more apertures.]

[7. The lithographic apparatus according to claim 2, wherein the gas is supplied to the apertures such that the maximum velocity of the gas is in the range of from approximately Ma 0.3 to Ma 0.6.]

[8. The lithographic apparatus according to claim 2, wherein the separation between the center of one aperture and the center of an adjacent aperture is in the range of from approximately 100 μm to 1 mm.]

[9. The lithographic apparatus according to claim 2, wherein the width of the apertures is in the range of from approximately 50 μm to 150 μm .]

[10. The lithographic apparatus according to claim 2, wherein the fluid handling structure comprises a plurality of openings, each provided between two adjacent apertures, wherein the openings are connected to an underpressure source.]

[11. A fluid handling structure for a lithographic apparatus that includes a substrate table having a substantially planar upper surface in which is formed a recess that is configured to receive and support a substrate and a cover comprising a substantially planar main body that, in use, extends around the substrate from the upper surface to a peripheral section of an upper major face of the substrate in order to cover a gap between an edge of the recess and an edge of the substrate, the fluid handling structure comprising a plurality of apertures configured to provide a corresponding plurality of discrete gas jets to disrupt the formation of a film of immersion fluid between an edge of the cover and immersion fluid contained by the fluid handling structure during movement of the substrate table relative to the fluid handling structure, and a controller configured to control supply of gas to the apertures such that the jets of gas are provided when the apertures are in the region of the cover and the jets of gas are not provided when the apertures are not in the region of the cover.]

[12. The fluid handling structure according to claim 11, wherein the plurality of gas jets are provided by a corresponding plurality of apertures formed in a surface of the fluid handling structure opposite the upper major surface of the substrate and/or the upper surface of the substrate table.]

[13. The fluid handling structure according to claim 12, wherein the surface of the fluid handling structure comprises a line of openings, surrounding the space in which immersion fluid is contained, configured to extract immersion fluid in order to contain the immersion fluid in the space; and the plurality of gas jets are provided outwardly of the line of openings.]

[14. The fluid handling structure according to claim 11, wherein the gas is supplied to the apertures such that the maximum velocity of the gas is in the range of from approximately Ma 0.3 to Ma 0.6.]

[15. The fluid handling structure according to claim 11, wherein the separation between the center of one aperture and the center of an adjacent aperture is in the range of from approximately 100 μm to 1 mm.]

[16. The fluid handling structure according to claim 11, wherein the width of the apertures is in the range of from approximately 50 μm to 150 μm .]

[17. The fluid handling structure according to claim 11, wherein the fluid handling structure comprises a plurality of openings, each provided between two adjacent apertures, wherein the openings are connected to an underpressure source.]

[18. A device manufacturing method, comprising:
providing a substrate to a substrate table having an upper surface and a recess in the upper surface that is configured to receive and support the substrate;
providing a cover comprising a planar main body such that it extends around the substrate from the upper surface to a peripheral section of an upper major face

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of the substrate in order to cover a gap between an edge of the recess and an edge of the substrate;
 providing an immersion fluid to a space between a final element of a projection system and the substrate and/or a substrate table using a fluid handling structure;
 providing a plurality of discrete gas jets from a structure in or on a surface of the fluid handling structure that is opposite the upper major surface of the substrate and/or the upper surface of the substrate table in order to disrupt the formation of a film of immersion fluid between an edge of the cover and immersion fluid contained by the fluid handling structure during movement of the substrate table relative to the fluid handling structure; and
 controlling supply of gas to the gas jets such that the jets of gas are provided when at least part of the structure is in the region of the cover and the jets of gas are not provided when the at least part of the structure is not in the region of the cover.]

[19. The method of claim 18, wherein the plurality of gas jets are provided by a corresponding plurality of apertures formed in the surface of the fluid handling structure and the controlling comprises controlling supply of gas to a first group of one or more apertures independently from a second group of one or more apertures.]

[20. The method of claim 18, further comprising exhausting gas through a plurality of openings, each opening provided between two adjacent apertures providing a respective gas jet.]

21. A liquid handling structure for a lithographic apparatus, the liquid handling structure configured to contain liquid in a space between a projection system of the lithographic apparatus and an upper major surface of a substrate table of the lithographic apparatus and/or of a substrate when located on the substrate table, the liquid handling structure comprising:

an outlet configured to remove liquid from the space;
 a plurality of openings located outward, relative to the space, of the outlet, the openings configured to provide respective flows of gas incident on the upper major surface that are spaced apart at the upper major surface;

a fluid opening configured to supply gas to contain liquid in the space; and

a control system, configured to control supply of gas to the plurality of openings so as to provide the respective flows of gas from the plurality of openings at least at a time when at least part of the plurality of openings is in the region of an edge of the substrate and to provide the respective flows of gas from the plurality of openings so as to break up liquid on the upper major surface while purposely allowing liquid to pass between adjacent respective flows.

22. The liquid handling structure according to claim 21, wherein the outlet comprises a line of apertures configured to surround the space in which liquid is contained, the apertures configured to extract liquid in order to contain liquid in the space.

23. The liquid handling structure according to claim 22, wherein the plurality of openings is arranged along a line, substantially parallel to the line of apertures of the outlet.

24. The liquid handling structure according to claim 21, wherein the control system is further configured to control the supply of gas to a first group of the plurality of openings independently from a second group of the plurality of openings.

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25. The liquid handling structure according to claim 21, wherein the control system is further configured to control the supply of gas to the plurality of openings such that the maximum velocity of the gas is in the range of from about Ma 0.3 to about Ma 0.6.

26. The liquid handling structure according to claim 21, wherein a separation between a center of one opening of the plurality of openings and a center of an adjacent opening of the plurality of openings is selected from the range of about 100 μm to about 1 mm.

27. The liquid handling structure according to claim 21, wherein a cross-sectional width of each of the plurality of openings is selected from the range of about 50 μm to about 150 μm .

28. The liquid handling structure according to claim 21, further comprising a plurality of apertures configured to exhaust gas, each aperture provided between two adjacent openings of the plurality of openings.

29. The liquid handling structure according to claim 21, wherein a gap between an edge of one opening of the plurality of openings and an edge of an adjacent opening of the plurality of openings is at least 50 μm .

30. The liquid handling structure according to claim 21, wherein the fluid opening is located outward, relative to the space, of the plurality of openings, and the control system is configured to control fluid flow through the fluid opening so as to essentially prevent liquid that passes between the adjacent respective flows from the plurality of openings from passing the fluid opening.

31. A lithographic apparatus comprising:
 the substrate table;
 the projection system; and
 the liquid handling structure of claim 21.

32. The lithographic apparatus according to claim 31, wherein the substrate table has a recess in the major upper surface of the substrate, the recess configured to receive and support the substrate.

33. A device manufacturing method, comprising:
 providing a liquid to a space between a projection system of a lithographic apparatus and an upper major surface of a substrate table of the lithographic apparatus and/or of a substrate when located on the substrate table;

containing liquid in the space by removing liquid from the space using an outlet of a liquid handling structure of the lithographic apparatus;

providing a respective flow of gas incident on the upper major surface from each opening of a plurality of openings of the liquid handling structure, the openings located outward, relative to the space, of the outlet;
 providing gas from a fluid opening to contain liquid in the space; and

controlling supply of gas to the plurality of openings so as to provide the respective flows of gas from the plurality of openings at least at a time when at least part of the plurality of openings is in the region of an edge of the substrate and to provide the respective flows of gas from the plurality of openings so as to break up liquid on the upper major surface while purposely allowing liquid to pass between adjacent respective flows.

34. The method according to claim 33, wherein the outlet comprises a line of apertures surrounding the space in which liquid is contained, the apertures extracting liquid in order to contain liquid in the space.

35. The method according to claim 34, wherein the plurality of openings is arranged along a line, substantially parallel to the line of apertures of the outlet.

36. The method according to claim 33, further comprising controlling the supply of gas to a first group of the plurality of openings independently from a second group of the plurality of openings.

37. The method according to claim 33, wherein a separation between a center of one opening of the plurality of openings and a center of an adjacent opening of the plurality of openings is selected from the range of about 100 μm to about 1 mm.

38. The method according to claim 33, wherein a cross-sectional width of each of the plurality of openings is selected from the range of about 50 μm to about 150 μm .

39. The method according to claim 33, wherein a gap between an edge of one opening of the plurality of openings and an edge of an adjacent opening of the plurality of openings is at least 50 μm .

40. The method according to claim 33, wherein the fluid opening is located outward, relative to the space, of the plurality of openings, and the method further comprises controlling fluid flow through the fluid opening so as to essentially prevent liquid that passes between the adjacent respective flows from the plurality of openings from passing the fluid opening.

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